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Programmable Logic Controller

# XGR CPU Module

**XGT Series** 

**User's Manual** 

CPU XGR-CPUH/F

XGR-CPUH/T

**Expansion drive XGR-DBST** 

XGR-DBSF

XGR-DBSH



# Safety Instructions

- Read this manual carefully before installing, wiring, operating, servicing or inspecting this equipment.
- Keep this manual within easy reach for quick reference.



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### Before using the product ...

For your safety and effective operation, please read the safety instructions thoroughly before using the product.

- Safety Instructions should always be observed in order to prevent accident or risk by using the product properly and safely.
- Instructions measures can be categorized as "Warning" and "Caution", and each of the meanings is as follows.

# **Warning**

This symbol indicates the possibility of serious injury or death if some applicable instruction is violated



This symbol indicates the possibility of severe or slight injury, and damages in products if some applicable instruction is violated

Moreover, even classified events under its caution category may develop into serious accidents depending on situations. Therefore we strongly advise users to observe all precautions in a proper way just like warnings.

► The marks displayed on the product and in the user's manual have the following meanings.



/! Be careful! Danger may be expected.



/\ Be careful! Electric shock may occur.

After reading this user's manual, it should be stored in a place that is visible to product users.

# Safety Instructions for design process

# **Warning**

- Please install a protection circuit on the exterior of PLC so that the whole system may operate safely regardless of failures from external power or PLC. Any abnormal output or operation from PLC may cause serious problems to safety in whole system.
  - Install protection units on the exterior of PLC like an interlock circuit that deals with opposite operations such as emergency stop, protection circuit, and forward/reverse rotation or install an interlock circuit that deals with high/low limit under its position controls.
  - If any system error (watch-dog timer error, module installation error, etc.) is detected during CPU operation in PLC, all output signals are designed to be turned off and stopped for safety. However, there are cases when output signals remain active due to device failures in Relay and TR which can't be detected. Thus, you are recommended to install an addition circuit to monitor the output status for those critical outputs which may cause significant problems.
- Never overload more than rated current of output module nor allow to have a short circuit. Over current for a long period time may cause a fire.
- Never let the external power of the output circuit to be on earlier than PLC power, which may cause accidents from abnormal output or operation.
- Please install interlock circuits in the sequence program for safe operations in the system when exchange data with PLC or modify operation modes using a computer or other external equipments Read specific instructions thoroughly when conducting control operations with PLC.

# Safety Instructions for design process

# 

► I/O signal or communication line shall be wired at least 100mm away from a high-voltage cable or power line. Fail to follow this instruction may cause malfunctions from noise

# Safety Instructions on installation process

# **!** Caution

- ▶ Use PLC only in the environment specified in PLC manual or general standard of data sheet. If not, electric shock, fire, abnormal operation of the product may be caused.
- ▶ Before install or remove the module, be sure PLC power is off. If not, electric shock or damage on the product may be caused.
- ▶ Be sure that every module is securely attached after adding a module or an extension connector. If the product is installed loosely or incorrectly, abnormal operation, error or dropping may be caused. In addition, contact failures under poor cable installation will be causing malfunctions as well.
- ▶ Be sure that screws get tighten securely under vibrating environments. Fail to do so will put the product under direct vibrations which will cause electric shock, fire and abnormal operation.
- ▶ Do not come in contact with conducting parts in each module, which may cause electric shock, malfunctions or abnormal operation.

# Safety Instructions for wiring process

# **Warning**

- Prior to wiring works, make sure that every power is turned off. If not, electric shock or damage on the product may be caused.
- After wiring process is done, make sure that terminal covers are installed properly before its use. Fail to install the cover may cause electric shocks.

# **∴** Caution

- ▶ Check rated voltages and terminal arrangements in each product prior to its wiring process. Applying incorrect voltages other than rated voltages and misarrangement among terminals may cause fire or malfunctions.
- ▶ Secure terminal screws tightly applying with specified torque. If the screws get loose, short circuit, fire or abnormal operation may be caused. Securing screws too tightly will cause damages to the module or malfunctions, short circuit, and dropping.
- ▶ Be sure to earth to the ground using Class 3 wires for FG terminals which is exclusively used for PLC. If the terminals not grounded correctly, abnormal operation or electric shock may be caused.
- ▶ Don't let any foreign materials such as wiring waste inside the module while wiring, which may cause fire, damage on the product or abnormal operation.
- Make sure that pressed terminals get tighten following the specified torque. External connector type shall be pressed or soldered using proper equipments.

# Safety Instructions for test-operation and maintenance

# **Warning**

- ▶ Don't touch the terminal when powered. Electric shock or abnormal operation may occur.
- Prior to cleaning or tightening the terminal screws, let all the external power off including PLC power. If not, electric shock or abnormal operation may occur.
- ▶ Don't let the battery recharged, disassembled, heated, short or soldered. Heat, explosion or ignition may cause injuries or fire.

# **∴** Caution

- ▶ Do not make modifications or disassemble each module. Fire, electric shock or abnormal operation may occur.
- Prior to installing or disassembling the module, let all the external power off including PLC power. If not, electric shock or abnormal operation may occur.
- ▶ Keep any wireless equipment such as walkie-talkie or cell phones at least 30cm away from PLC. If not, abnormal operation may be caused.
- When making a modification on programs or using run to modify functions under PLC operations, read and comprehend all contents in the manual fully. Mismanagement will cause damages to products and accidents.
- Avoid any physical impact to the battery and prevent it from dropping as well. Damages to battery may cause leakage from its fluid. When battery was dropped or exposed under strong impact, never reuse the battery again. Moreover skilled workers are needed when exchanging batteries.

# Safety Instructions for waste disposal

# **⚠** Caution

▶ Product or battery waste shall be processed as industrial waste.

The waste may discharge toxic materials or explode itself.

# **Revision History**

Version	Data	Main contents	Revised location
V 1.0	'08. 6	First Edition	-
V 1.1	'08.7	Modifying contents	-
		(2) How to configure redundancy system	2-5
		(3) Performance specification	4-1,4-2
		(4) Scan Time	5-6,5-8
		(5) Program memory	5-28
		(6) I/O module skip function	6-19,6-20
		(7) Module changing wizard during RUN	6-21
		(8) Performance specification	7-1,7-3
		(9) Example of calculating consumption current/power	8-5
		(10) Caution in handling	11-5
		(11) Grounding	11-13
		2. Adding contents	-
		(1) XGR redundancy system configuration	1-3
		(2) Remote I/O system	2-13
		(3) Scan Time	5-8
		(4) I/O module skip	6-20
		3. Deleting contents	-
		(1) Max install-able module number in specification	7-1
V 1.2	'09.9	Modifying contents	-
		(1) Performance specification	4-2
		(2) redundancy parameter setting window	5-2, CH6
		(3) Flag	A-6, A-11
V 1.3	'09.9	1. Adding contents	
		<ol> <li>Contents on redundancy system communication operation setting (ONE IP Solution)</li> </ol>	6-18~20
		2. modifying contents	
		(1) Product list (add new products)	
		- XGR-DC32, XGR-DMMA	2-1
		- XGF-SOEA	2-3
		- XGL-EIPT	2-4

# **Revision History**

Version	Data	Main contents	Revised location
V 1.4	'09.12	Adding contents     adding contents related to DC power	CH8.1, CH8.2, CH8.3

<sup>\*</sup> The number of User's manual is indicated right part of the back cover.

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## **About User's Manual**

Thank you for purchasing PLC of LS Industrial System Co., Ltd.

Before use, make sure to carefully read and understand the User's Manual about the functions, performances, installation and programming of the product you purchased in order for correct use and importantly, let the end user and maintenance administrator to be provided with the User's Manual.

The User's Manual describes the product. If necessary, you may refer to the following description and order accordingly. In addition, you may connect our website(http://eng.lsis.biz/) and download the information as a PDF file.

#### Relevant User's Manuals

Title	Description	No. of User's Manual
XG5000 User's Manual (for XGI/XGR)	It describes how to use XG5000 software, which it is applied to the IEC standard language, especially about online functions such as programming, printing, monitoring and debugging by using XGI/XGR series products.	10310000834
XGI / XGR Series Instructions & Programming	It is the user's manual for programming to explain how to use commands that are used PLC system with XGI CPU and XGR CPU.	10310000833
XGI-CPU User's Manual	It describes CPU specifications and technical terms for the XGT PLC system using a series of XGI-CPU.	10310000832

# 

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# Chapter 1. Overview

### 1.1 About this User Manual

This User Manual describes the performance specifications and operation procedures of the redundancy system including the XGR-CPU, in addition to the configuration of communication system and the use of special module in relation to the redundancy system.

This User Manual provides the basic specifications of the CPU module, power module, I/O module, main/expansion base of redundancy and expansion drive module, which are applied to the basic system of redundancy (XGR).

Classification	Model Name
Redundancy CPU Module	XGR-CPUH/F, XGR-CPUH/T
Expansion Drive Module	XGR-DBST, XGR-DBSF, XGR-DBSH
Redundancy Power Module	XGR-AC12, XGR-AC22, XGR-AC13, XGR-AC23, XGR-DC42
I/O Module	XGI-0000, XGQ-0000
Redundancy Basic Base	XGR-M06P
Redundancy Expansion Base	XGR-E12P

For programming, see following manuals in addition to this User Manual;

- XG5000 User Manual (for XGI/XGR)
- XGI/XGR Instruction User Manual

For further information on the special and communication modules, see the manuals and technical data pertinent to each special module and communication modules.

- User Manuals of the special modules
- User Manuals of the communication modules

#### This User Manual contains following information.

Chapter	Subject	Description
Chap. 1	Overview	Describes the configuration, product features, and glossaries.
Chap. 2	System Configuration	Describes the product types and system configurations available for the XGR series.
Chap. 3	General Specifications	Provides the common specifications of the modules used in the XGR series.
Chap. 4	CPU Module Specifications	
Chap. 5	Configuration of program and operation method	Describes the performance, specification, and operation of the XGR-CPUH.
Chap. 6	CPU Module Functions	
Chap. 7	Expansion driver module	
Chap.8	Power Module	Describes the specifications and use of the I/O module and power module,
Chap. 9	IO Module	except the CPU module.
Chap. 10	Base · Expansion Cable	
Chap. 11	Installation and Wiring	Provides the guidelines for installation, wiring and precaution of the PLC system to secure system reliability.
Chap. 12	Maintenance	Provides the items and methodology of maintenance for PLC system to prevent failure throughout the service life.
Chap. 13	EMC Compliance	Provides the system construction and configuration in response to the EMC specification.
Chap. 14	Troubleshooting	Describes various errors and faults which may occur in the system and countermeasures
Append. 1	Flag List	Describes the types and contents of various flags.
Append. 2	Dimensions	Provides the external size of the CPU, I/O module and base.
Append. 3	GLOFA Compatibility	
Append. 4	Warranty	

- 1) This User Manual does not describe the special and communication modules and programming. Refer related manuals for the information.
- 2) XGR CPU is a kind of XGT PLC system whose CPU type can be classified as follows;
  - XGK Series: the XGT PLC systems having the CPU using Master-K language(LS language)
     XGI Series: the XGT PLC systems having single CPU using IEC language

  - ③ XGR Series: the XGT PLC systems having redundant CPUs using IEC language

### 1.2 Configuration of the XGR Redundant System

XGR Redundancy System provides reliable solution for various types of redundancy systems required in diversified applications. The XGR Redundancy System is economical and user-convenient because the system makes use of the most resources of the XGI system, added with the components for redundancy.

#### Redundancy

- CPU module redundancy
- Power module redundancy
- Ethernet communication module redundancy

#### **Modules for redundancy**

- 2 redundant CPUs [optical, electrical]
- 4 types of power module [standard, large output] AC110V, AC220V individual
- Redundant bases (6 slots: 6 communication modules can be installed.
- 3 types of expansion drive modules [per media class: optical, electrical, combined]
- Expansion base (12 slots: according to consumption current)

#### **CPU Module**

- IEC 61131-3 language supported, ladder process rate of 42ns/command, 1MB (Approx. 128kstep) program capacity, 128,000 of I/O points
- 1Gbps optical communication for CPU synchronization
- Built-in I/O communication master
- Provides 2 types of CPU module according to the I/O communication media [optical, electrical]

#### Redundant system Network

- Expansion drive module
- Topology: ring [bus type operation activated in case of one error]
- Provides optical, electrical, and combined media
- Applied with 100Mbps class industrial Ethernet technology
- Max. available I/O points: 23,808 (31 stations x 12 slots x 64 points)

#### **Programming Tool**

- Integrated control of all the all XGT types with XG5000 XGK, XGI, XGB, XGR
- Convenient programming, various motoring function, diagnosis function, edit funtion
- Supports various IEC type languages: LD, ST, SFC, IL[Only view function]
- Supports communication parameter setting, frame monitoring function through XG-PD
- Supported with software packages per functionalities for motion, APM, temperature controller, etc.

### 1.3 Features of the XGR Redundancy system

XGR Redundancy System provides optimized solutions in various applications with its superb performance and convenience features.

#### High performance

- ✓ CPU process rate: 42ns / command
- √ High speed backplane
- ✓ Large capacity control points: max. 128,000 points
- ✓ Sufficient program capacity (max. 128ksteps)
- ✓ Sufficient data memory
- ✓ Long data type (64bit) and high speed real number operation (single, double) provided
- ✓ Switching operation with minimum delay: if the master CPU fails, operation is switched to the backup CPU within 50ms

#### Minimum size implemented

- ✓ Compact panel can be implemented with the minimum size among the class
- ✓ CPU module: Width(55 mm) \* Height(98 mm) \* Depth(90 mm)
- ✓ Power module
  - 1) XGR-AC12/AC22: Width (55 mm) \* Height (98 mm) \* Depth(90 mm)
  - 2) XGR-AC13/AC23: Width (55 mm) \* Height (98 mm) \* Depth (110 mm)

#### Easy expansion using network

- ✓ Easy installation of expansion bases using network cable
- ✓ Up to 31 remote bases can be added
- ✓ Software program can be uploaded/downloaded via online access from expansion base
- ✓ Communication master module on expansion base enables the installation of smart I/O at anywhere

#### Improved maintenance maintain ace by system history, network ring configuration, etc.

- ✓ Provides system analysis data including the operation, error, and system histories
- ✓ Network ring configuration enables normal system operation even when a network cable fails
- ✓ Provides network monitoring and protocol monitoring functions
- √ If communication fails (smart I/O, etc.), the failed channel can be monitored (by monitoring the flag via HMI).
- ✓ Graphic display of system configuration
- ✓ Module Changing Wizard enables safe replacement of module during operation
- ✓ Base Changing Wizard enables safe replacement of base during operation

#### IEC 61131-3 (standard language) specification compliance

- ✓ Provides IEC standard LD, ST, SFC, IL(only view function)
- ✓ Provides IEC standard program structure and data type

#### Supports various communication functions

- Open network enables convenient interface with other products (Ethernet, Profibus, DeviceNet, RS-232C, RS-422/485, etc.)
- Supports various protocols for improved convenience
- Up to 24 communication master modules (12 high speed links, 8 P2Ps) can be mounted on one redundant system.
- Simple and east network diagnosis using network and communication frame monitoring function
- RAPIEnet module can be inserted on basic base

#### Diverse I/O modules are provided for easy system configuration

- 8, 16, 32, and 64 point modules are provided (8/16 point modules for relay output)
- Single input, single output, mixed I/O module provided

#### Extended applications with enhanced analog function

- Analog modules can be connected to the slots of all the expansion bases (max. 250 output modules, 139 input modules)
- Supports various applications with insulated type analog and temperature module
- Convenient use by special parameter settings and flags
- Strengthened debugging function by monitoring flags and data and changing the setting value through special monitor display window

#### Provides integrated programming & engineering environments

- Integrated control of all the all XGT types with XG5000 XGK, XGI, XGB, XGR
- Convenient programming, various motoring function, diagnosis function, edit funtion
- Supports various IEC type languages: LD, ST, SFC, IL[Only view function]
- Supports communication parameter setting, frame monitoring function through XG-PD
- Supported with software packages per functionalities for motion, APM, temperature controller, etc.

#### Provides diversified additional function

- Battery backup and flash memory backup for software programs
- Various restart mode(warm, cold)
- Task program process
- Forced ON/OFF of I/O
- Clock
- Module changing wizard available during operation
- Fault mask function
- Module skip function
- Extensive operation history supported (system history)
- Detail error report supported (error history)
- LED indication of operation status
- Dot matrix indicator: display operation information and abnormal matters in texts.

#### **PID Function**

- Max. 256 loops supported
- Parameter setting using XG5000, convenient monitoring on loop status through Trend monitor
- Easy control parameter setting using improved auto-tuning function
- Provides various control modes including normal/reverse combination operation, 2 step SV PID control, cascade control, etc.
- Safety secured by diversified alarm functions including PV MAX, PV change, etc.

# 1.4 Glossary

This section provides the major terms and their definitions, used in this Manual.

Terms	Definition	Remark
Module	A standardized component having a specific function to constitute a system. E.g., I/O board designed to be inserted into base.	CPU module, power module, I/O module, etc.
Master CPU Module	The CPU module running the present software program. Automatically switched to backup CPU module when the operation is stopped and transfers the control	
Standby CPU Module	The control function of the master CPU module is transferred to this standby CPU module in case of failure, and this standby CPU module becomes the master CPU module.	
Redundant Basic Base	This base can accommodate the CPU module and Ethernet communication module.  •Master CPU system: the redundant basic system whose CPU module is operating as the master.  •Standby CPU system: the redundant basic base whose CPU module is operating as backup mode.	
Redundant Expansion Base	Expansion base where power module, I/O module, and special/communication module can be installed. (The communication module can be any module except the FEnet and RAPIEnet).	
Expansion Drive Module	The module for communication between bases. It also enables setting the base numbers (1~31) with a rotary switch	
Synchronous cable	1Gbps optical cable for connection between the CPU modules of a redundant system	
CPU redundancy	As a part of redundant system, the system is constructed to enable continuous operation when the master CPU module fails using a backup CPU module	
Power redundancy	A system constructed with redundant power modules to enable continuous system operation when a module of the base fails	
Unit	A module or a set of module which is the minimum unit of a PLC system operation. A PLC system comprises units and/or sets of units	Basic unit. Expansion unit
PLC System	A system consists of PLC and peripheral devices and can be controlled with user software program	
XG5000	A programming tool for developing software program, editing and debugging	
Module Changing Wizard	A software used for the replacement of CPU module during PLC operation. Power module, I/O module, some of the special modules, and base module can be replaced with this software	Replaceable special modules: A/D,D/A, HSC,RTD

# **Chapter 1. Overview**

Terms	Definition	Remark
Cold Restart	Starting a PLC system and user program after initializing all data (variables and programs such as I/O image area, internal register, timer, counter, etc.) automatically or manually	
Warm Restart	Along with the function that notifies user-program about power OFF incidents, the user programs are restarted with holding previous data according to setting, after a power OFF.	
I/O Image Area	The internal memory area of the CPU module installed to maintain I/O status	
Cnet	Computer Network	
FEnet	Fast Ethemet Network	
Pnet	Profibus-DP Network	
Dnet	DeviceNet Network	
Rnet	Remote Network	
RTC	Real Time Clock. The generic IC with a built-in clock function	
Watchdog Timer	The timer which monitors the preset running time of a user program, and triggers alarm if the process fails to be completed within preset time	
Function	The operation units which do not store the operation result in the instructions, such as the 4 arithmetical and comparison operations, and output the results of the inputs immediately	
Function Block	The operation units which store the operation results in the instruction, such as timer and counter, and use the results over multiple scans	
Direct Variable	The variables used without declaring name and type. For example, I, Q, and M areas are direct variables.	%IX0.0.2 %QW1.2.1 %MD1234, etc.
Automatic Symbolic Variable	The variables used with names and type declared by user if declared as 'INPUT_0'=%IX0.0.2, 'RESULT'=%MD1234, 'INPUT_0' and 'RESULT' names can be used in the program instead of %IX0.0.2 and %MD1234.	
Task	The condition for a program start-up, such as fixed cycle task, internal contact point task, and initialization task	

Terms	Definition	Remark
Sink Input	The method wherein the current enters PLC input terminal from switch when the input signal is turned ON  PLC  Common	Z: input impedance
Source Input	The method wherein the current enters switch from PLC input terminal when the input signal is turned ON  Common PLC  Current  SW  The method wherein the current enters output terminal from load when the PLC output is ON	
Sink Output	Output Contact Current Common	
Source Output	The method wherein the current enters from output terminal when the PLC output is ON  PLC Common  Current  Current  Contact	

# **Chapter 2. System Configuration**

The XGR Series offer various products for basic systems, computer communication and network systems. This Chapter describes the configuration method and features of each system.

# 2.1 Product List

The product line of the XGR Series is as follows.

#### 1) Products exclusive for redundancy

Product	Model	Description		
Redundancy CPU	XGR-CPUH/F	Max. I/O points: 6,144, program capacity: 1MByte     For optical communication		
Module	XGR-CPUH/T	Max. I/O points: 6,144, program capacity: 1MByte     For electrical communication		
Redundancy Basic Base	XGR-M06P	<ul> <li>For mounting redundancy CPU module, power redundancy</li> <li>Available for 6 communication modules</li> </ul>		
Redundancy Expansion Base	XGR-E12P	for mounting I/O module, power redundancy     Available for 12 I/O modules		
	XGR-DBST	Communication module for XGR expansion base operation.  Electrical media		
Expansion Drive Module	XGR-DBSF	Communication module for XGR expansion base operation. Optical media		
	XGR-DBSH	Communication module for XGR expansion base operation.  Electrical/optical media mixing		
	XGR-AC12	• DC5V: 5.5A, AC110V input		
	XGR-AC22	• DC5V: 5.5A, AC220V input		
Power Module	XGR-AC13	• DC5V: 8.5A, AC110V input		
	XGR-AC23	• DC5V: 8.5A, AC220V input		
	XGR-DC42	• DC5V: 7.5A, DC24V input		
Sync. Cable  XGC-F201  XGC-F301  XGC-F301  XGC-F501  • LC type optical cable (multi core), length: 2 m  • LC type optical cable (multi core), length: 3 m  • LC type optical cable (multi core), length: 5 m				
	XGC-C001	Twisted pair cable     FTP used		
I/O Expansion Cable	XGC-F201 XGC-F301 XGC-F501	<ul> <li>LC type optical cable (multi core), length: 2m</li> <li>LC type optical cable (multi core), length: 3m</li> <li>LC type optical cable (multi core), length: 5m</li> </ul>		
Dustproof module XGR-DMMA • dustproof module for not used power module slot		dustproof module for not used power module slot		

# 2) Common Products for XGT Series

### (1) Digital I/O Module

Product	Model	Description	
	XGI-D21A	DC 24V input, 8 points (current source / sink input)	
	XGI-D22A	DC 24V input, 16 points (current source / sink input)	
	XGI-D24A	DC 24V input, 32 points (current source / sink input)	
	XGI-D28A	DC 24V input, 64 points (current source / sink input)	
Digital Input Module	XGI-D22B	DC 24V input, 16 points (current source input)	
	XGI-D24B	DC 24V input, 32 points (current source input)	
	XGI-D28B	DC 24V input, 64 points (current source input)	
	XGI-A12A	AC 110V input, 16 points	
	XGI-A21A	AC 220V input, 8 points	
	XGQ-RY1A	Relay output, 8 points (2A, single COM.)	
	XGQ-RY2A	Relay output, 16 points (2A)	
	XGQ-RY2B	Relay output, 16 points (2A), Varistor incorporated.	
	XGQ-TR2A	Transistor output, 16 points (0.5A, sink output)	
Digital Output Madula	XGQ-TR4A	Transistor output, 32 points (0.1A, sink output)	
Digital Output Module	XGQ-TR8A	Transistor output, 64 points (0.1A, sink output)	
	XGQ-TR2B	Transistor output 16 points (0.5A, source output)	
	XGQ-TR4B	Transistor output 32 points (0.1A, source output)	
	XGQ-TR8B	Transistor output 64 points (0.1A, source output)	
	XGQ-SS2A	Triac output, 16 points (1A)	
Digital I/O Mixed Module	XGH-DT4A	DC 24V input, 16 points(current source / sink input)     Transistor output, 16 points (0.1A, sink output)	
Anti-vibration Module	XGT-DMMA	Anti-vibration module for unused slots	

# **Chapter 2. System Configuration**

### (2) Process and Motion Control Modules

Product	Model	Description	
	XGF-AV8A	<ul> <li>Voltage input: 8channels</li> <li>DC 1 ~ 5V / 0 ~ 5V / 0 ~ 10V / -10 ~ +10V</li> </ul>	
A/D Conversion Module	XGF-AC8A	<ul><li>current input: 8 channels</li><li>DC 4 ~ 20mA / 0 ~ 20mA</li></ul>	
7 VD CONVENSION WICKARD	XGF-AD8A	Voltage/current input: 8 channels	
	XGF-AD4S	Voltage/current input: 4 channels, insulated channels	
	XGF-AD16A	Voltage/current input: 16 channels	
	XGF-DV4A	<ul> <li>Voltage output: 4 channels</li> <li>DC 1 ~ 5V / 0 ~ 5V / 0 ~ 10V / -10 ~ +10V</li> </ul>	
	XGF-DC4A	<ul><li>current output: 4 channels</li><li>DC 4 ~ 20mA / 0 ~ 20mA</li></ul>	
D/A Conversion Module	XGF-DV4S	Voltage output: 4 channels, insulated channel	
D/A Conversion Module	XGF-DC4S	current output: 4 channels, insulated channel	
	XGF-DV8A	<ul> <li>Voltage output: 8 channels</li> <li>DC 1 ~ 5V / 0 ~ 5V / 0 ~ 10V / -10 ~ +10V</li> </ul>	
	XGF-DC8A	<ul><li>current output: 8 channels</li><li>DC 4 ~ 20mA / 0 ~ 20mA</li></ul>	
Thermocouple input Module	XGF-TC4S	Temperature (T/C) input, 4 channels, insulated channel	
Resistance Temperature Detector	XGF-RD4A	Temperature (RTD) input, 4 channels	
input Module	XGF-RD4S	Temperature (RTD) input, 4 channels, insulated channel	
Temperature Control Module	XGF-TC4UD	<ul> <li>Control loop: 4 loops</li> <li>input(4 channels, TC/RTD/Voltage/current), output(8 channels, TR/current)</li> </ul>	
High Speed Counter	XGF-HO2A	Voltage input type (Open Collector type)     200KHz, 2 channels	
Module	XGF-HD2A	Differential input type (Line Driver type)     500KHz, 2 channels	
	XGF-PO3A	Pulse output(Open Collector type), 3 axes	
	XGF-PO2A	Pulse output(Open Collector type), 2 axes	
Positioning Module	XGF-PO1A	Pulse output(Open Collector type), 1 axis	
. Comorning Module	XGF-PD3A	Pulse output(Line Driver type), 3 axes	
	XGF-PD2A	Pulse output(Line Driver type), 2 axes	
	XGF-PD1A	Pulse output(Line Driver type), 1 axis	
Motion Control Module	XGF-M16M	Exclusive net for motion (M-II) type, 16 axes	
Event input module	XGF-SOEA	DC24V input, 32-point, Sequence of Event module	

#### (3) Communication Modules

Product	Model	Description	
	XGL-EFMF	Fast Ethernet(optical), Master     100/10 Mbps supported	
FEnet I/F Module (optical/electrical)	XGL-EFMT	Fast Ethernet(electrical), Master     100/10 Mbps supported	
	XGL-ESHF	Optical switch module for fast Ethernet	
	XGL-EIMT	Communication module between PLCs, electrical media, 100 Mbps industrial Ethernet supported	
RAPIEnet Communication Module	XGL-EIMF	Communication module between PLCs, optical media, 100 Mbps industrial Ethernet supported	
	XGL-EIMH	Communication module between PLCs, electrical/optical mixed media, 100 Mbps industrial Ethernet supported	
	XGL-C22A	Serial communication     RS-232C, 2 channels	
Cnet I/F Module	XGL-C42A	<ul> <li>Serial communication</li> <li>RS-422(485), 2 channels</li> </ul>	
	XGL-CH2A	Serial communication     RS-232C 1 channel / RS-422(485) 1 channel	
Rnet I/F Module	XGL-RMEA	For Rnet Master I/F (Smart I/O communication supported)     1 Mbps base band	
	AOL RIVILA	• For twisted cables	
Profibus-DP I/F Module	XGL-PMEA	Profibus-DP master module	
DeviceNet I/F Module	XGL-DMEA	DeviceNet master module	
Ethernet/IP I/F Module	XGL-EIPT	EtherNet/IP (electricity)     100/10Mbps supported	
Fnet I/F Module	XGL-FMEA	Fnet Master Module	
Switching Hub Module	XGL-EH5T	• 10/100Mbps 5 –port switching hub module	
Dustproof module	XGK-DMMA	Dustproof module for not used slot	

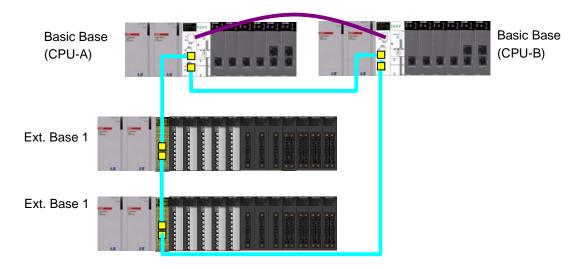
### Note

<sup>1)</sup> For the active coupler, optical converter, repeater and block type remote module, see the network related technical documents.

# 2.2 Redundancy System

### 2.2.1 Redundant System Configuration

The configuration of the basic system incorporating the redundant basic base and expansionbases connected with cables are shown below.



Classification	Description
Basic base constitution	Constructed with 2 basic bases of the same structure.
Max. extendable stacks	Expansion bases can be installed up to 31 stacks.
Max. I/O modules	Up to 372 I/O modules can be installed in expansion bases.
Max. I/O points	<ul> <li>16-point modules: 5,952 points</li> <li>32-point modules: 11,904 points</li> <li>64-point modules: 23,808 points</li> </ul>
Max. expansion distance	Between bases     Optical: 2 km     Electrical: 100 m     Total max length     Optical: 62km (when installing 31 expansion modules)     Electrical: 3.1km (when installing 31 expansion modules)

Classification	Description		
I/O number allocation for expansion bases	The beginning value of the I/O numbers of each base is determined by the base number setup in the expansion drive module.  In the base, the I/O numbers are allocated by 64 (fixed) points per slot. Each slot is allocated with 64 points regardless of the installation and type of module.  Different from the digital I/O modules, special modules do not use I/O number for control. They use U device and exclusive function block.  An exemplary allocation of I/O numbers of a 12 slot base is shown below.  Slot No.  Downer Bxt. Drive  Base No. 1  SQX1.11.0~15  %QX1.11.0~15  %QX1.10.0~31  %QX1.9.0~63  %IX1.8.0~15		
I/O number of basic base	<ul> <li>Since communication module only can be installed on the basic base, I/O numbering is meaningless.</li> <li>Though the basic base does not use the I/O number, the same numbers (768 points) as that of a 12 lot expansion base are allocated.</li> <li>The basic base has the base No. of "0" located at the first digit of the I/O No.</li> </ul>		

#### Note

- 1)The redundant basic base has a fixed base No. of 0. Expansion bases are provided with switches for setting up base No.
- 2) The base modules installed with redundant CPU are available for the basic base only.
- 3) The redundant CPU is a CPU module which occupies 2 slots.
- 4) The type of module setup with I/O parameter must agree with that of the actual module to enable operation to start.

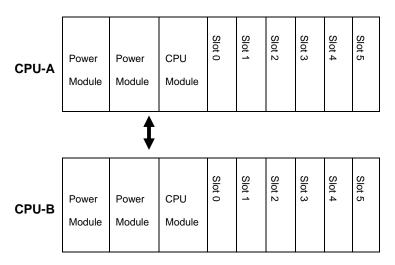
#### 2.2.2 Redundancy of CPU system

A redundant system has the redundancy of power supply modules, CPU modules, basic base modules, and communication modules. On the basic base module of a redundant system, two identical power, CPU, and communication modules are installed. The two CPU modules are connected with a sink cable.

One of the two CPU systems functions as the master which is in charge of the operation and the other is the backup system which takes over the operation when the master system fails.

After correcting the failure, the previous master system can participate in the redundant operation as a backup system. Master and backup systems can be selected using software tool and key switch during redundant operation.

Use the switch on the CPU module to setup CPU-A and CPU-B. If the setting is duplicated with A or B, normal redundant operation cannot be achieved.



[Fig. 2.3.2] Slot configuration of duplicated basic base

The modules which can be installed on the basic base are as follows.

Modules	Type/Model
CPU Module	XGR-CPUH/T, XGR-CPUH/F
Power Module	XGR-AC12, XGR-AC22, XGR-AC13, XGR-AC23
Communication	FEnet module, RAPIEnet module
Module	
Base Module	XGR-M06P

#### Note

- 1) Redundant CPU cannot be installed on an expansion base module.
- 2) The O/S version of the two CPUs must be the same.
- 3) As shown in [Fig. 2.3.2], the modules on CPU-A: 0, 1, 2, 3, 4, 5 slots and CPU-B: 0, 1, 2, 3, 4, 5 slots must be of the same product type. If the CPU-A: 0 slot is installed with an XGL-EFMF(FEnet) module, the same module must be installed on the CPU-B: 0 slot.

#### 2.2.3 Power Module Redundancy

The power modules of the basic and expansion base systems can have a redundancy.

The redundant power module enables continuous system operation without interruption when one of the two power modules fails to supply power.

Power system or power module failure can be repaired or the module can be replaced during operation without interruption.

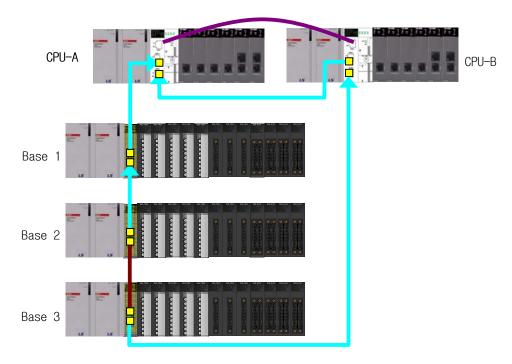
#### 2.2.4 Expansion Base Communication Path Redundancy

Since the cable connection of the expansion bases are ring-structured, the system can be operated without interruption even when a cable fails, by using the other cable.

In normal ring operation mode, operation is performed using the path which is nearer to the master. When a cable fails, the system operation is maintained by line operation mode.

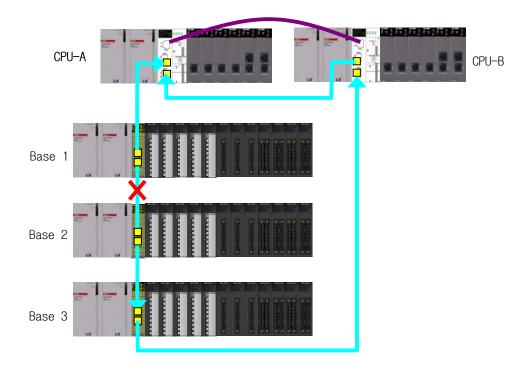
The failed cable can be replaced without interrupting the operation.

#### 1) Ring Operation Mode



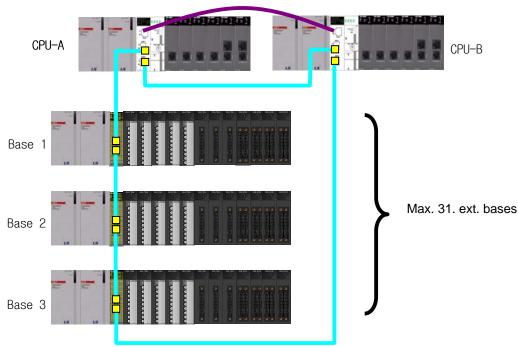
# **Chapter 2. System Configuration**

# 2) Line Operation Mode

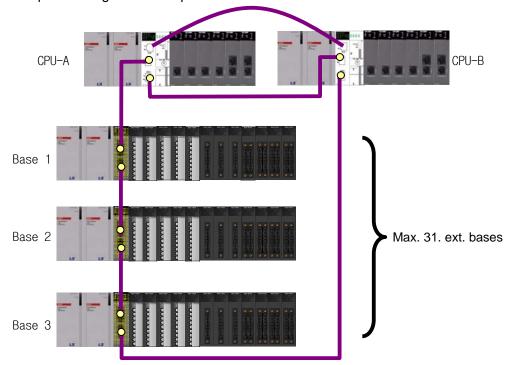


### 2.2.5 Example of Redundant System Configuration

1) Example of using electrical modules



- CPU-A module, CPU-B module: XGR-CPUH/T
- Ext. drive modules of base 1,2,3: XGR-DBST
- 2) Example of using electrical optical modules

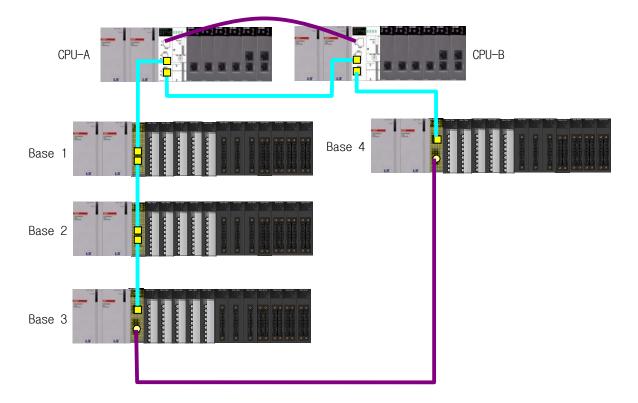


- CPU-A module, CPU-B module: XGR-CPUH/F
- Ext. drive modules of base 1,2,3: XGR-DBSF

### **Chapter 2. System Configuration**

#### 3) Example using mixed modules

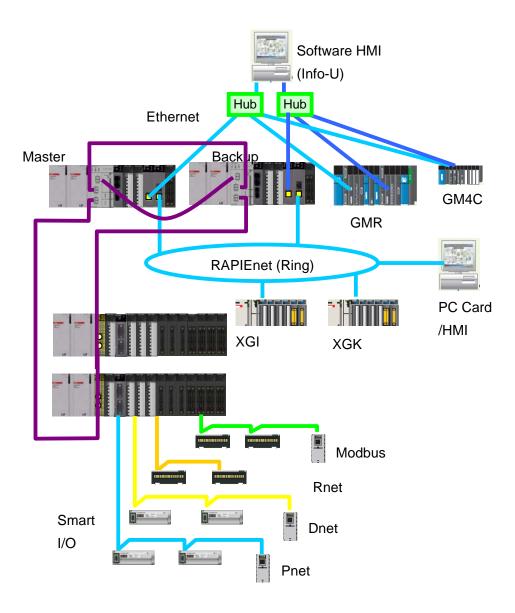
In a system that electrical modules are already established where distance among the stations is too far or electrical noise is severe, the section can be replaced with optical modules to build an optical/electrical mixed module network without an additional converter.



- CPU-A module, CPU-B module: XGR-CPUH/T
- Ext. drive modules of base 1,2,3: XGR-DBST
- Ext. drive modules of base 1,2,3: XGR-DBSH

#### 4) Example of using dedicated Ethernet for upper level HMI connection and between PLCs

The communication network between upper level systems, existing PLCs and the controllers from other suppliers can be constructed using an Ethernet communication module (FEnet). With XGT PLCs, a high speed and reliable system can be built using an industrial Ethernet module (RAPIEnet).



# 2.3 Network System

XGR Series support diversified network systems for flexible system configuration methodology.

For the communication between PLCs and upper level systems or between PLCs, Ethernet (FEnet, RAPIEnet) and Cnet are provided. For lower control network system, Profibus-DP, DeviceNet, and Rnet are provided.

#### 2.3.1 Networking among Systems

Only FEnet and RAPIEnet communication modules are available for the redundant basic base. All communication modules except Ethernet communication module can be installed in the expansion base. Maximum 24 communication modules can be installed in the redundant basic base and expansion bases. Maximum number of modules limited by functionality are as follows;

Functionality	Maximum No. of Modules
Max. No. of modules for high speed link configuration	12
Max. No. of P2P <sup>1)</sup> service modules	8
Max. No. of dedicated service (slave) modules	24

<sup>\*</sup>Note<sup>1)</sup>: P2Pservice: 1 to 1 communication

### 2.3.2 Remote I/O System

For the control network systems of the I/O modules distributed across remote locations, Profibus-DP, DeviceNet, Rnet, Cnet, etc., are provided.

#### 1) I/O System Application by Network Type

Remote I/O modules are classified into base board type and block type (Smart I/O, etc.). Base board type may not be supported in certain network types.

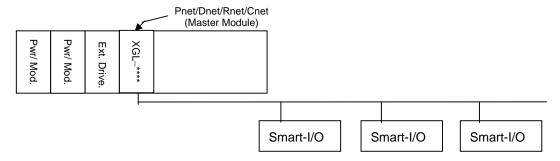
No.	Network Type (Master)	Block-type Remote I/O (Smart IO)	Exttype Remote I/O
1	Profibus-DP	0	0
2	DeviceNet	0	0
3	Rnet	0	0
4	Cnet(MODBUS)	0	-

<sup>\*</sup> The above specifications can be changed for functional improvement. Please refer to the technical material of the network system for detail information.

#### 2) Block-type Remote I/O System

### (1) System Configuration

Constructed with Profibus-DP, DeviceNet, Rnet and Cnet. Block-type remote I/O can be used regardless of the PLC series in the system. Profibus-DP and DeviceNet are developed in compliance with the international standard, therefore, they can be connected with other suppliers' products as well as our own.



# (2) I/O Allocation and I/O Numbering Scheme

- available to allocate variable to remote IO by High Speed Link parameter
- I, Q, M area of master can be designated as READ/WRITE area for the remote I/O area.
- For smooth use of forced I/O setting function, it is recommended to use 'I' and 'Q' areas.
- For the setting method of the high speed link parameters of module, see the technical documents of the network system.

#### Note

- 1) Remote station numbers and areas must be set-up without overlapping.
- 2) Input and output services, such as forced On/Off, are provided only when the inputs and outputs are allocated with I/O variables (%IW,%QW).
- 3) For SMART IO connected to master module, in case you set Read area(Q) and Save area(I) through XG-PD, forced I/O setting is available.

# **Chapter 3 General Specifications**

# 3.1 General Specifications

Table 3.1 shows the general specifications of XGT series.

	[Table 3.1] General specifications						
No.	Items		Specifications				Related standards
1	Ambient temperature		0~55℃				
2	Storage temperature			-25∼+70°C			
3	Ambient humidity		Ę	5 ~ 95%RH (Non-con	densing)		
4	Storage humidity		Į.	5 ~ 95%RH (Non-con	densing)		
			Occa	sional vibration		-	
		Frequency		Acceleration	Amplitude	How many times	
		$10 \le f < 57Hz$	!	_	0.075mm		
5	Vibration	$57 \le f \le 150Hz$		9.8m/s <sup>2</sup> (1G)	-	405	
3	resistance		Conti	nuous vibration		10 times each directions	IEC61131-2
		Frequency		Acceleration	Amplitude	(X, Y and Z)	
		10 ≤ f < 57Hz		_	0.035mm	(X, 1 and 2)	
		57 ≤ f ≤ 150Hz	4	.9m/s²(0.5G)	_		
,	Shock	Peak acceleration: 147  Purplime 14 peak	7 m/s <sup>2</sup> (15G)				IEC61131-2
6	resistance	Duration: 11ms     Holf sine 3 times each	direction no	r oods ovis			
		Half-sine, 3 times each	raireation pe	e eacraxis			
		Square wave Impulse noise			±1,500 V		LSIS standard
		Electrostatic discharge	4kV (Contact discharge)			IEC61131-2 IEC61000-1-2	
		Radiated					IEC01000-1-2
7	Noise resistance	electromagnetic field noise		80 ~ 1,0	80 ~ 1,000 MHz, 10V/m		IEC61131-2, IEC61000-1-3
		Fast transient/bust	Segme nt	Power supply module	_	nalog input/output nication interface	IEC61131-2
		noise	Voltage	2kV		1kV	IEC61000-1-4
8	Environment	Free from corrosive gasses and excessive dust					
9	Altitude	Up to 2,000 ms					
10	Pollution degree	Less than equal to 2					
11	Cooling	Air-cooling					
		<b>J</b>					

#### Note

- 1) IEC (International Electrotechnical Commission):
  - An international nongovernmental organization which promotes internationally cooperated standardization in electric/electronic field, publishes international standards and manages applicable estimation system related with.
- Pollution degree

An index indicating pollution degree of the operating environment which decides insulation performance of the devices. For instance, Pollution degree 2 indicates the state generally that only non-conductive pollution occurs. However, this state contains temporary conduction due to dew produced.

# **Chapter 4 CPU Module**

# 4.1 Performance Specifications

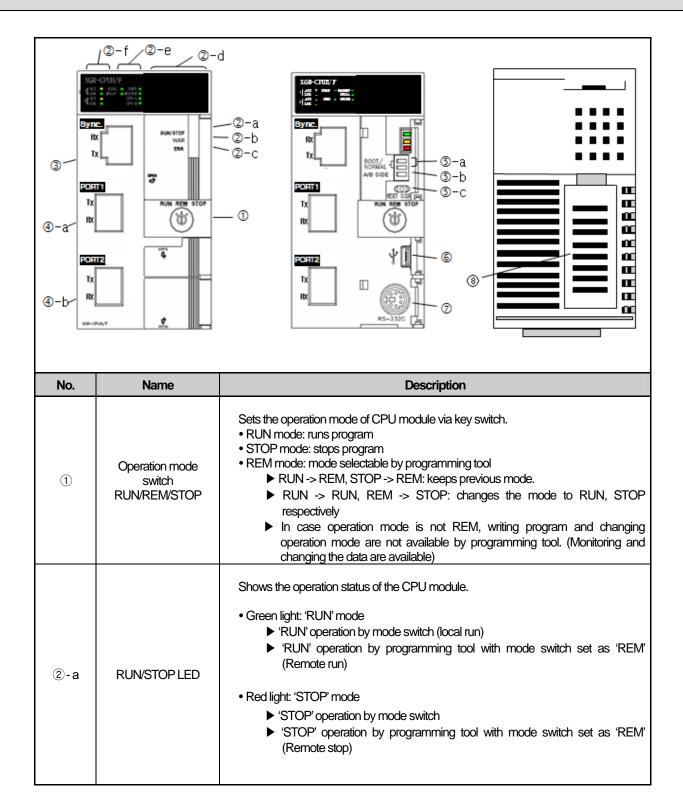
The performance specifications of the redundant CPU module are as follows.

репоппак	performance specifications of the		or tric r	Specif	Downster	
	Item		XGR-CPUH/F	XGR-CPUH/T	- Remarks	
Progra	m opera	ation meth	nod	Scan program: Reiterative ope	•	
- 109101	- regram operation metros		Task program: Initialization, Cycle, Internal device		D: (	
1/0	I/O Control system			·	essing system (refresh system).	Direct method by command is not supported.
				LD (Ladder Diagram), ST (Stru		
Pro	ogram la	nguage		SFC (Sequential Function Chart)		
				IL (Instruction List, view function only)		
	-	perator			18	
	Ва	asic funct	ion	130 types + real number ope	eration function	
No. of Instruction		asic funct ock	ion		41	
		edicated nction blo	ock	FB dedicated for special mode	ule, FB for process control	
		asic		0.042 µs	/command	
Operat process	N A	MOVE			/ command	
speed (ba	asic R	in ear number			(S), 1.078 µS(D)	S: Single real number
instruction	an)				(S), 2.394 \( \mu \)S(D)	D: Double real number
D			-14		s(S), 2.660 μS(D)	la alcaffa accorda a diseas accorda
		ory capa			MB	Including upload program
·	` `	stallable)		23,808 points (31bas	ses * 12slots * 64points)	
Max. I/O	memory	contact p	point	I: 131,072, Q: 131,072		
	Input v	rariable(I)		16KB		
	Output	Output variable(Q)		16	6KB	
	Autom area(A	atic varia	ble	512KB (max. 256	6KB retain settable)	
			М	256KB (max. 128	8KB retain settable)	
	Direct	variable	R	64KB *	* 2 blocks	64KB per block
Data memory			W	12	28KB	Same area with R
Incinory			F	4	IKB	System flag
			K	18KB (PII	O 256 loops)	PID flag
	Flag variable	variable	L	2	2KB	High speed link flag
			N	4:	2KB	P2P flag
			U	32KB (31 base,	16 slot, 32channel)	Analogue refresh flag

# **Chapter 4 CPU Module**

Home		Specific	ations	D
	Item	XGR-CPUH/F	XGR-CPUH/T	Remarks
	Timer	<ul> <li>No point limit</li> <li>Time range: 0.001~ 4,294,967.295 second(1,193 hours)</li> </ul>		Occupying 20 bytes of automatic variable area per point Occupying 8 bytes
	Counter	<ul><li>No point limit</li><li>Coefficient range : 64 bit expression</li></ul>	range (-32,768 ~ +32,767)	of automatic variable area per point
	Total no. of programs	256		
Program	Initialization task	1(_int)		
structure	Circulation to all	32 (range	e: 0~31)	
	Internal device task	32 (range:	: 64~95)	Processed at scan END
C	Operation mode	RUN, STOF	P, DEBUG	
	Restart mode	Cold, V	Varm	
Self	diagnosis function	Operation delay monitoring, memory fault, l	O fault, battery fault, power fault and etc	
Data	protection in case of power failure	Setting retain area in the Basic Parameter Retain setting of auto variable		
Max	x. expansion base	31 stages		One base per stage
Max. lenç	gth between expansion			
	base	Electrical (100m)		
	Operation monitoring between CPU	Redundant monitoring by Sync. Line and ring type I/O network		
	Data backup between CPU	1 G bps optical line, max. length 200 m (recommended)		
Redund	Data Sync. Method between CPU	Set in the Redundancy Parameter		
ancy perform ance	Delay in case of redundancy operation	Proportional to data which master transmits to backup - Max. 15ms -optimization available by user setting Basic 15ms + user designated amount (2kword) * 0.250ms/2kword		Refer to 5.1.4
	Master switching time	22n	ns	Refer to 5.1.4
-	Operation delay in case of standby start			Refer to 5.1.4
Internal consumption current (mA)		1,310 mA	980 mA	
	Weight (g)	276 g	257 g	

# 4.2 Names and Functions of Parts



# **Chapter 4 CPU Module**

No.	Name	Description
②-b	WAR. LED	On(yellow): displaying an warning     Force I/O setting     Skip I/O/Fault mask setting     Run when Fuse error     Run when Fuse error     Run when special module error     Run when special module error     Run when communication module error     Warning abnormal RTC data     Warning existence of base which doesn't participate in the operation     Abnormal operation stop warning     Task collision warning     Abnormal battery warning     Warning detection of light error of external device     High speed link setting warning     P2P setting warning     Fixed cycle error warning     Abnormal base power module warning     Abnormal base skip cancellation warning     Abnormal base number setting warning     Warning redundant configuration     Warning OS version inconsistency     Warning Ring topology configuration     Off: No warning
②-c	ERR. LED	On(red): displays error makes the operation unavailable  CPU configuration error  Module type mismatch error  Module detached error  Fuse disconnection error  Detection of heavy trouble of external device  Basic parameter error  Vo parameter error  Vo parameter error  Special module parameter error  Vuser program error  Program code error  CPU abnormal end or malfunction  Base power error  Scan watchdog error  Base information error  Standby CPU run error  Expansion base detached error  Redundant parameter error  Module insertion location error  Redundant Sync. Error  AB side overlapped setting error  Base abnormal configuration error  No error

No.	Name	Description
②-d	Displaying operation status	<ul> <li>Displays operation status with 4 characters</li> <li>Normal operation</li> <li>Warning</li> <li>Error (Refer to XGR error code)</li> </ul>
②-e	Displaying redundancy status	<ul> <li>Displays operation/installation status of CPU system.</li> <li>RED: On when redundant operation, Off when single operation</li> <li>MASTER: on; CPU operating as master, off; standby CPU</li> <li>CPU-A: on when CPU position designation switch (⑤-b) set as A</li> <li>CPU-B: on when CPU position designation switch (⑤-b) set as B</li> </ul>
②-f	Displaying expansion network status	Displays communication status with expansion base  • ACT On (yellow): relevant channel is operating  • LINK On (Green): link of relevant channel is connected  ▶ 1 indicates upper channel (④-a), 2 indicates lower channel (④-b).  • RING On (Green): Expansion network is configured as Ring.  • Ring Off: Expansion network is not established or configured as Line because part of Ring fails
3	Sync. connector	Data sharing and monitoring between two CPUS.

No.	Name	Description
(4)-a (4)-b	Connector for expansion connector	Connector used for connecting with expansion base  • For easy Ring configuration, two connector supported  • Two types, optical/optical, electrical/electrical
⑤-a	BOOT/NORMAL switch	Used to download OS at first time  • BOOT/NORMAL (right side): used for normal operation  • BOOT/NORMAL (left side): used to download OS (OS download mode).  Caution  (1) BOOT/NORMAL switch always should be set to right side. (2) In case of setting to left side, system doesn't operate properly and
⑤-b	A/B side switch (CPU position designation switch)	Designates the logical position of CPU  • Left side means CPU position is set as A  • Right side means CPU position is set as B  • Two CPU should have a different position. (available to check in the programming tool)  • In case two PLC are set as same position, the lately started one cause "E101" error
⑤-c	Reset/D. Clear switch	If it is moved left side, reset will be executed.  • move to left -> return to center: Reset executed  • move to left -> keep 3 seconds or above -> return to center: Overall reset executed If it is moved right side, data clear will be executed.  • move to right -> return to center:  : General data area and retain area will be cleared.  • move to left -> keep 3 seconds or above -> return to center:  : General data area, retain area and R data area will be cleared.
		(1) Data clear function is only executed in stop mode.
6	USB connector	Connector for connecting with peripheral (XG5000 etc.) (supports USB 1.1)
7	RS-232C connector	Connector for connecting with peripheral (XG5000 etc.)
8	Backup battery cover	Backup battery cover

# 4.3 Battery

# 4.3.1 Battery specifications

Item	Specifications
Nominal Voltage / Current	DC 3.0 V / 1,800 mAh
Warranty period	5 years(at ambient temperature)
Applications	Program/data backup, RTC operation in case of power failure
Туре	LiMnO2 Lithium Battery
Dimensions (mm)	φ 17.0 X 33.5 mm

# 4.3.2 Cautions for usage

- 1) Do not heat it up nor weld the electrode(it may reduce the life)
- 2) Do not measure the voltage with a tester nor short-circuit it(it may cause a fire).
- 3) Do not disassemble it without permission.

## 4.3.3 Battery life

The XGR-CPUH is designed to use it for 7 years and longer at any environment. However, the battery life varies depending on the duration of power failure, operation temperature range and etc.

If the battery voltage level is low, the CPU module generates a warning of 'Low Battery Level'. It can be checked by the LED of the CPU module, flag and error message in XG5000.

If it is occurred to a low battery level warning, please shortly change the battery.



# **Caution**

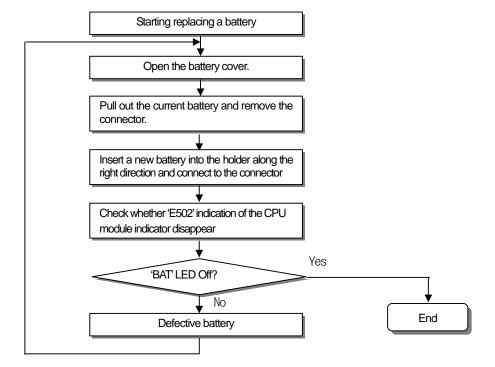
In general, it generates the warning after 7 years from the purchase, but if the current is excessively discharged due to defective battery or leakage current, it may warn it earlier. If it warns shortly after replacing a battery, the CPU module may need A/S service.

# **Chapter 4 CPU Module**

# 4.3.4 Replacement

A battery used as a backup power for program and data in case of power failure needs replacing regularly. The program and data is kept by the super capacity for about 30 minutes even after removing the battery, but it needs urgently replacing it as soon as possible.

Replace a battery in accordance with the following steps.

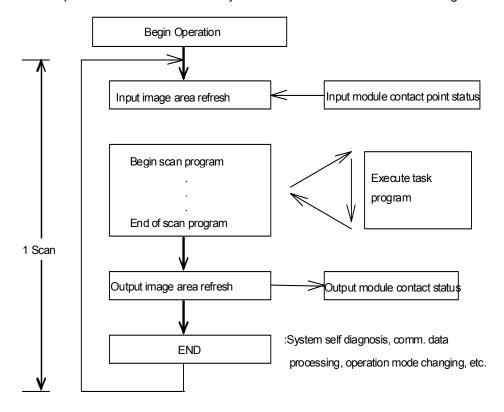


# 5.1 Program Basics

# 5.1.1 Program Structure and Execution

The program for the XGR PLC is made out with XG5000, compiled into an executable program, and transmitted to PLC for execution.

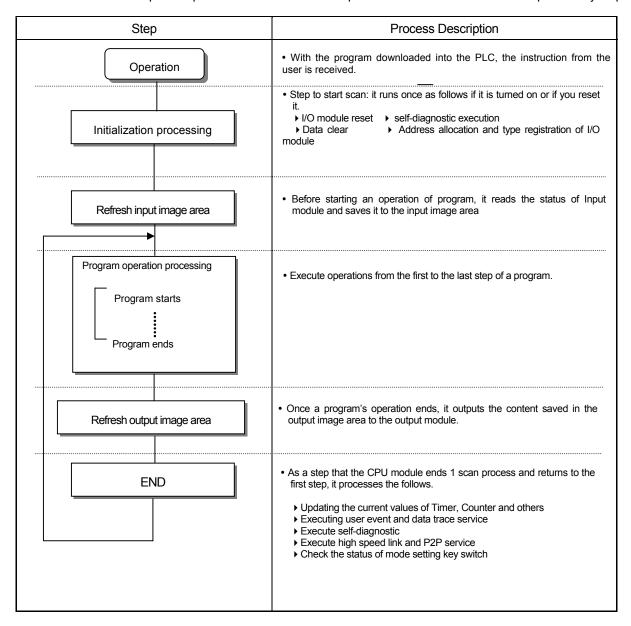
- 1) The programs can be classified into scan programs and task programs. The scan programs are executed at every scanning, and the task programs are executed by a task.
  - Scan program: the program executed every scan repeatedly
  - Task program: the program executed by task
- 2) A scan program runs from the first to the last step registered in the project in the registered order, and terminates the scanning (END). The entire process is referred to as "1 scan."
- 3) This process methodology which runs a program from the beginning to the end and then runs the entire process again, is called 'cyclic operation method.'
- 4) Before starting the operation of a scan program, the status of the input module is read and saved in the input image area, and the status of the output image area is outputted to the output module when the operation of the scan program is completed. This process is called 'I/O Refresh.'
- 5) XGR PLC series is based on the cyclic operation method. In the operation process, input or output status is not entered directly, but the operation is executed by I/O refreshing by scan unit basis. To this end, the statuses of the input and output contact points are stored in the memory area of the PLC. This area is called image area.



#### 5.1.2 Program Execution Methodology

#### 1) Cyclic Operation Method (Scan)

A program scan is an operation cycle of a program from the first step to the end step. In a cyclic operation, the first step is restarted after the end step of the previous scan has been completed. The table below shows this process by step.



#### Note

The synchronization between the data of the master CPU and standby CPU begins after the start-up of the standby CPU. See 5.3 Operation Mode for the details of redundant operation.

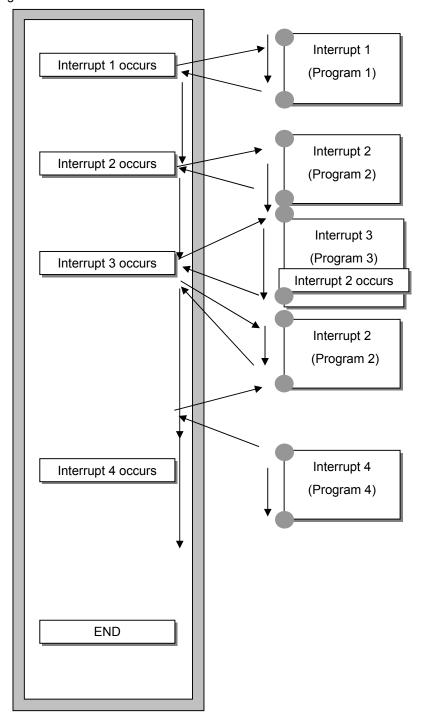
# 2) Interrupt Operation Method (Fixed Cycle Task Program)

In the interrupt operation method, if it is required to execute a task program with priority during scan program operation, the current scan program operation is interrupted and the task program is executed. When the task program operation is completed, the system returns to the previous scan program operation.

An interrupt signal instructs the CPU to execute a task program with priority.

A typical interrupt operation is the fixed cycle interrupt operation. In this method, the interrupt signals are generated at the times preset by the user to execute task programs. After the completion of a task program, the system returns to the scan program.

#### Scan program

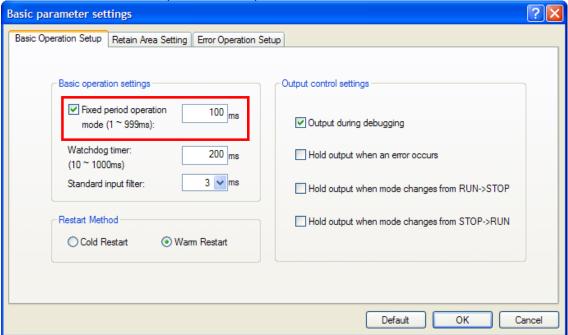


#### 3) Constant Scan

Constant scan is an operation method which repeats the execution of a basic scan program at fixed cycle time. In case that the fixed cycle time is longer than the time required for executing the scan program, the system waits for the remaining time, and restarts the scan program at the beginning of the next cycle time. Therefore, different from the fixed cycle task program, the program can be executed matching the I/O refreshing and synchronization. In such case, the scan time is indicated excluding the waiting time.

On the contrary, if the fixed cycle time is setup shorter than the time elapsed for the scan program execution, the '\_CONSTANT\_ER' flag is turned 'ON' and the operation is executed with the time during which the operation can be executed.

The constant scan can be setup with the basic parameters of the XG5000.



### Note

When configured for a constant scan operation, the scan time is indicated as follows.

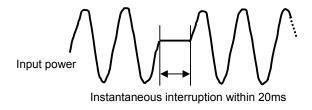
The maximum and current scan times are indicated with the scan times setup with the fixed cycle operation parameters, and the minimum scan time indicates the actual time elapsed for the program execution deducted with the waiting time.

## 5.1.3 Operation of instantaneous interrupt

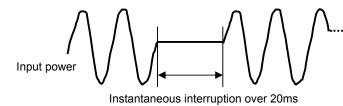
The CPU module detects instantaneous interruption when the voltage of input power supplied to the power module is lower than the nominal value.

If the CPU module detects instantaneous interruption, it processes operation as follows.

1) In case of instantaneous interruption within 20ms occurs



2) In case of instantaneous interruption over 20ms occurs



- (1) It stops an operation with the output at the moment of instantaneous interruption maintained.
- (2) It resumes the operation once the interruption is removed
- (3) The output voltage of power module is maintained within the specified value.
- (4) Even though an operation stops due to instantaneous power failure, timer measurement and interrupt timer measurements still work normally.
- (1) It executes initialization process such as when it is turned on
- (2) In a redundant CPU operation, the system triggers CPU switch-over.
- 3) If the system has a redundant power, the operation will be one of followings;
  - (1) Instantaneous power interruption in one of two power modules which have been in operation;
  - the other power module keeps operation, without interrupting PLC operation.
  - (2) Instantaneous power interruption in both power modules by shorter than 20ms;
  - the modules operate as described in Clause 1) above.
  - (3) Instantaneous power interruption in both power modules by longer than 20ms;
  - the modules operate as described in Clause 2) above.

#### Note

1) What is instantaneous interruption?

It means the status that the power supply voltage specified in the PLC is out of the allowable variance range and falls, and especially, a short term interruption(several ms ~ dozens of ms) is called instantaneous interruption.

2) CPU switching

In a redundant CPU operation, if a power interruption longer than 20ms occurs in all the power modules of the master CPU, the operation is switched over to the standby CPU. For the details of redundant operation, see 5.3 Operation Mode.

5-5

#### 5.1.4 Scan Time

The time required to complete all steps from the first step (0 step) to last step, that is, a time taken for one control operation is called 'scan time.' It is directly related to the control performance of the system.

#### 1) Operation and performance of XGR

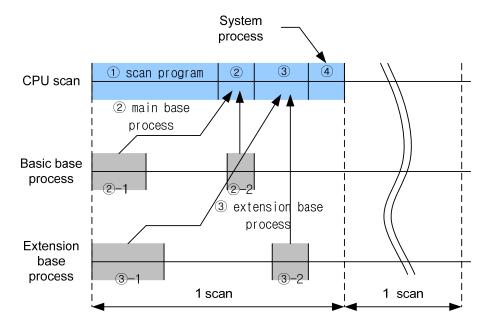
The major factors which influence scan time are program operation time, I/O data process time, communication service time, and the data synchronization between the master and standby CPUs. By utilizing the hardware relay method for the data exchange between expansion drive modules, the data communication performance of the XGR is greatly improved. In addition, the scan time is greatly reduced by MPU's ladder program execution and the paralleled execution of the I/O data scanning by bus controller.

In a single CPU operation, the scan process times of CPU are as follows.

Item	Content to be processed	time
Process time of scan program	Scan program+ Task program	42ns per 4 byte of execution program
Process time of basic base	Module process	Communication module: within 200 $\mu$ s per one
	Communication service	Within 500 $\mu$ s per one service
	Every expansion base	Within 300 ⊭s per one base
	Module process	Digital I/O: within 10 \( \mu \sigma \) per one Special module: within 30 \( \mu \sigma \) Communication module: within 150 \( \mu \sigma \)
Process time of Expansion base	Communication service	Within 1000
Dase	PUT/GET instruction process	Different according to data  ~ 0.5 kbyte: 800 \( \mu \sigma \) or less  ~ 1 kbyte: 2.5 \( \mu \sigma \) or less  ~ 4 kbyte: 8 \( \mu \sigma \) or less  ~ 8 kbyte: 15 \( \mu \sigma \) or less
Process time of system	Basic O/S process routine, module error check, Fault mask, I/O skip etc.	Different according to setting environment In case of normal operation, within 4ms

2) Calculation of scan time (Single CPU operation)

The CPU module executes controls along the following steps. A user can estimate the control performance of a system that the user is to structure from the following calculation.



Scan time = 1 scan program process + 2 basic base process + 3 expansion base process + 4 system process

1) Scan program process = program size/4 x 0.042 (usec)

(For correct scan time calculation, add the execution speed of the applied instructions.)

- 2 Basic base process
  - 2-1. module process: processes refresh data of module in basic base
    - Communication module: 200  $\mu$ s or less per one
  - 2-2. communication service process: executes HS, P2P service
    - 500 \( \mu \s \) or less per one service
- 3 Expansion base process
  - 3-1. module process: processes refresh data of module in basic base
  - Process time per expansion base: 300  $\mu s$  or less per expansion base
  - Digital I/O: 10 \( \mu \s \) or less per one
  - Special module: 30  $\mu$ s per one
  - Communication module: 150  $\mu$ s or less per one
  - 3-2. Communication service process and PUT/GET instruction process: executes HS, P2P service and PUT/GET instruction set by user
    - Communication service process: 1000  $\mu$ s or less per service
    - PUT/GET instruction process
      - ~ 0.5 kbyte : 800  $\mu$ s or less
      - ~ 1 kbyte : 2.5 ms or less
      - $\sim$  4 kbyte : 8 ms or less
      - ~ 8 kbyte: 15 ms or less

- System process: executes system internal process includig basic O/S process routin, battery check, module error check,
   I/O skip, forced I/O, loader service etc.
  - different according to the environment In case of normal 4ms or less

#### Example

CPU(program 32KB) + 6 32-point I/O modules + 6 analog modules (total PUT/GET size 1000byte) + 4 communication modules (two in basic base, other two in expansion base, one communication service setting for each module) What is the scan time of above system (the number of expansion base is 2)

Scan time( $\mu$ s) = ladder process time + basic base process time + expansion base process time + system process time =  $(32768/4 \times 0.042) + (200 \times 2) + (200 \times 2)$ 

= 11384 µs

= 11.4 ms

#### 3) Scan time monitor

In an actual XGR CPU operation, the actual scan time can be obtained by monitoring following data.

(1) Scan time is saved into the following flag(F) areas.

\_SCAN\_MAX : max. value of scan time(unit of 0.1ms)

\_SCAN\_MIN : min. value of scan time(unit of 0.1ms)

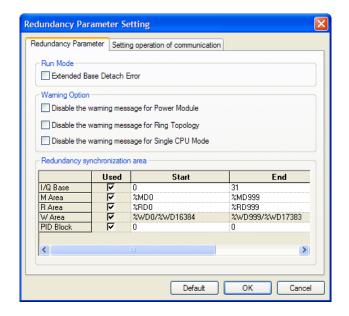
SCAN CUR: current value of scan time (unit of 0.1ms)

\_SCAN\_MAX, \_SCAN\_MIN value can be initialized using \_SCAN\_WR flag.

If the \_SCAN\_MAX is larger than WDT (Watch Dog Timer) value, a system error occurs. The WDT time can be setup with the basic parameters.

## 4) Scan Time in Redundant Operation

In redundant operations, compared with single CPU operation, the scan time substantially increases due to the system data sharing between the CPUs. The scan time also varies according to the data volume setup by the user in the redundancy parameter setting area. The increase in the scan time by data volume is as follows.



Redundancy parameter	Contents	Operation	
Run mode	Expansion base power cut error	Enable error message when all power modules in expansion base is off.	
	Disable the warning message for Power Module	Disables warning message when one between two power modules in expansion base is off	
Warning option	Disable the warning message for Ring Topology	Disables warning message when configuring line	
	Disable the warning message for Single CPU Mode	Disables the warning message for Single CPU Mode	

- (1) Redundant CPU system data: share basic data, e.g., system flag, communication flag, etc. (2.8ms)
- (2) Redundancy parameter setting data: synchronization time in each area is as follows; I/Q base: 1ms/32 bases

M area: approx. 250  $\mu$ s per 2 kwords. Approx. 16 ms for synchronizing 128kword

R area: approx. 1.5ms per 2 kword. Approx. 12ms for max. 16 kword synchronization. (When 2 kword in R area is transmitted, 2 kword in W area are also transmitted; total 4 kword are transmitted)

PID Area: 016.7  $\mu$ s required for each PID setting one loop. When max. 8 blocks are synchronized, approx. 4ms is required.

#### Example

CPU(program 32KB) + 6 32-point I/O modules + 6 analog modules (total PUT/GET size 1000byte)

+ 4 communication modules(two in basic base, other two in expansion base, one communication service for each one module) what is the scan time of above system? (Two expansion bases, synchronizes M area 2kword and PID 2 blocks)

Redundancy Run scan time = single Run scan time + time for synchronizing redundancy data

- = Single Run scan time + redundancy system data+ I/O base + synchronizing M area and PID area
- = 11.4ms + 2.8ms + 1ms + 0.25ms + 0.5 x 2
- = 16.45

#### 5) Delay Time at Entering Redundancy Operation

When a redundant CPU is added to single CPU operation, the scan time of the current scan cycle is increased temporarily, for the standby CPU to be initiated to enter redundancy operation mode. Since the data synchronization is carried out by 10% equivalent to the scan time of single operation, the scan time during the data synchronization increases by about 10% compared with single operation.



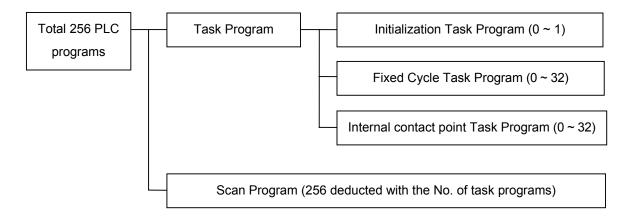
# **Caution**

- 1) When the standby CPU is activated to change the system from single operation to redundant operation, the scan time increases for a short time to synchronize the program and data from the master CPU to the standby CPU.
- It should be noted that, during single mode operation, including when the standby CPU is not in operation, data is not synchronized between the master CPU and standby CPU. Therefore, the data may differ from each other CPU.

# 5.2 Program Execution

## 5.2.1 Program Type

The programs for the XGR PLC can be classified as presented in the chart below, according to their conditions of execution. Total 256 programs can be used.



#### 5.2.2 Program Execution

#### 1) Task Program

#### (1) Initialization Task Program

The initialization task programs are used for system initialization when starting PLC operation in cold or warm restart mode.

During the execution of an initialization task program, the system operation status information flag \_INIT\_RUN is turned to ON.

The initialization task program executes cycle operation including I/O refresh until the INIT DONE flag is ON.

#### (2) Fixed Cycle Task Program

Fixed cycle task programs are executed in repetition at the cycle setup in the task.

## (3) Internal Contact Point Task Program

The internal contact point task programs are executed when such events as rise, fall, transition, on, or off of the internal contact points occur.

The point of time of execution is determined by the condition of event occurrence after the completion of scan program.

## 2) Scan Program

In order to process the signals which are repeated regularly in each scan, the operation is executed from the first (0) step to the last step in the sequential order.

In case that a condition of interrupt execution is met by the fixed cycle task or interrupt module during the execution of scan program, the current program is suspended, and the respective task (interrupt) program is executed. The occurrence of an event of internal contact point program is checked when the scan program has been completed.

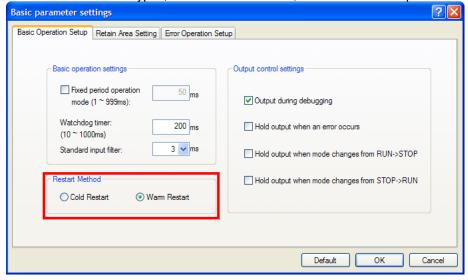


# Caution

- Of the initialization tasks, the first scan On/Off is executed for the first scan only, and not executed from the next scan until the completion of \_INIT\_DONE.
- The above mode applies when the master CPU is started from stop state. Since the standby operates according to the status of the master, restart mode does not apply.
- For manual reset switch activation in redundant operation, please take care of followings; Activating the reset switch of the master CPU will restart the entire system, but activating the reset switch of the standby CPU will restart the standby CPU only.
- When activating the Run/Stop switch during redundant operation, please take care of following; If you activate Stop switch of CPU operating as master, CPU operating as master will become Stop mode and standby CPU will operates as master

#### 5.2.3 Restart Mode

The restart mode sets up the method of initializing variables and the system at the start-up of PLC operation. Restart mode has two types; cold and warm restart, which can be set up in the basic parameters of the XG5000.



When the standby CPU starts up, it executes the initialization according to the restart mode and receives the program and data backup from the master. When set up in flash operation mode, it receives the flash data backup from the master too.

When the standby CPU is switched to master CPU during operation, it is not a restart, therefore, no further action is taken.

The conditions of the execution of the restart modes are as follows.

#### 1) Cold restart

- (1) All data is reset (deleted) to "0." Here, the 'all data' means the M area, R area, and automaton variables. The flag area, such as PID, which does not belong to this category is not deleted.
- (2) Only the variables whose initial values are set up are reset to the initial values.
- (3) Even though the parameter is set up to warm restart mode, at the first running after changing the program to be executed, the following program will be executed with cold restart mode.

(4) Pressing the manual rest switch for 3 seconds (same as the overall reset of the XG5000), the system will start in cold restart mode regardless of the set up restart mode.

#### 2) Warm restart

- (1) The data which was set up to maintain previous value will maintain the previous value. The data which has user defined initial value will be reset to the initial value. Other data will be deleted to "0."
- (2) When set up in warm restart mode, too, the first run, after an interruption by program download or error, will be started in cold restart mode.
- (3) When set up in warm restart mode, if the data is abnormal (data was not maintained during a power failure), the system will be started in cold restart mode.
- (4) Pressing the manual reset switch for less than 5 seconds during power-on, same as the reset instruction in the XG5000, if the setting is warm restart mode, the operation will begin in warm restart mode.

Data initialization according to the restart modes are as follows.

The variables related with restart mode are default, retain, and initialization variables. The method of initializing the variables in the execution of restart mode is as follows.

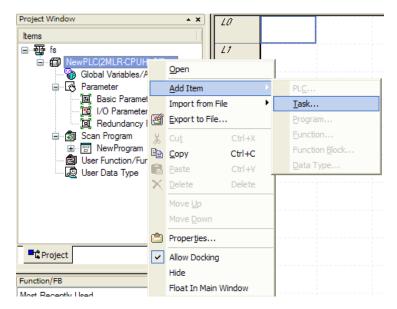
Mode Variable	Cold	Warm
Default	Initialize to '0'	Initialize to '0'
Retain	Initialize to '0'	Maintain the previous value
Initialization	Initialize to user defined value	Initialize to user defined value
Retain & Initialization	Initialize to user defined value	Maintain the previous value

## 5.2.4 Task Program

This section describes the programming and configuration of the task programs with XG5000 which is the programming software of the XGR.

### 1) Programming Task Programs

(1) In the project window of the XG5000, select the PLC to which the task is added. Click the right button of mouse, and select [Add Item]-[Task].



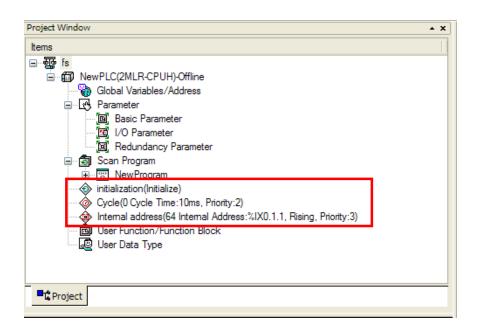
(2) In the Task dialog box, set up the task to be added, and click Confirm button.



# Note

External contact point task is not supported in the XGR PLC Series, and will be developed in the near future.

(3) The configured task will be displayed as shown in the window below. For detail configuration, see the User Manual of the XG5000.



### 2) Task Types

The below table summarizes the types and functions of tasks.

Type Spec.	Initialization	Cycle time	Internal address
Number	1	32	32
Start-up condition	When entering RUN mode, prior to starting scan program	Cycle time (settable up to 4,294,967.295 seconds at the unit of 1ms)	Conditions of internal device designation
Detection/exec ution	Execute until the flag _INIT_DONE is ON	Cyclically execute at the predefined interval.	Checks and Executes after completing scan program
Detection delay time	-	Delayed as long as 0.2ms to the max.	Delayed as long as the max. scan time.
Execution priority		Setting 2 ~ 7 levels (level 2 is the highest priority)	Setting 2 ~ 7 levels (level 2 is the highest priority)
Task number	-	Assigning it between 0~31 so that it is not duplicate	Assigning it between 64~95 so that it is not duplicated

#### 3) Processing method of task program

It describes the common processing method and cautions of task program

#### (1) Features of task program

- Task program does not reiteratively be processed like a scan program and instead, it is executed only when the execution conditions occur. Make sure to remember this when creating a task program.
- For instance, if a task program with 10 seconds of fixed cycle is used with a timer and counter, the timer may have an error of 10 seconds maximum while the counter checks every 10 seconds, any counter input changed within 10 seconds is not counted.

#### (2) Execution priority

- If several tasks to execute are waiting, it processes from the highest priority task program. If there are several tasks of same priority, they are processed by the order which is occurred.
  - The task priority is applied to only each task.
  - · Please set the priority of task program considering program features, importance level and urgency demanding execution.

#### (3) Process delay time

The delay of task program processing occurs due to the following factors. Make sure to consider them when setting a task or creating a program.

- Task detection delay(please refer to the details of each task)
- Program execution delay due to the execution of preceding task program

#### (4) Correlation between scan program and task program in the initialization

Fixed Cycle task and internal contact point task does not operate while initialization task program is working.

Since scan program has a low priority, if a task occurs, it stops a scan program and executes a task program. Therefore, if tasks frequently occur during one scan, a scan time may increase unreasonably. A special attention should be paid when setting the conditions of task.

- (5) Protection from task program of a currently running program
  - If program execution continuity is lost by executing a higher priority program, you can partially protect the task program from being executed, for a problematic part. At the moment, a program can be protected by application function commands of 'DI (task program operation disabled)' or 'EI(task program operation enabled)'
  - Insert the application function command, 'DI' into the beginning position of a section to be protected and the application function command, 'EI' to the position to cancel it. Initialization task is not affected by the application function commands of 'DI' and 'EI'.

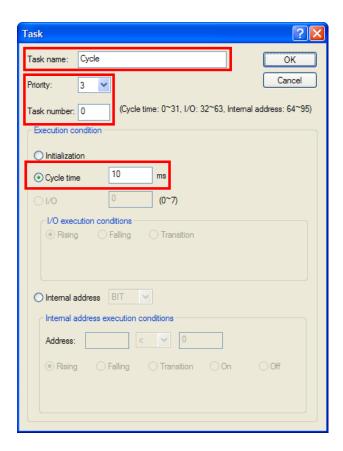
#### Note

1) If task program priority is duplicate set, a program works according to the creation order.

#### 4) Cycle Time Task Program

### (1) Setting up cycle task

The window below shows the setting up of a fixed cycle task. In order to set up a fixed cycle task, enter task name, priority, and task number for task control, and select Fixed Cycle radio button in the Condition of Execution, and enter the cycle time of execution.



#### (2) Fixed cycle task processing

• Execute a fixed cycle task program at a pre-defined interval.

## (3) Cautions for using a fixed cycle task program

- •If a same task program is to be executed when a fixed cycle task program is in operation or waiting for execution, a new task is ignored.
- Only for a moment when the operation mode is RUN, a timer requiring executing a fixed cycle program is counted. Any interruption time is ignored.
- Remember that several fixed cycle task programs are to be executed simultaneously when setting the execution cycle of a fixed cycle task program.

If using 4 fixed cycle task programs of which cycle is 2, 4, 10 and 20 seconds respectively, it may have simultaneous execution of 4 programs every 20 seconds, probably causing a longer scan time.

# <u>/!</u>\

# Caution

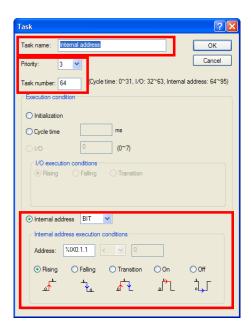
- 1) Note that if the total time length during which cycle time task are executed simultaneously is longer than the specified time length when several cycle time tasks occur simultaneously, a short cycle time task may not be successfully executed.
- 2) The only cycle time task of which cycle is longer than scan cycle can be guaranteed for the fixed cycle.

#### 5) Internal device task

Bit and Word device can be set as execution condition for task.

#### (1) Task setting

In order to set up an internal device task, set task name, priority, and task number, Internal Device, the type of device and the condition of start up (Rising, falling, transition, on and off)



#### (2) Internal Device Task Handling

After the completion of scan program by CPU module, the internal device task program will be executed if starting condition is met according to the priority.



# **Caution**

Internal address task program is executed at the moment when a scan program is completely executed. Therefore, although a scan program or task program generates the execution conditions of internal address task program, it is not immediately executed and instead, it is executed at the moment when a scan program is executed completely. Therefore, if the execution conditions of internal address task occur and disappear within a scan program, a task is not executed because it is not detected at the moment when the execution conditions are surveyed.

### 6) Task processing in instantaneous interruption

When resuming operation due to a long instantaneous interruption, ignore any waiting task and tasks that occur during the interruption and process the only tasks from the moment of starting operation. If an interruption is within 20ms, a task that was waiting is executed once the interruption is removed. Any fixed cycle interrupt task that is duplicated during the interruption is ignored.

#### 7) Verification of task program

After creating a task program, verify it in accordance with the followings.

(1) Is the task set properly?

If a task occurs excessively or several tasks occur simultaneously in a scan, it may cause longer scan time or irregularity If a task setting can not be changed, check the max. scan time.

(2) Is the task priority well arranged?

A low priority task program may not be processed in a specified time due to a delay from a higher priority task program. The case may be, since the next task occurs with a preceding task delayed, it may cause task collision. The priority should be set in consideration of urgency of task, execution time and etc.

(3) Is the task program created as short as possible?

A longer execution time of task program may cause a longer scan time or irregularity. In addition, it may cause task program collision. Make sure to set the execution time as short as possible(especially, create a fixed cycle task program so that it could be executed within 10% of the shortest task cycle among several tasks.)

(4) Doesn't the program need to be protected against the highest priority task during the execution of program?

If a different task breaks into a task program execution, it completes a current task and then, operates from a task with the highest priority among waiting tasks. In case it is prohibited that a different task breaks into a scan program, it can be protected by using 'DI'/'EI' application functional commands. It may cause a trouble while processing a global parameter process commonly used with other program or a special or communication module.

#### 8) Program configuration and example of processing

First of all, register task and program as follows.

```
    Registering a task:
    T_SLOW (fixed cycle: = 10ms, Priority:= 3)
```

PROC\_1 (internal contact : = M0, Priority := 5)

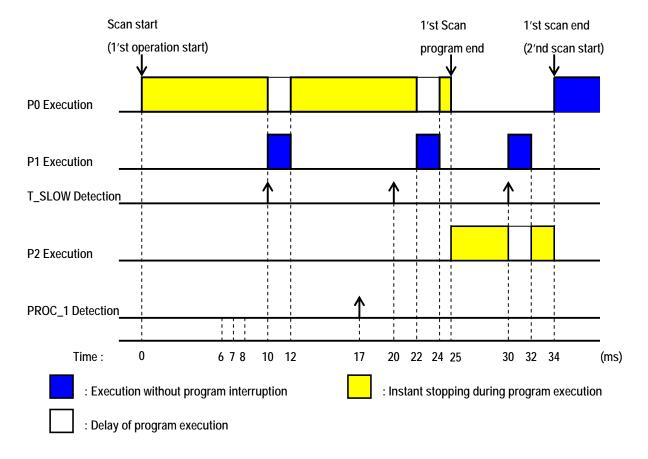
• Registering a program :

Program --> P0 (scan program)

Program --> P1 (operating by task T\_SLOW)
 Program --> P2 (operating by task PROC 1)

Then, if the program execution time and the occurrence time of external interrupt signal are same,

- Execution time of each program: P0 = 21ms, P1 = 2ms and P2 = 7ms, respectively
- PROC\_1 occurrence: During a scan program, the program is executed as follows.



# • Processing by time period

Time(ms)	Processing	
0	Scan starts and the scan program P0 starts operation	
0~10	Program P0 is executed	
10~12	P0 stops due to the execution request for P1 and P1 is executed	
17	Execution request for P2	
12~20	P1 execution is complete and the suspended P0 resumes	
20~24	20~24 P0 stops due to the execution request for P1 and P1 is executed	
24~25	24~25 As P1 execution is complete, the suspended P0 is completely executed.	
25	Check the execution request for P2 at the moment when scan program(P0) is complete and execute P2.	
25~30	Execute program P2	
30~32	P2 stops due to the execution request for P1 and P1 is executed	
32~34	As P1 execution is complete, the suspended P2 is completely executed.	
34 Start a new scan(P2 execution starts)		

# 5.3 Operation Mode

# 5.3.1 Operation Mode

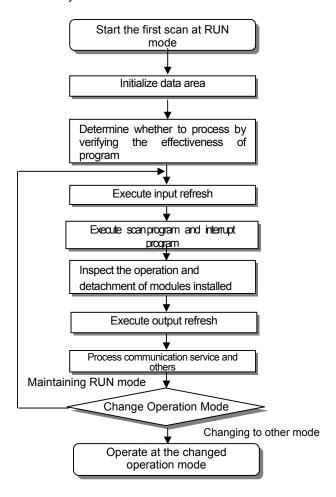
1) Program Execution Mode

Program execution mode is the status of program execution by the CPU module. There are three modes; Run, Stop, and Debug. The operational status of each mode may vary by the status of the redundant operation.

It describes the operation process at each operation mode.

### **5.3.2 RUN mode**

It executes a program operation normally.



- 1) Process of switching to Run mode
  - (1) When the PLC module is switched to the Run mode, the data area is initialized.
    - According to the set up restart mode (cold, warm)
  - (2) Check the program validity to judge the possibility of execution.

#### 2) Operation process

Execute I/O refresh and program operation.

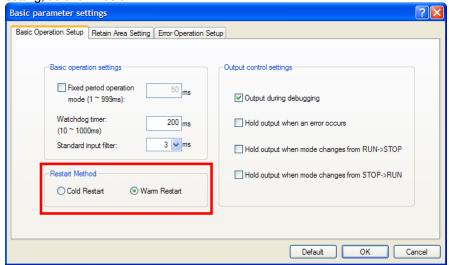
- (1) Execute the interrupt program by detecting the operation conditions of interrupt program.
- (2) Inspect the operation and detachment of modules installed.
- (3) Process communication service and other internal operations.
- (4) Synchronize the data between the master and standby CPUs.

#### 5.3.3 Stop Mode

It stops with no program operation. Program can be transmitted through XG5000 only at remote STOP mode.

1) Process in mode switching

When switched to the Stop mode, the output images are processed in two ways according to the basic parameter setting, as shown below.



When set up to maintain output in Run → Stop switching

When the mode is switched from Run to Stop operation, the output image area maintains the results of the last operation, and carries out output refreshing.

When the output is released from maintenance at switching from Run to Stop

When the mode is switched from Run to Stop operation, the output image area is deleted and output refreshing is carried out.

#### 2) Operation process

- (1) Execute I/O refresh.
- (2) Inspect the operation and detachment of modules installed.
- (3) Process communication service and other internal operations.

# 5.3.4 Debug Mode

As a mode to find any error from a program or trace an operation procedure, the mode can be changed only from STOP mode. In the mode, a user can verify a program while checking the program execution and data.

- 1) Processing when a mode is changed
  - (1) At the beginning when the mode is changed, initialize the data area.
  - (2) Clear the output image area and execute input refresh.
- 2) Operation process
  - (1) Execute I/O refresh.
  - (2) Debugging operation depending on the settings.
  - (3) After completing debugging operation to the end of the program, it executes output refresh.
  - (4) Inspect the operation and detachment of modules installed.
  - (5) Process communication service and other internal operations.

### 3) Conditions of debug operation

There are four types of debug operation conditions and if reaching the break point, it is possible to set a different type of break point.

Operation condition	Description
Stepwise execution of operation(step over)	Upon an operation command, it executes a unit of operation and stops
Execution according to the designation of break point	Once a break point is designated in a program, it stops at the designated point
Execution according to the status of contact	If designating the contact area to monitor and the status(read, write, value), it stops when the designated operation occurs at the pre-defined contact.
Execution according to the designated scan frequency	Once designating the scan frequency to operation, it stops after operating as many as the scan frequency designated.



# **Caution**

- 1. Debug mode is only available in single system.
  - (1) To use debug mode, turn off the power of standby CPU and so that the system runs in single.
  - (2) Convert to remote stop mode by mode key switch.
- 2. During debug mode, the user can't change mode by mode switch.
- 4) Operation method
  - (1) Set the debug operation conditions at XG5000 and execute the operation.
  - (2) The interrupt program can be set by enabled/disabled at the unit of each interrupt.

    (For the details of operation, please refer to Chapter 12 Debugging in the user's manual of XG5000)

#### 5.3.5 Switching Operation Mode

1) How to change an operation mode

An operation mode can be changed as follows.

- (1) Mode change by the mode key of the CPU module
- (2) Change by accessing the programming tool(XG5000) to a communication port of CPU
- (3) Change of a different CPU module networked by XG5000 accessed to a communication port of CPU
- (4) Change by using XG5000, HMI and computer link module, which are networked.
- (5) Change by 'STOP' command while a program is operating.

#### 2) Type of Operation Mode

(1) Changing program execution mode with mode key the method of changing operation mode using mode key is as follows.

<b>1</b>		
Mode Key Position	Operation Mode	
RUN	Local RUN	
STOP	Local STOP	
$STOP \to REM$	Remote STOP	
$REM \to RUN$	Local RUN	
$RUN \rightarrow REM$	Remote RUN	
$REM \rightarrow STOP$	Local STOP	

# (2) Changing remote operation mode

Changing remote modes can be done with the operation mode switch at 'Remote Allowed: REM.'

Mode Key Position	Mode change	Mode change by XG5000	Change by computer communication, etc.
REM -	$Remote\;STOP\toRemote\;RUN$	0	○(review)
	Remote STOP → DEBUG	0	X
	Remote RUN $\rightarrow$ Remote STOP	0	0
	Remote RUN $\rightarrow$ DEBUG	X	X
	DEBUG → Remote STOP	0	0
	$DEBUG \to Remote \; RUN$	X	Χ

# **Caution**

If changing the remote 'RUN' mode to 'RUN' mode by switch, the PLC is continuously operating without suspension.

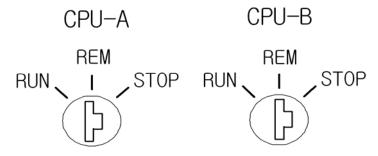
Editing during RUN is possible in the 'RUN' mode by switch, but the mode change by XG5000 is restricted. Make sure to change it only when the mode change is not remotely allowed.

# 5.4 Redundancy System Operation

# 5.4.1 Redundancy System Operation

#### 1) Redundant operation mode

A redundant system has data synchronization (SYNC) cable between CPUs. Each CPU module has a key switch for operation mode setting. The key switches look as shown below;



The operation statues of redundancy system can be classified as flows according to the installation, power supply, whether dada communication cable is connected between the CPUs, and the operation mode of each CPU.

Data sync. Cable between CPUs	Current operation status	Operation mode of CPU-A(B)	Operation mode of CPU-B(A)	Description
Connected	Single operation	RUN	STOP	Only CPU-A or CPU-B is operating in redundant operation mode. Same single CPU operation.
	Redundant operation	RUN	RUN	In redundant operation mode, CPU-A and CPU-B are set up as master and standby to perform redundant operation.
	Operation stopped	STOP	STOP	CPU-A and CPU-B are set up as master and standby to perform redundant operation, but the operation is stopped.
Not connected	Single operation	RUN/STOP	-	The operation is same as a single CPU operation.

# **∕** Caution

When a standby CPU is added to a system operating with a single CPU (master) for redundant operation, the additional (standby) CPU must be installed in accordance with following procedures for uninterrupted operation of the PLC.

With the power of the standby-side base OFF, construct a same module as the master-side base.

Install the standby CPU in the CPU mounting slot. And set the A/B side switch in Standby CPU differently from Master CPU

Connect the CPUs with the data synchronization cable (Sync cable) and expansion cable.

Confirm that the cables are correctly connected, turn the power of the standby base ON.

Turn the operation mode switch to Local Run mode, so that the standby CPU is incorporated in the redundant operation.

The standby CPU must be incorporated in the redundancy system operation to be able to run the same programs as those of the master CPU.

(Take care that, if the standby CPU has not been participating in the redundant operation, its program may differ from that of the master CPU.)

#### 2) Changing redundant operation mode

(1) According to the change of the CPU operation mode with mode key or by XG5000, the operation mode of the redundant system is changed as follows.

	Mode C	hange	Description
Current Status	Master Operation	Standby Operation	
Single Operation	$RUN \to STOP$	STOP status is maintained	When the master is changed to STOP state, the operation is stopped
(RUN/STOP)	(No change: RUN)	→ RUN	Changing the standby to Run mode, the operation is changed to redundant operation.
Redundant	$\rightarrow$ STOP	(No change: RUN)	If the master is changed to STOP, the standby becomes master in single operation status.
Operation (RUN/RUN)	(No change: RUN)	→ STOP	If the standby is changed to STOP, the master operates in single operation mode.
Operation Stop (STOP/STOP)	$\rightarrow$ RUN	(No change: RUN)	The one, A or B, that enters RUN mode first gets the operation control and becomes the master in single operation status.

#### 3) Changing master in redundant operation

- (1) Conditions for automatic master switching
- A. Master CPU power supply failure
- B. Master CPU stopped due to failure in program execution
- C. Module removal/replacement error in the master CPU's basic base
- D. Master CPU failure (CPU excluded)
- E. Module on an expansion base is removed (isolated)
- F. A system error in the master CPU (abnormal termination of CPU, scan watchdog error)
- (2) Conditions for manual master switching
- A. Master CPU's mode key switch is set to Stop
- B. Switched to Stop mode by the XG5000 connected with the master CPU
- C. Execution of master switching instruction via XG5000 online access
- D. Master/standby switching instruction (MST\_CHG) is executed
- E, Master/standby switching flag (\_MASTER\_CHG) is executed.

- (3) Conditions that do not switch master
- A. One of two power supply fails
- B. Master fails when the standby has been failed
  - a) If the same failure is identified, the operation is stopped.
  - b) When en error is detected in the module in which error mask has been set up, the master is not switched.
- C. When the standby CPU is not in Run operation state

#### 5.4.2 Start-up of Redundant System

- 1) Programming
  - (1) Conduct programming with XG5000.
  - (for details, see 'XG5000 User Manual'.)
  - (2) Transmit the program
  - Transmit the program with XG5000.
- 2) Starting methods

Following methods are available for starting-up PLC;

(1) Starting with local key:

Download the program in remote mode (REM), set the front key to 'RUN'

(2) Starting with XG5000:

Set the front key on the CPU module to 'REM,' select RUN on the XG5000's online menu.

(3) Starting by power ON:

When the power is turned ON with the front key set to RUN or if the system was in Remote RUN mode before power OFF, the system can be started by power ON.

(4) Restarting with reset key:

Restarting with reset key has two methods; Reset and Overall Reset

- Reset: activated by pressing the reset button on the front of the CPU module less than 3 seconds. 'RST' will appear on the indicator panel of the CPU. This is the same as power ON/OFF.
- Overall Reset: activated by pressing the reset button on the CPU module for more than 3 seconds. 'RSTC' will appear on the indicator panel of the CPU. When the button is released, the system will be restarted in cold restart.

### 3) Beginning the first operation

The procedures of system setting-up and starting-up for the first time operation of a redundant system are as follows.

- (1) Prepare the program bocks suitable for the purpose, in as independent forms as possible
- (2) In the redundancy parameters, set up the data synchronization area.
- (3) When the programming is completed, compile it and carry out debugging.
- (4) Using the XG5000 program tool, access CPU communication port and download the program
- (5) Switch CPU-A or B to RUN mode using the mode switch key or XG5000.
- (6) Switch the CPU which is not the master to RUN mode to set it to the standby CPU
- (7) Stop the CPU-A to check normal operation of the standby CPU-B.

#### 4) Participating in operation

When the standby CPU participates in the operation while the master CPU is in operation, the standby CPU is synchronized with the master CPU in following procedures.

- (1) CPU initialization
- (2) Checking the redundant components
- (3) Transfer non-variable data to the master
- (4) Transfer variable data from the master

- (5) Check synchronization with the master CPU
- (6) Participate in the operation at the same time as the master CPU

#### Note

- For the redundant operation mode setting and parameter setting, see '6.7 Redundant System Operation
- (1), (2), and (3) are processed separately with delay time less than approximately 50ms at every scan of the master.
- (4), (5), and (6) must be processed within one scan of the master, with the delay time not exceeding 50ms. (If the volume of the variables used exceeds the standard variable value, the delay time may exceed 50ms. For further information, see '5.1.4 Scan Time')

- 5) Procedures of participating in standby operation
  - Detail procedures of participating in standby operation are as follows.
  - (1) Power ON
    - Check that the master is in operation
    - Standby entering mode
    - CPU self diagnosis
    - Transfer program from the master (store in RAM and memory module)
  - (2) Checking redundant system components
    - Check switching I/O access
    - Receive and check switching I/O module information from the master
    - Scan the redundant I/O module information installed in the standby-side
    - Compare with the I/O parameters
  - (3) Transfer non-variable data from the master
    - Receive the flag from the master (executed by being divided into multiple scans as necessary)
    - After confirming that the flag status has not been changed, proceed to (4)
  - (4) Receive the variable data from the maser
    - User data area and a part of system buffer
  - (5) Check synchronicity with the master
    - All the operation data in the CPU is synchronized
  - (6) Participate in the operation at the same time as the master
    - Conduct redundant operation from the input refreshing
- 6) Operation according to starting status
  - (1) Normal start-up

The master CPU module checks system configuration at power ON. In case of late power on of the expansion base, the base being check appears on the front indicator panel and wait for power on.

In 'STOP' mode, wait for 10 seconds and switched to Stop mode.

- The first operation after program modification begins in cold restart.
- When the system had been shut-down normally, the restarting will be performed according to the set-up parameters, including mode key, XG5000, power OFF and reset.
- To cold-restart a system set up in warm restart mode, use reset key or the Overall Reset function of the XG5000.
- If the system was stopped due to an error in operation, the restarting method will be determined by the type and release method of the error (see 'Chapter 13. Program Troubleshooting').
- (2) When I/O skip has been set up
- Since the I/O module set up with skip is excluded from the operation in the restarting, failure check, etc., are not conducted, and included in the operation normally when the skip is released during operation. For detail information, see '9.2 I/O Skip' and '9.3 Module Replacement during Operation.'
- (3) When failure mask has been set up
- Since the modules set up with failure mask are included in the operation in the restarting, failure check, etc., are conducted. However, even if module type disagreement error occurs in the initial phase of the restart, the operation is continued. For further information, see '9.1 Failure Mask.'
- When the entire bases are set up with mask, if the power of the respective base is off, the CPU waits for power on in waiting mode.

# 5.5 Memory

The CPU module contains two types of memory that can be used by a user. One is the program memory to save a user program created to construct a system and the other one is the data memory to provide a device area to save the data during operation.

# 5.5.1 Program memory

The storage capacity and data area type of the program memory are as follows.

Item(area)		Capacity	Remark
Whole memory area		25MB	Whole memory capacity
	Program Memory	3МВ	Include Upload
	System Memory	4MB	System data and parameter area
	Data Memory	2MB	Device memory, Flag, System area
	Flash Memory	16MB	For flash operation mode

### 5.5.2 Data memory

The storage capacity and data area type of the data memory are as follows.

Item(area)		Capacity
Whole	data memory area	2MB
S	System area :	
•	I/O data table	770KB
• Fo	orcible I/O table	TTORB
• F	Reserved area	
	System flag	4KB
	Analogue image flag	8KB
Flag area	PID flag	16KB
	High speed link flag	22KB
	P2P flag	42KB
Inpu	t image area(%I)	16KB
Outpu	it image area(%Q)	16KB
R area(%R)		128KB
Direct parameter area(%M)		256KB
Symbolic	parameter area(max.)	512KB
	Stack area	256KB

### 5.5.3 Data retain area setting

If the data necessary for operation or the data that occur during operation are to be kept for use even when the PLC stops and resumes operation, the default(auto.) parameter retain is to be used. Alternatively, a part of the M area device may be used as the retain area by parameter setting.

The following table summarizes the features of retain settable device.

Device	Retain setting	Feature
Auto variable	User-defined	Retain settable if adding a parameter to the auto parameter area
M	User-defined	Retain settable into internal contact area by parameter
K(PID)	X	Contact that is kept as contact status in case of interrupt
F	Χ	System flag area
U	Not retained	Analogue data register (retain not settable)
1	Not retained	High speed link/P2P service status contact of communication
L <sub>i</sub>	(V1.1 or above)	module(retained)
N	X	P2P service address area of communication module(retained)
R	X	Exclusive flash memory area(retained)

- 1) K, L, N and R devices are basically retained.
- 2) K, L and N devices can be deleted in the memory deletion window of PLC deletion, an online menu of
- 3) For details of directions, please refer to the 'Online' in the user's manual of XG5000.

#### 1) Data initialization by restart mode

There are 3 restart mode related parameters; default, initialization and retain parameter and the initialization methods of each parameter are as follows in the restart mode.

Mode Parameter	Cold	Warm
Default	Initializing as '0'	Initializing as '0'
Retain	Initializing as '0'	Maintaining the previous value
Initialization	Initializing as a user-defined value	Initializing as a user-defined value
Retain & initialization	Initializing as a user-defined value	Maintaining the previous value

#### 2) Operation in the data retain area

Retain data can be deleted as follows.

- D.CLR switch of the CPU module
- RESET switch of the CPU module (3 seconds and longer: Overall Reset)
- RESET by XG5000 (Overall Reset)
- Deleting memory at STOP mode by XG5000
- Writing by a program (recommending the initialization program)
- Writing '0' FILL and etc at XG5000 monitor mode

D.CLR clear does not work at RUN mode. To do it, after make sure to change to STOP mode. In addition, the default area can be also initialized when clearing by D.CLR switch.

When instantaneously operating D.CLR, the only retain area is deleted. If maintaining D.CLR for 3 seconds, 6 LEDs blink and at the moment, if the switch returns, even R area data are also deleted.

For the maintenance or reset(clear) of the retain area data according to the PLC operation, refer to the following table.

Item	Retain M area retain		R area
Reset Maintaining the previous value		Maintaining the previous value	Maintaining the previous value
Over all reset	Initializing as '0'	Initializing as '0' Initializing as '0'	
DCLR Initializing as '0'		Initializing as '0'	Maintaining the previous value
DCLR (3sec)	DCLR (3sec) Initializing as '0' Initializing as '0'		Initializing as '0'
STOP→RUN	Maintaining the previous value	Maintaining the previous value	Maintaining the previous value

When STOP->RUN, in case it is set as Cold Restart, Retain Auto variable is initialized In case it is set as Warm Restart, Retain Auto variable is maintained.

#### Note

- 1) The terms and definitions for 3 types of variables are as follows.
- (1) Default variable: a variable not set to maintain the initial/previous value
- (2) Initialization(INIT) variable: a variable set to maintain the initial value
- (3) Retain variable: a variable set to maintain the previous value

#### 3) Data initialization

Every device memory is cleared up as '0' at the status of memory deletion. The data value may be assigned initially depending on a system and at the moment, the initialization task should be used.

# **Chapter 6. CPU Module Functions**

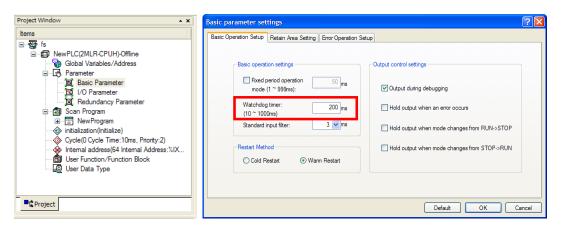
# 6.1 Self-diagnosis Function

- (1) The self-diagnostic is the function that the CPU module diagnoses any trouble of the PLC system.
- (2) It detects any trouble when turning on the PLC system or any trouble is found during the operation, avoid the system from malfunctioning and taking preventive measures.

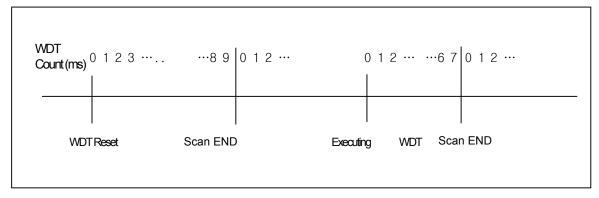
# 6.1.1 Scan watchdog timer

WDT(Watchdog Timer) is the function to detect any program runaway resulting from abnormal hardware/software of PLC CPU module.

1) WDT is a timer used to detect an operation delay from abnormal user program. It can be set in the basic parameter of XG5000.



- 2) WDT monitors any scan overtime during operation and if it detects any overtime delay, it immediately suspends the PLC operation and turns off every output.
- 3) If it is expected that programming a specific part(using FOR ~ NEXT command, CALL command and etc) may have an overtime delay of scan watchdog timer while executing a user program, you can clear the timer by using 'WDT' command. The 'WDT' command restarts from 0 by initializing the overtime delay of scan watchdog time(for the details of WDT command, please refer to the chapter about commands in the manual).
- 4) To release a watchdog error, turn it on again, operate manual reset switch or change the mode to STOP mode.



# Caution

- The setting range of the watchdog timer is  $1 \sim 999$ ms(1ms step), and the initial value is 200ms.
- If the cycle is set too short, scan watchdog time error may occur if the scan time is elongated by communication traffic overload, etc. It is recommended to set the cycle sufficiently longer that \_SCAN\_MAX

### **Chapter 6. CPU Module Functions**

#### 6.1.2 I/O Module Check Function

This function checks the I/O module when entering Run mode or during PLC operation

- 1) When entering Run mode, check if a module disagrees with the parameter setting or in failure (E030)
- 2) Check if the I/O module is isolated or failed during operation (E031)

If an abnormality is detected, the error indicator lamp (ERR LED) turns on, error number is indicated on the status indicator, and the CPU stops operation.

### 6.1.3 Battery level check

The function monitors battery level and detects, if any, low battery level, warning a user of it. At the moment, the warning lamp (BAT) on the front of the CPU module is On. For the details of measures, please refer to "4.3.3 Battery Life".

### 6.1.4 Saving error log

The CPU module logs, if any, errors so that a user can easily analyze the error and take corrective measures.

It saves each error code to the flag area.

#### Note

- 1) The results of self-diagnostic check are logged in the flag area.
- 2) For the details of self-diagnostic and troubleshooting against errors, please refer to 14.5 Error Codes List during CPU Operation of Chapter 13. Troubleshooting.

#### 6.1.5 Troubleshooting

#### 1) Types of trouble

A trouble occurs mainly by the breakage of PLC, system configuration error and abnormal operation results. 'Trouble' can be categorized by 'heavy fault mode' at which the system stops for the purpose of the system safety and 'light fault mode' at which the system warns a user of a trouble and resumes operation.

The PLC system may have a trouble by the following causes.

- · Trouble in the PLC hardware
- System configuration error
- Operation error while a user program is operating
- Error detection resulting from a fault external device

#### 2) Operation mode when a trouble is found

If a trouble is detected, the PLC system logs the trouble message and stops or resumes operation depending on a trouble mode.

#### (1) Trouble in the PLC hardware

If heavy fault that the PLC may not properly work, such as CPU module, power module and others occurs, the system stops. However, the system resumes operation in case of light fault such as abnormal battery.

#### (2) System configuration error

It occurs when the hardware structure of PLC is not same as defined in the software. At the moment, the system stops. This occurs at module type disagreement error, module isolated error, or when the I/O mounted on the PLC differs from the I/O set up in the XG5000.

(3) Operation error while a user program is operating

In case of numerical operation error as a trouble occurring while a user program is operating, error flag(\_ERR) and error latch flag(\_LER) are displayed and the system resumes operation. If an operation time exceeds the overtime delay limit or the built-in I/O module is not controlled, the system stops.

#### Note

Error latch flag is maintained as long during a scan program if an error occurs in scan program. Every time a command is executed, error flag is cleared and set just after a command generating an error is executed.

(4) Error detection resulting from a fault external device

It detects a fault of external device; in case of heavy fault, the system stops while it just displays a fault of the device and keeps operating in case of light fault.

#### Note

- 1) If a fault occurs, the fault number is saved into the flag( ANNUM ER).
- 2) If light fault is detected, the fault number is saved into the flag( ANNUM WAR).
- 3) For further information about the flags, please refer to Appendix 1. Flags List.

#### (5) Error detection in redundant operation

Nonconformity of redundancy parameter is detected by the redundancy parameter error flag (\_DUPL\_PRM\_ER), and data communication error during redundant operation is detected by the redundancy synchronization error flag (\_DUPL\_SYNC\_ERR). If an error occurs, the system stops. In addition, the status information on the current redundancy system configuration is provided with the redundancy Configuration warning error flag (\_REDUN\_WAR). If this error is detected, the system displays the status but continues operation.

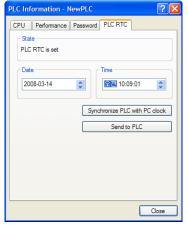
# 6.2 Clock Function

The CPU module contains a clock element (RTC), which operates by the backup battery even in case of power-off or instantaneous interruption.

By using the clock data of RTC, the time control for the operation or trouble logs of the system is available. The present time of RTC is updated to the clock-related F device per scan.

# 1) Read from XG5000/Setting

Click 'PLC RTC' in the online mode, 'PLC Information.'



# **Chapter 6. CPU Module Functions**

It displays the time from the PLC RTC. If it displays the present time incorrectly, a user can fix it up by transferring the right time after manually setting the time or performing "Synchronize PLC with PC clock" method to transmit the time of PC clock connected to the PLC.

#### 2) Clock reading by Flag

It can be monitored by flags as follows.

Flags	Examples	Size	F area	Description
_RTC_TIME[0]	16#08	BYTE	%FB12	Current time [year, last two digits]
_RTC_TIME[1]	16#02	BYTE	%FB13	Current time [Month]
_RTC_TIME[2]	16#23	BYTE	%FB14	Current time [Date]
_RTC_TIME[3]	16#14	BYTE	%FB15	Current time [Hour]
_RTC_TIME[4]	16#16	BYTE	%FB16	Current time [Minute]
_RTC_TIME[5]	16#17	BYTE	%FB17	Current time [Second]
_RTC_TIME[6]	16#06	BYTE	%FB18	Current time[day]
_RTC_TIME[7]	16#20	BYTE	%FB19	Current time [hundred year]

### 3) Clock data modified by program

A user also can set the value of clock by using a program.

It is used when setting the time manually by external digital switches or creating a system to calibrate a clock periodically on network.

Input a value into the below flag area and use the '\_RTC\_TIME\_USER' function block. The time data is updated in scan END.

Flags	Examples	Size	F area	Description
_RTC_TIME_USER[0]	16#08	BYTE	%FB3860	Current time [year, last two digits]
_RTC_TIME_USER [1]	16#02	BYTE	%FB3861	Current time [Month]
_RTC_TIME_USER [2]	16#23	BYTE	%FB3862	Current time [Date]
_RTC_TIME_USER [3]	16#14	BYTE	%FB3863	Current time [Hour]
_RTC_TIME_USER [4]	16#16	BYTE	%FB3864	Current time [Minute]
_RTC_TIME_USER [5]	16#17	BYTE	%FB3865	Current time [Second]
_RTC_TIME_USER [6]	16#06	BYTE	%FB3866	Current time[day]
_RTC_TIME_USER [7]	16#20	BYTE	%FB3867	Current time [hundred year]

Alternatively, instead of using function blocks, it is also possible to enter clock data into the above area and turn on 'RTC WR' in order to input the time.

- No input is allowed unless time data is entered in a right format (However, even if the day of the week data is not correct, it is set without error detected)
- After writing the clock data, check whether it is rightly set by monitoring Reading Clock device.

### 4) How to express the day of the week

Number	0	1	2	3	4	5	6
Day	Sunday	Monday	Tuesday	Wednesday	Thursday	Friday	Saturday

#### 5) Time error

The error of RTC varies depending on the operating temperature. The following table shows the time error for a day.

Operating temp.	Max. error (sec/date)	Ordinary (sec/date)
0 °C	- 4.67 ~ 1.38	-1.46
25 °C	- 1.64 ~ 2.42	0.43
55 °C	- 5.79 ~ 0.78	-2.29



# **Caution**

- 1) Initially, RTC may not have any clock data.
- 2) When using the CPU module, first make sure to set the accurate clock data.
- 3) If any data out of the clock data range is written into RTC, it does not work properly. i.e.) 14M 32D 25H
- 4) RTC may stop or have an error due to abnormal battery and other causes. The error is released if a new clock data is written.
- 5) For further information of how to modify the clock data, please refer to the description of XGI commands
- 6) In the sybchronization of the master and backu CPUs, time difference may occur between the master and backup.

### 6.3 Remote Function

The operation mode of the CPU can be changed by communication, in addition to the key switch on the module. For remote operation, set the key switch of the CPU module to REM (remote) position>

#### 1) Types of remote operation

- (1) Operation by connecting to XG5000 via USB or RS-232C port installed on the CPU module
- (2) Operate by connecting XG5000 via the USB port on the expansion drive module
- (3) Other PLC networked on the PLC can be controlled with the CPU module connected to XG5000.
- (4) The PLC operation is controlled by HMI software and other applications through the dedicated communication.

#### 2) Remote RUN/STOP

- (1) Remote RUN/STOP is the function to execute RUN/STOP remotely with the dip switch of the CPU module set to REMOTE and the RUN/STOP switch set to STOP.
- (2) It is a very convenient function when the CPU module is located in a place hard to control or in case the CPU module is to run/stop from the outside.

#### 3) Remote DEBUG

- (1) Remote DEBUG is the function to control DEBUG with the dip switch of the CPU module set to REMOTE and RUN/STOP switch set to STOP.
- (2) It is a very convenient function when checking program execution status or data in the debugging operation of the system.

#### 4) Remote Reset

- (1) Remote reset is the function to reset the CPU module remotely in case an error occurs in a place not to directly control the CPU module.
- (2) Like the switch control, it supports 'Reset' and 'Overall Reset.'

#### Note

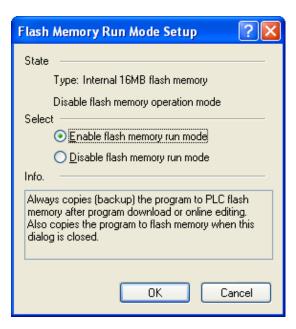
1) For the further information about remote functions, please refer to the 'Online' part in the user's manual of XG5000.

#### 5) Flash memory operation mode

(1) What is the flash operation mode? It means that the system operates by the backup program in flash in case the program in ram is damaged. If selecting "Flash Memory Operation Mode", it starts operation after program in flash moves to the program memory of the CPU module when the operation mode is changed from other mode to RUN mode or when restarting. (2) Flash Memory Operation Mode Setting

Check the operation mode setting by using 'Online → Set Flash Memory ... → 'Enable flash memory run mode' and click 'OK.'

Once pressing it, it shows a dialogue box stating "Saving flash memory program ..." and copies the program from user program area to flash.





# **∕**!∖ Caution

- 1) The default is 'Flash Memory Operation Mode deselected'.
- 2) Flash memory operation mode is maintained as 'On' as long as it is not 'Off by XG5000.
- 3) Flash memory operation mode can be changed, irrespective of RUN/STOP mode.
- 4) Flash memory operation mode can be set by the online menu of XG5000 when executing flash 'operation mode setting' after program debugging is complete with the flash memory operation mode off.
- 5) If modifying during RUN with 'flash memory operation mode' set, the changed program may be applied only when it restarts as long as the program is successfully written in flash memory. Note that if the PLC restarts before a program is saved into flash memory, a program that is saved in advance, instead of the changed program, works.
- 6) If flash memory operation mode is changed from 'disabled' to 'enable', flash memory operation mode is applied as long as the flash memory writing is complete. In case the PLC restarts before completing program writing, "Flash memory operation mode" is released.

# **Chapter 6. CPU Module Functions**

# (3) Flash memory operation method

If restarting the PLC system or changing its operation mode to RUN, it works as follows depending on the flash operation mode setting.

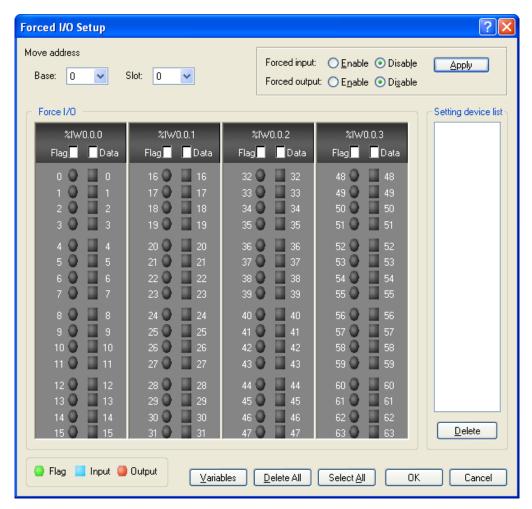
Flash memory operation mode setting	Description
On	If program memory data are damaged because flash memory and program memory are different or battery voltage is low, it downloads the program saved in flash memory to program memory.
Off	CPU understands that flash memory does not have any program and operates by the program saved in RAM.

# 6.4 Forced On/Off Function of I/O

The forcible I/O function is used to forcibly turn on or off I/O area, irrespective of program execution results.

### 6.4.1 Force I/O Setting

1) Click [Online]-[Force I/O] on XG5000.



- 2) To set forcible I/O, select the flag of a contact to set and the data checkbox
- 3) To set "1", select the flag and data of a bit and then, select a flag.
- 4) To set "0", select a flag only, not the data corresponding to the bit.
- 5) If selecting 'forcible input or output enabled', the setting is applied and it works accordingly.

For further directions, please refer to the user's manual of XG5000.



- 1) Forcible I/O setting is available only in local I/O module.
- 2) It can not be set in remote I/O module(smart I/O module).
- 3) If forcible I/O is set, "CHK LED" is On.
- 4) The forcible I/O set by a user is maintained even though a new program is downloaded.

# 6.4.2 The point of time of method of forced On/Off process

#### 1) Forcible input

'Input' replaces the data of a contact set by Forcible On/Off from the data read from input module at the time of input refresh with the forcibly set data and updates input image area. Therefore, a user program can execute operation with actual input data and forcibly set data.

#### 2) Forcible output

'Output' replaces the data of a contact set by Forcible On/Off from the output image area data containing operation result at the time of output refresh with the forcibly set data and outputs to an output module after completing user program operation. Unlike input, the data in output image area is not changed by forcible On/Off setting.



# **Caution**

#### Cautions for using forcible I/O

- It works from the time when input/output are set to 'enable/disable' respectively after setting forcible data.
- Forcible input can be set even though actual I/O module is not installed.
- The previously set On/Off setting data are kept in the CPU module, despite of power off → on, operation mode change, program download or manipulation by reset key. However, it is deleted if overall reset is executed.
- Forcible I/O data are not deleted even in STOP mode.
- To set new data from the first, release every setting of I/O by using 'overall reset'.

# 6.5 Operation history saving function

There are four types of operation logs; Error log, Mode change log, shut down log and System log. It saves the time, frequency and operation of each event into memory and a user can conveniently monitor them through XG5000. Operation log is saved within the PLC unless it is deleted by XG5000.

#### 6.5.1 Error history

It saves error log that occurs during operation.

- Saving error code, date, time and error details.
- Saving logs up to 2,048
- Automatically released if memory backup is failed due to low battery level and etc

#### 6.5.2 Mode change history

It saves the change mode information and time if an operation mode is changed.

- Saving the date, time and mode change information.
- Saving up to 1,024.

### 6.5.3 Shut down history

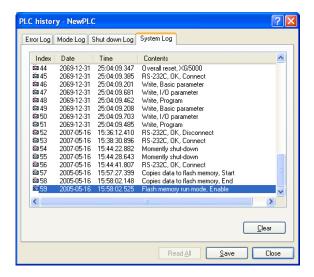
Saving power On/Off data with it's time data.

- Saving On/Off data, date and time.
- Saving up to 1,024.
- History of master and standby power is indicated respectively.

### 6.5.4 System history

It saves the operation log of system that occurs during operation.

- Saving the date, time and operation changes
- XG5000 operation data, key switch change information
- Instantaneous interruption data and network operation
- Saving up to 2,048



### Note

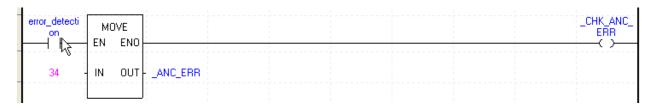
- 1) The saved data are not deleted before it is deleted by selecting a menu in XG5000.
- 2) If executing Read All in case logs are more than 100, the previous logs are displayed.

# 6.6 External device failure diagnosis function

It is the flag that a user detects a fault of external device so that the suspension/warning of a system could be easily realized. If using the flag, it can display a fault of external device, instead of creating a complex program and monitor a fault position without XG5000 and source program.

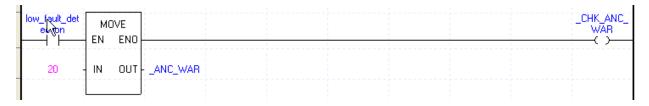
- 1) Detection/classification of external device fault
  - (1) The fault of external device is detected by a user program and it can be divided into heavy fault(error) that requires stopping the PLC operation and light fault(warning) that only displays fault status while it keeps operating.
  - (2) Heavy fault uses '\_ANC\_ERR' flag and light fault uses '\_ANC\_WB' flag.
- 2) If a heavy fault of external device is detected
  - (1) If a heavy fault of external device is detected in a user program, it writes the value according to error type defined in a system flag, '\_ANC\_ERR' by a user. Then, with \_CHK\_ANC\_ERR flag On, it checks at the completion of a scan program. At the moment, if a fault is displayed, it is displayed in '\_ANNUN\_ER' of '\_CNF\_ER', which is the representative error flag. Then, the PLC turns off every output module(depending on the output control setting of basic parameter) and it has the same error status with PLC fault detection. At the moment, P.S LED and CHK LED are On, besides ERR LED.
  - (2) In case of a fault, a user can check the cause by using XG5000 and alternatively, check it by monitoring '\_ANC\_ERR' flag.
  - (3) To turn off ERR LED, P.S LED and CHK LED, which are On by heavy fault error flag of external device, it is necessary to reset the PLC or turn it off and on again.

#### ■ Example



- 3) If a light fault of external device is detected
  - (1) If a light fault of external device is detected in a user program, it writes the value according to warning type defined in '\_ANC\_WAR' by a user. Then, with \_CHK\_ANC\_WAR On, it checks at the completion of a scan program. At the moment, if a warning is displayed, '\_ANNUN\_WAR' of '\_CNF\_WAR', which is the representative error flag of system is On. At the moment, P.S LED and CHK LED are On.
  - (2) If a warning occurs, a user can check the causes by using XG5000. Alternatively, a user can check the causes by directly monitoring '\_ANC\_WAR' flag.
  - (3) With \_CHK\_ANC\_WAR OFF, P.S LED and CHK LED are off and the display, '\_ANNUN\_WAR' of '\_CNF\_WAR' is reset.

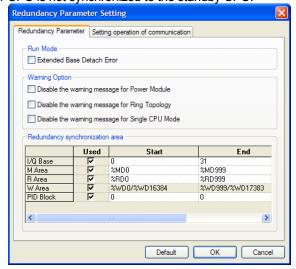
#### ■ Example



# 6.7 Redundancy system operation setting

For redundant system operation, redundancy parameters have to be set up.

Redundanct parameter configuration classified into the operation mode setting and data synchronization area setting. The default setting has no data synchronization area. Be careful that, if the data synchronization area is not set up, the data of the master CPU is not synchronized to the standby CPU.



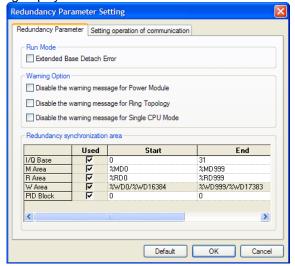
Different from other parameters, the dredundancy parameters can be written during running.

However, the redundancy parameters cannot be automatically dpwnloaded during running writing. From the XG5000 online writing, select the redundancy parameters only and download them.

#### 6.7.1 Operation mode setting

### 1) Single CPU operation mode

If the system is operation with master CPU only, without standby, redundancy system configuration warning occurs. To configure XGR system with a single CPU, select the 'Disable the warning message for Single CPU Mode' check box to prevent the warning display.



### **Chapter 6. CPU Module Functions**

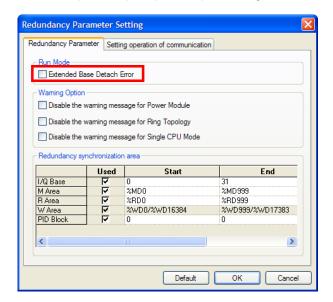


# **Caution**

It is recommended to configure the XGR system in redundant CPU system. If the redundant system is configured with single CPU, the system stops if the CPU module fails. To prevent system interruption, set up the system in redundant CPU configuration

### 2) Error handling in power cut-off of expansion base

In a redundant XGR system configured wuth multiple extensin bases for enhanced system reliability and diversity, in case of detach (powr off) of expansion base(s), the user can select whether to consider it as error or CPU restarts the system and watis until exension base in problem paricipate in operation again.



a) If the check box "Extended Base Detach Error" is not selected;

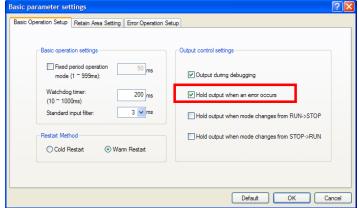
As the default setting, in case of a problem in an expansion base, the system is restarted and the CPU module waits until the base in failure is normalized. The base in failure is indicated with "Ebxx" in the CPU indicator panel.

When the failed base is restarted normally and returns to the system, the CPU module restarts in the same manner as the initial start-up and carry out normal operation.

b) If the check box "Extended Base Detach Error" is selected;

In case of failure of an expansion base, other modules operate in accordance with the error process setting in the basic parameter settings.

If the basic parameter was set to maintain output under error occurrence, other modules maintain the last output.



# 6.7.2 Data synchronization area setting

### 1) M area setting

Setting can be made by 1 kbyte step within 1 ~ 256 kByte range.

Initial value: %MW0~%MW2000 Change in Start End method

#### 2) I/Q: setting by base unit

Setting can be made in base unit.

Initial value is 31 bases (error message if the setting value is less than the number of installed bases)

# 3) PID: setting by block (max. 8 blocks)

For the synchronization area of the PID area, 32 PID areas are allocated for each block

- Initial value: 0 block

#### 4) R(W): set R only, and automatic setting for W

Synchronization area for R(W) area

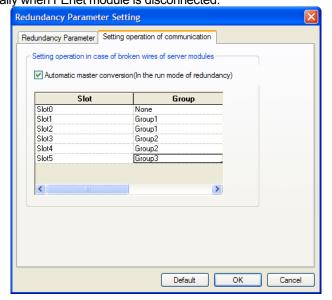
- Initial value: %RW0~%RW2000(%WW0~%WW2000, %WW32768~%WW34768)

# **Caution**

- 1) The M area retain can be set up in the "Basic Parameter Setting." For details, see "5.5.3 Data Retain Area Setting."
- 2) When the master/standby CPUs are performing redundant operation, followings are automatically synchronized.
  - (a) L (high speed link flag), N(P2P parameter setting) device area
  - (b) F (system flag area) device area (however, individual flag areas are not synchronized).
  - (c) U (special module refresh area) device area (however, only installed modules are synchronized).
- 3) If a variable value has been changed during monitoring by XG5000, it applies to the respective areas of the master and standby CPUs, regardless of the data synchronization area setting.

# 6.8 Setting operation of communication

Here you can set operation when FEnet module's cable is disconnected. According to setting, master CPU and Standby CPU are converted automatically when FEnet module is disconnected.



#### 6.8.1 Automatic master conversion

#### (1) Automatic master conversion setting

When cable of FEnet module, which is set as server, is disconnected, check the Automatic master conversion for automatic master conversion. This setting is applied in case of when redundancy operation

#### (2) Detail option

Here sets the condition for automatic master conversion through detail option. This means setting the group for each FEnet module installed at main base. Each module can be set as same group or not. When automatic master conversion setting and detail option setting is done, if the following two conditions are met, master conversion occurs.

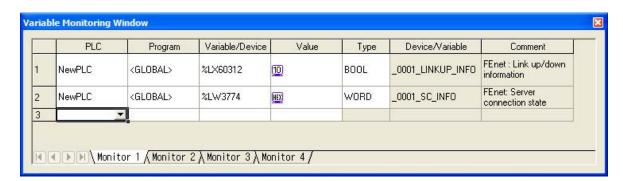
- (a) All master base FEnet module belonging to one group are disconnected and
- (b) At least one standby base FEnet module belonging to the above group is under normal connection status

For example, In case you set slot 1 and slot 2 as group 1, slot 3 and slo4 as group 2 and slot 5 as group3, master conversion occurs under the following three conditions. (We assumes that FEnet modules on standby base are normal connection status)

- (a) Slot 1 and slot 2 are disconnected or
- (b) Slot3 and slot4 are disconnected or
- (c) Slot 5 is disconnected

#### 6.8.2 Global status variable

After installing FEnet module, you can check the server connection status of FEnet module and physical cable connection status through Global variable at XG5000. In order to monitor global variable, register relevant variable at Variable Monitoring Window after executing [Edit]-[Register Special/Communication Module Variable] in XG5000. And these variables can be used at user program



#### (1) Sever connection status variable

Sever connection status variable indicates connection status of each client connected to server. Each bit indicates each client status in order of connection to server and if bit is on, it is normal connection status. Each bit indicates status of each client in the order as connected and if it's ON, its normal connection.

### (2) Link up/down information variable

Link up/down information variable indicates physical cable connection status of relevant FEnet module. If variable is on, it means normal connection and if variable is off, it means disconnection or detachment

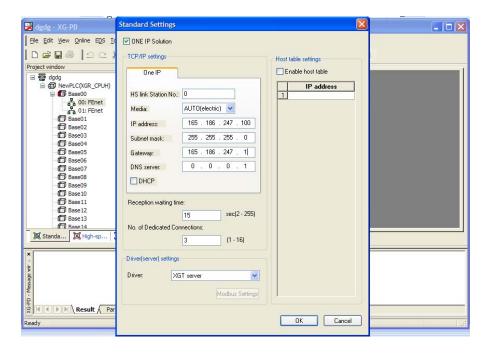
### 6.8.3 ONE IP Solution

You can connect to the master base FEnet module of XGR redundancy system with one IP regardless of master conversion through One IP Solution. For this, in case of master conversion, master base FEnet module and standby FEnet module change each other's IP address

### (1) IP setting

You set IP of FEnet module at standard setting window after registering FEnet module at XG-PD. If you check ONE IP Solution of standard setting window, ONE IP Solution function will be activated. Unlike when ONE IP Solution is not used, you can set only one IP address (For how to set IP address when ONE IP Solution is not activated, refer to FEnet user manual). When using ONE IP Solution, IP address should be even number. That IP address becomes IP address of master base FEnet module and master base FEnet module's IP address + 1 becomes IP address of standby base FEnet module

# **Chapter 6. CPU Module Functions**



#### (2) IP change

If you use ONE IP Solution, in case of master conversion caused by error, communication disconnection, master base and standby FEnet modules change each other's IP address. For this, after master conversion, individual module reset is conducted.

# **Caution**

(1) Individual module reset should be complete after master conversion so let no master conversion occurs again within 3 second (time for completing individual module reset) after master conversion.

# 6.9 Fault Mask Function

### 6.9.1 Applications and operations

- Fault mask helps a program keep operating even though a module is in trouble during operation. A module designated as fault mask normally works until a fault occurs.
- If an error occurs on a module on which fault mask is set, the module stops working but the entire system keeps working.
- If a fault occurs in a module during operation, the CPU module sets the error flag and "PS LED" on the front is "On."
   The error is displayed when accessing to XG5000.

### 6.9.2 Fault mask setting

- Fault mask can be set by the online menu of XG5000. For the details, please refer to the user's manual of XG5000.
- Fault mask can be also set by a program. It is achieved by setting fault mask flag with a program(please refer to Appendix 1 Flags list)

# 6.9.3 Releasing fault mask

Fault mask is released only by the following methods.

- Releasing the setting in the online menu of XG5000
- Releasing by overall reset
- Automatically releasing in case memory backup is failed due to low battery level and other causes

Note that the fault mask is not released even in the following cases.

- Power Off→On
- Operation mode change
- Program download
- Reset key(released only when it is pressed for 3 seconds and longer)
- Data clear



- 1) If releasing fault mask with error flag in the CPU module not cleared although the causes of an error are eliminated, the system stops. Please check the state of error flag before releasing fault mask flag.
- 2) To remove an error flag, release it after setting I/O skip in the respective module. For details, see [XG5000 online help desk >>I/O Skip.

# 6.10 I/O Module Skip Function

# 6.10.1 Applications and operations

During operation, the I/O module skip function excludes a designated module from the operation. For the designated module, the data update and fault diagnostics of I/O data stops as soon as being designated. It is available when temporarily operating it with the fault excluded.

#### 6.10.2 Setting and processing I/O data

- It can be set at the unit of I/O module.
   (For further information about setting, please refer to the user's manual of XG5000)
- Input(I) image area suspends input refresh, so it maintains the value set before skip setting. However, even in the case, the image manipulation by forcible On/Off is still effective.
- The actual output of output module is Off when setting the skip function but it changes depending on a user program's
  operation, irrespective of skip setting. After the skip setting, the output value of output module can not be controlled by
  forcible On/Off.
- The skip function is identically executed even when using I/O function.

#### 6.10.3 Releasing skip function

The I/O module skip function is released only by the method of setting.

- Releasing by the online menu of XG5000
- Releasing by overall reset
- Automatically releasing in case memory backup is failed due to low battery level and other causes

Note that the fault mask is not released even in the following cases.

- Power Off→On
- Operation mode change
- Program download
- Reset key(released only when it is pressed for 3 seconds and longer)
- Data clear



1) If any fault is found in a module when releasing the skip function, the system may stop. Before releasing the skip function, make sure to release the skip with fault mask set and check the operation of a module.

# 6.11 Base Skip Function

# 1) Purpose and outline of the operation

Base skip is the function to exclude the designated base from operation during an operation. The excluded base stops all functions from the skip. This function is useful to continue operation by excluding a failed base or replace the base.

# 2) Setting method

• This setting can be done for each base.

### 3) Releasing skip function

Base skip can be released by following methods only.

- Selecting XG5000's [Online >> I/O Skip Setting] menu
- Release by Overall Reset
- Automatic release at backup memory lost by battery voltage drop, etc.

Note that followings do not release the failure mask;

- power Off → On,
- operation mode change,
- · program download,
- reset key operation (however, released if pressed for 3 seconds or longer), and
- data clear



# **Caution**

- (1) When expansion driver is detached, all modules in base are automatically initialized.
- (2) When expansion driver is detached, digital output module operates as set in Output control settings of Basic parameter.
- (3) When expansion driver is detached, analog output module operates as set in Output type setting
- (4) For more detail, refer to each module's user manual.

# 6.12 Module Replacement Function during Operation

A module can be replaced during operation in the redundant system. However, a special attention should be paid because the module replacement during operation may cause malfunction. Make sure to follow the steps directed in the user's manual.

# 🔼 Warning

- (1) The special modules which can be normally replaced are A/D, D/A, TC, and RTD. HSC and APM modules can be replaced but the previous data cannot be maintained.
- (2) Some communication modules(XGL-PMEA, XGL-DMEA) can be connected as long as network is set(using Sycon software).
- (3) When replacing a module, align the bottom of the base and the holding part of a module before inserting it. A wrong insertion may cause 'system down.'

### 1) Module replacement in redundant system

CPU module, power module, I/O module, a certain special modules, and the base module can be replaced during redundant operation. For safety purpose, this Manual provides the methods using the Module Replacement Wizard and Base Replacement Wizard only.

### 2) Replacing I/O module in redundant system

To replace a module in the base in redundant operation, change the main base to backup operation status and cut-off the power. If the Module Replacement Wizard is used, the I/O and internal data of the module is lost.

To replace a module, users can use XG5000's [Online >> Module Replacement Wizard] function. For details, see XG5000 User Manual [Online >> Module Replacement Wizard].

# ∕!∖ Caution

Replacement of the main base (base 0) using the XG5000's [Online >> Module Replacement Wizard] function is available only during single CPU operation.

#### 3) Replacing base module in redundant system

Bases can be replaced in redundant operation. For a line-configured system, the last base only can be replaced. For a ring-configured system, all the bases of the 1-31 bases which are participating in the operation can be replaced.

For safety purpose, this Manual provides XG5000's [Online >> Base Replacement Wizard] function only. For further details, see XG5000 User Manual [Online >> Base Module Replacement Wizard].

# 

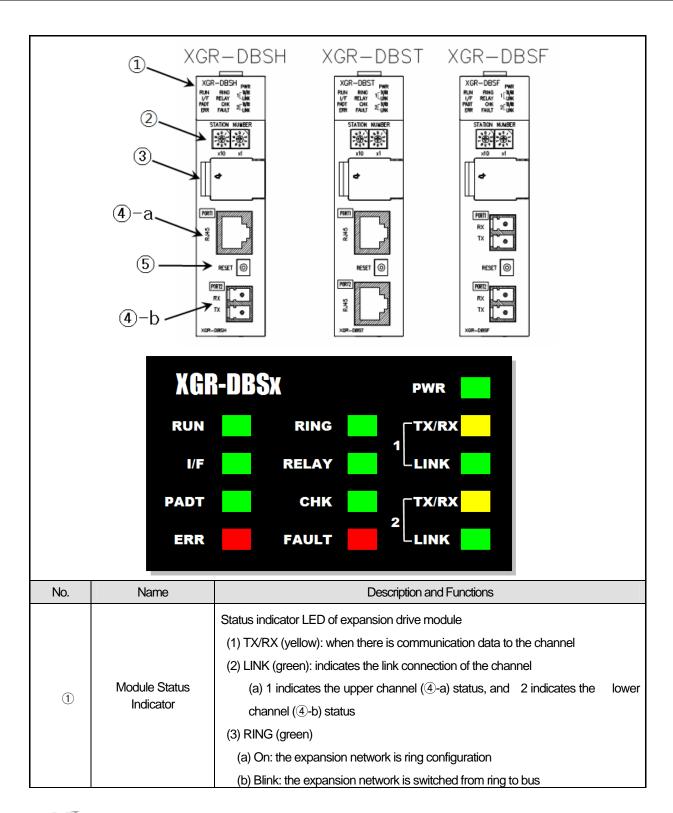
- (1) In this process, only one base can be replaced at a time for safety reason.
- (2) The main base cannot be replaced during operation.

# **Chapter 7. Expansion Drive Module**

# 7.1 Performance specifications

Itomo		Spec	cification	
	Items	100BASE-FX	100BASE-TX	
Transmission Method		Base band		
<b>.</b>	Max. Expansion distance between nodes	2km	100m	
Transmission Specification	Max. Number of nodes		31	
ansm	Max. Protocol size	1,	,516 byte	
발 ઝ	Communication access method	С	SMA/CD	
	Frame error check method	CRC $32 = X^{32} + \lambda$	$\chi^{26} + \chi^{23} + \dots + \chi^2 + \chi + 1$	
	Cable	Multi Mode Fiber	FTP/STP/SFTP	
Lo	Transmission speed	100Mbps		
Communication Media	Flow control	Full Duplex		
Comr	Communication port	2 port		
	Auto Crossover	Cross / Direct Cable is supported (Recommend : Cross cable)		
Network	Topology	Ring, Line		
Conversion Time	Ring → Line(Bus)	10ms		
Conv	Line(Bus) → Ring	500ms		
ion	Dimensions(mm)	98(H) X 27(W) X 90(D)		
Basic Specification	Current consumption (mA)	DBSF: 850 / DBSH: 660 / DBST: 490		
တိ	Weight (g)	DBSF: 102/DBSH: 101/DBST: 99		

# 7.2 Identification and Function



<b>⑤</b>	Expansion Drive Module Reset Switch	(1) Used to reset module only.  (2) Make sure to skip the module before conducting module reset  (3) Take care that resetting without skip setting of the respective base will cause module isolation error.
4	Expansion Network Connector	device  (2) Optical-optical, electrical-electrical, and optical-electrical models are provided to enable network construction using mixed electrical/optical  Pressing this switch will trigger module reset operation.
		Connector for expansion base connection. (1) 2 connectors are provided for ring connection without additional switching
3	USB Connector	Connector for peripheral devices (XG5000 etc.) (USB 1.1 supported)
2	Base Setting Switch	<ul> <li>(1) x10 for 10 digit setting, x1 for 1 digit setting</li> <li>(2) Max. 31 bases can be set up</li> <li>(3) Error LED on at station No. conflict or setting more than 31 station numbers</li> </ul>
		Switch for setting expansion base No.
		(9) PADT On (green): on in PADT connection (10) ERR On (red): CPU operation mode is ERR
		(b) Off: I/F with expansion manager unavailable
		(a) Blink: in normal I/F with expansion manager
		(8) I/F (green)
		(c) Off: CPU operation mode is STOP
		(a) On: CPO operation mode is RON  (b) Blink: expansion drive is in wait state for CPU recognition
		(a) On: CPU operation mode is RUN
		(b) Blink: frame error occurred (7) RUN (green)
		(a) On: network station No. conflict (self station No.)
		(6) FAULT (red)
		(b) Blink: station No. in the expansion network conflict (other station numbers)
		(a) On: indicates CPU's WAR LED
		(5) CHK (green)
		conduct as a data relay
		(b) Off: the module neighboring the two channels are connected and does not
		as a data relay
		(a) On: the module neighboring the two channels are connected and conducts
		(4) RELAY (green)
		first
		(c) Off: the expansion network connection is off, or in bus configuration from the

# **Chapter 8 Power Module**

This chapter describes the selection, type and specifications of power module.

# 8.1 Type and Specification

We provide diverse types according to input voltage and output capacity. Select right module according to environment and system. Table 8.1.11 Power module specification

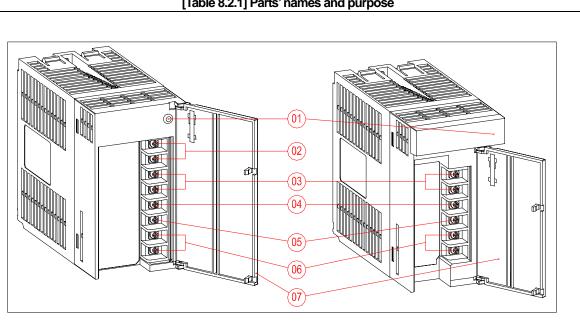
[Table 6.1.1] Power module specification							
ltem		XGR-AC12	XGR-AC22	XGR-AC13	XGR- AC23	XGR-DC42	
Input	Rated input voltage	110 VAC	220 VAC	I10 VAC	220 VAC	24 VDC	
	Input voltage range	85V~132VAC	176V~264VAC	85V~132VAC	176V~264VAC	19.2~28.8 VDC	
	Input frequency	50/60 Hz (47~63 Hz)			-		
	Max. input power	110 VA / 42 W		176 VA / 72 W		-	
	Inrush current	20A peak and lower (within8 ™s )			80A peak and lower		
	Efficiency	65% or higher					
	Input fuse	Built in(not replaceable by					
	Allowed instantaneous interruption	Within 20 ms					
	Output voltage	5VDC (±2%)					
Output	Output current	5.5A		8.5A		7.5A	
	Output power	27.5W @ 55℃		46.75W @ 55℃		37.5W @ 55°C	
	Over current protection	6.0 A~13.0 A		9.3 A~17.0 A		9.0 A~17.0 A	
	Purpose	RUN contact (refer to 8.2)					
Relay	Rated switching voltage/current	24VDC, 0.5A					
Output	Min. switching load	5VDC, 1 mA					
	Response time	Off→On/ On→Off: 10 ms and lower/12 ms and lower					
	Life	Mechanical life: 20 million and more times, electrical life: rated switching current: 100 thousand and more times					
Voltage status	display	LED On when output voltage is normal					
Specification of	cable	0.75~2 mm <sup>2</sup>					
Available clamped terminal		RAV1.25-3.5, RAV2-3.5					
Dimension (WxHxDmm)		55 x 95 x 90 55 x 95 x 110					
Weight		326g	382g	334g	384g	417g	
Applied base and install position		Power part of basic/expar	nsion base	Power part of expansion b	oase	Power part of basic/expansion base	

# Note

- (1) Allowable instantaneous interruption time
  - (a) The time that the normal output voltage is maintained(normal operation) with the input voltage of 110/220VAC lower than the rated value(85/170VAC)
- (2) Over current protection
  - (a) If a current over the rated level is allowed on 5VDC circuit, an over current protective system cuts off the circuit, suspending the
  - (b) If there is any overcurrent, the system should be restarted after eliminating the causes such as low current capacity, short-circuit and etc.

#### Parts' Names 8.2

It describes the names and applications of parts of the power module.



[Table 8.2.1] Parts' names and purpose

No.	Name	Purpose		
1	Power LED	5VDC Power display LED		
2	NC	Not used		
3	RUN Terminal	Displaying RUN state of a system (1) On when CPU is normal RUN mode. (2) Off when the stop error of CPU occurs. (3) It is Off when the mode of CPU turns to STOP.		
4	FG Terminal	Functional Grounding terminal for reliability of system operation.		
5	LG Terminal	Grounding terminal of power filter		
6	Power input Terminal	Power input terminal (1) XGR-AC12, XGP-AC13: 110VAC connection (2) XGR-AC22, XGP-AC23: 220VAC connection (3) XGR-DC42 : DC 24V connection		
7	Terminal cover	Terminal unit protection cover		

# 8.3 Selection

The selection of power module is determined by the current that input power voltage and power module should supply to the system, that is, the sum of current consumption of digital I/O module, special module and communication module that are installed on a same base with the power module.

If it exceeds the rated output capacity of power module, the system does not properly work. Select a power module by considering the power current of each module when structuring a system.

ITable 8.3.11 Current consumption by modules

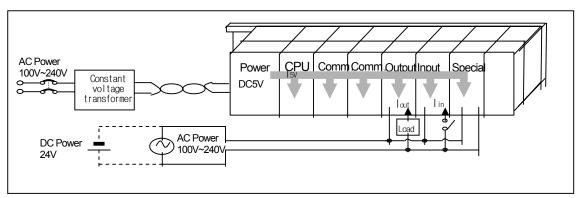
	[Table 8	Consumption current (Unit: mA)	Item	Name	Consumption current (Unit: mA)
Item	Name				
	XGR-CPUH/T	980		XGF-AV8A	420
CPU module	XGR-CPUH/T	980	Analog input module	XGF-AC8A	420
	XGR-CPUH/F	1,310		XGF-AD4S	610
Ei dá	XGR-DBST	550		XGF-AD8A	420
Expansion drive	XGR-DBSF	550		XGF-AD16A	330
module	XGR-DBSH	550		XGF-DV4A	190 (250)
	XGI-D21A	20	Analog output module	XGF-DC4A	190 (400)
	XGI-D22A	30		XGF-DC4S	200 (220)
D040/04) / i 4	XGI-D22B	30		XGF-DV8A	147 (180)
DC12/24V input	XGI-D24A	50		XGF-DC8A	243 (300)
module	XGI-D24B	50		XGF-DV4S	200 (150)
	XGI-D28A	60	High speed counter	XGF-HO2A	270
	XGI-D28B	60	module	XGF-HD2A	330
AC110V input module	XGI-A12A	30		XGF-PO3A	400
AC220V input module	XGI-A21A	20		XGF-PO2A	360
	XGQ-RY1A	250	Positioning module	XGF-PO1A	340
Relay output module	XGQ-RY2A	500		XGF-PD3A	860
	XGQ-RY2B	500		XGF-PD2A	790
	XGQ-TR2A	70		XGF-PD1A	510
	XGQ-TR2B	70		XGF-PO4H	430
Transistor output	XGQ-TR4A	130		XGF-PO3H	420
module	XGQ-TR4B	130		XGF-PO2H	410
	XGQ-TR8A	230		XGF-PO1H	400
	XGQ-TR8B	230		XGF-PD4H	890
Triac output module	XGQ-SS2A	300		XGF-PD3H	850
mac output module				XGF-PD2H	600
I/O module	XGH-DT4A	110		XGF-PD1H	520
I/O module			RTD input module	XGF-RD4A	450
	XGL-EFMF	640		XGF-RD4S	783
FEnet I/F module (Optical/Electricity)	XGL-EFMT	410	Thermocouple input module	XGF-TC4S	610
	XGL-ESHF	1,200	Event input module	XGF-SOEA	700
PAPIEnet I/F Module	XGL-EIMF	490	Motion control module	XGF-M16M	640
FAFIEHELI/FIVIOUUIE	XGL-EIMT	335	Analog I/O module	XGF-AH6A	770
	XGL-EIMH	400	/ siding i/O Hoddie	/\GI -/\IU/\	110

Item	Name	Consumption current (Unit: mA)	ltem	Name	Consumption current (Unit: mA)
Ethernet/IP I/F module	XGL-EIPT	400	Dnet I/F module	XGL-DMEA	440
	XGL-C22A	330	FDEnet I/F module	XGL-EDMF	410
Cnet I/F module	XGL-C42A	300	FDENEUF Module	XGL-EDMT	410
	XGL-CH2A	340	Pnet I/F module	XGL-PMEA	560
Rnet I/F module	XGL-RMEA	410	-	-	-

<sup>()</sup> means the current consumption for external DC24V.

### 8.4 Example of Current Consumption/Power Calculations

It describes which power module should be used for the XGR system with the following module.



[Figure 8.4.1] Example of use of power module

#### 8.4.1 In case of basic base

Though you equip all modules that consume maximum current, it is not higher than 5.5A. So consider input voltage and select XGR-AC12 or XGT-AC22

[Table 8.4.1] Consumption current/power calculation of basic base

Туре	Name	No. of equipment	Consumption current (5V)
CPU module	XGR-CPUH/F	1	1.31A
Basic base	XGR-M06RP	1	0.2A
FEnet module	FEnet module XGL-EFMF 6		0.61A
Consumption current (Total) / Power (Total)			1.31A + 0.61A*6 = 4.97A / 4.97×5V = 24.85W

### 8.4.2 In case of expansion base

Calculate the consumption current of module equipped at expansion base and select 5.5A or 8.5A Table 8.4.21 Consumption current/power calculation of basic base

[lable 6.4.2] Consumption current/power calculation of basic base									
Туре	Name	No. of equipment	Consumption current (5V)						
Expansion drive module	XGR-DB <b>S</b> F	1	0.65A						
Expansion base	XG <b>B</b> - E12RP	1	0.21A						
Input module	XGI-D24A	2	0.05A						
Output module	XGQ-RY2A	6	0.5A						
A/D conversion module	XGF-AD4S	2	0.61A						
Profibus-DP	XGL-PMEA	2	0.56A						
Consumption current (Total) / Power (Total)			0.65A + 0.21A+0.05A*2 + 0.5A*6 + 0.61A*2 + 0.56A*2 = 6.30A /6.30A × 5V = 31.50 W						

Since total of consumption current (5V) is 6.17A, use one among XGR-AC13, XGP-AC23 according to input voltage. If power module is less than a necessary capacity, reliability of system is not guaranteed.

#### Note

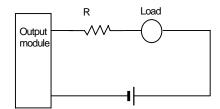
If efficiency of power module is applied to power (5V), the user can estimates the maximum input power of PLC system. Ex) Total of consumption power (5V) / Power module efficiency (Min.) = 100 W / 0.65 % = 154 W

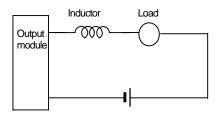
## Chapter 9. I/O Module

### 9.1 Cautions for Selecting Module

It describes the cautions when selecting digital I/O modules used for the XGI series.

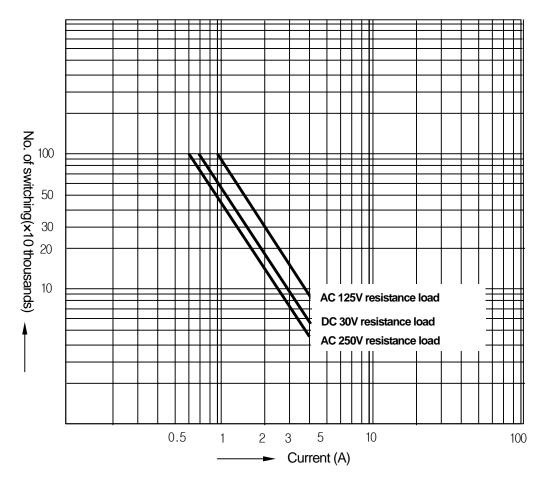
- 1) There are two digital input types; current sink input and current source input Since the wiring method of external input power varies in a DC input module, it should be selected considering the specifications of input connectors.
- 2) The max. simultaneous input point varies depending on a module type. That is, it may be different, depending on input voltage and ambient temperature. Please review the specifications of input module to apply before use.
- 3) In case of an application for highly frequent switching or inductive load switching, the relay output module may have a shorter life, so it needs a transistor module or triac output module, instead of it.
- 4) If an output module operates an inductive load(L), the max. On/Off frequency should be limited to On per 1 second and Off per 1 second, each.
- 5) In case a counter timer using DC/DC converter is used as a load in an output module, setting the average current may cause a trouble because it may have inrush current in case of On or a certain cycle during operation. Therefore, if using the foresaid load, it is necessary to connect resistance or inductor parallel to load or alternatively use a module of which max. load current is large.





6) A fuse in an output module can not be replaced. That's why it is intended to prevent external wiring from being damaged when the output of a module is short-circuited. Therefore, the output module may not be protected. If an output module is destructed in any other fault mode save for short-circuit, a fuse may not work.

7) The following figure shows the relay life of relay output module. It also shows the max. life of relay used for relay output.



8) A clamped terminal with sleeve can not be used for the XGI terminal strip. The clamped terminals suitable for terminal strip are as follows(JOR 1.25-3:Daedong Electricity).



- 9) The cable size connected to a terminal strip should be 0.3~0.75 m² stranded cable and 2.8 mm thick. The cable may have different current allowance depending on the insulation thickness.
- 10) The coupling torque available for fixation screw and terminal strip screw should follow the table below.

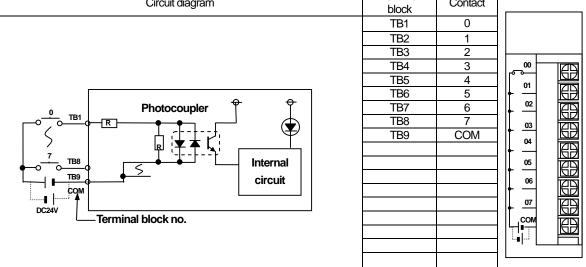
Coupling position	Coupling torque range
IO module terminal strip screw(M3 screw)	42 ~ 58 N·cm
IO module terminal strip fixation screw(M3 screw)	66 ~ 89 N⋅cm

11) Transistor output module(XGQ-TR4A, XGQ-TR8A) supports terminal protector function. Thermal Protector is the function to prevent overload and overheat.

# 9.2 Digital Input Module Specifications

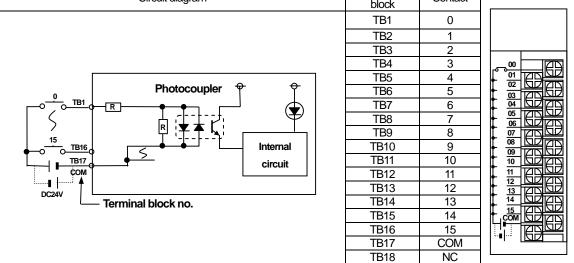
### 9.2.1 8 point DC24V input module (source/sink type)

	Module type	D	C Input module				
Spec.			XGI-D21A				
Input point		8 points					
Insulation method		Photo coupler insulation					
Rated input voltage		DC24V					
Rated input current		Approx. 4 mA					
Voltage range		DC20.4~28.8V (5% and lower ripp	le rate )				
Input derating		None					
On voltage / On curre	ent	DC19V and higher / 3 mA and high	ner				
Off voltage / Off curre	ent	ver					
Input resistance		Approx. 5.6 kΩ					
Response time	Off → On	1ms/3ms/5ms/10ms/20ms/70ms/100ms (Set by CPU Parameter) Initial value:3ms					
response ume	$On \rightarrow Off$	1ms/3ms/5ms/10ms/20ms/70ms/100ms (Set by CPU Parameter) Initial value:3ms					
Withstand voltage		AC560V rms/3 Cycle (altitude 2000m)					
Insulation resistance		10 <sup>MΩ</sup> and higher by Insulation ohmmeter					
Common method		16 point/ COM					
Suitable cable size		Stranded cable between 0.3~0.75	mm² (2.8mm and smaller outer dia.)				
Suitable clamped ten	minal	R1.25-3 (Sleeve built-in clamped terminal is not available)					
Current consumption	(mA)	20mA					
Operation display		LED On with Input On	LED On with Input On				
External connection i	method	9 point Terminal strip connector (M	3 X 6 screws)				
Weight		0.1 kg					
	Circuit di	agram	Terminal Contact				



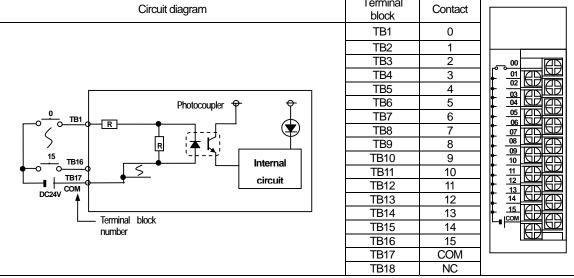
## 9.2.2 16 point DC24V input module (source/sink type)

Module type DC Input module Spec. XGI-D22A							
Input point		16 points	AOI-DZZA				
Insulation metho	d	Photo coupler insulation					
Rated input volta	-	DC24V					
Rated input curre	<u> </u>	Approx. 4 mA					
Voltage range		DC20.4~28.8V (5% and lower rip	ole rate )				
Input derating		None	pio rato j				
On voltage / On o	current	DC 19V and higher / 3mA and high	her				
Off voltage / Off of		DC 11V and lower / 1.7mA and lo					
Input resistance	Janon K	Approx. 5.6 k $\Omega$	wo.				
	Off → On	1mc/3mc/5mc/10mc/20mc/70mc/100mc /Sat by CPLL Parameter)					
Response time  On → Off  On → Off							
Insulation withsta	ind voltage	AC560V rms/3 Cycle (altitude 200	00m)				
Insulation resista	nce	10 MΩ and higher by Insulation oh	mmeter				
Common metho	d	16 point/ COM					
Suitable cable siz	ze	Stranded cable between 0.3~0.75	5 mm² (2.8mm and s	smaller outer	dia.)		
Suitable clamped	terminal	R1.25-3 (Sleeve built-in clamped	erminal is not ava	nilable)			
Current consump	otion(mA)	30mA					
Operation display	/	LED On with Input On					
External connect	ion method	18 point Terminal strip connector	(M3 X 6 screws)				
Weight		0.12 kg					
	Circuit	diagram	Terminal block	Contact			
			TB1	0	]		
			TB2	1	4		
			TB3 TB4	3	00     Z		
			TB5	4	01 10 10		
_	Pho	otocoupler 🕈 🔫	TB6	5			
<del>0</del>	→ R →		TB7	6			
	1 — Y	<u>社士</u> -> <b>学</b>	TB8	7	05 100		
	R	'▼ <b>주</b>	TRO	Ω			



### 9.2.3 16 point DC24V input module (source type)

	Module type		DC Input module				
Spec.		XGI-D22B					
Input point		16 points					
Insulation metho	d	Photo coupler insulation					
Rated input volta	ige	DC24V					
Rated input curre	ent	Approx. 4 mA					
Voltage range		DC20.4~28.8V (5% and lower rip	ple rate )				
Input derating		None					
On voltage / On	current	DC 19V and higher / 3mA and high	gher				
Off voltage / Off of	ff current DC 11V and lower / 1.7mA and lower						
Input resistance		Approx. $5.6 \mathrm{k}\Omega$					
Deep ence time	Off → On	1ms/3ms/5ms/10ms/20ms/70ms/100ms (Set by CPU Parameter) Initial value:3ms					
Response time	$On \rightarrow Off$	1ms/3ms/5ms/10ms/20ms/70ms Initial value:3ms	/100ms (Set by CPU Parameter)				
Insulation withsta	and voltage	AC560V rms/3 Cycle (altitude 2000m)					
Insulation resista	nce	10 MΩ and higher by Insulation oh	mmeter				
Common metho	d	16 point/ COM					
Suitable cable siz	ze	Stranded cable between 0.3~0.75 m² (2.8mm and smaller outer dia.)					
Suitable clamped	d terminal	R1.25-3 (Sleeve built-in clamped terminal is not available)					
Current consump	otion(mA)	30mA					
Operation display	у	LED On with Input On					
External connect	tion method	18point Terminal strip connector (	int Terminal strip connector (M3 X 6 screws)				
Weight		0.12 kg					
	Oineit	Paramana	Terminal Contact				



## 9.2.4 32 point DC24V input module (source/sink type)

	Module type	DC Input module								
Spec.	"			ĠI-D24/						
Input point		32 points								
Insulation method	d	Photo coupler insulation								
Rated input volta	ge	DC24V								
Rated input curre	ent	Approx. 4 mA								
Voltage range		DC20.4~28.8V (5% and low	er ripple r	ate)						
Input derating		Refer to the below derating le	evel							
On voltage / On o	current	DC 19V and higher / 3mA ar	nd higher							
Off voltage / Off of	current	DC 11V and lower / 1.7mA a	nd lower							
Input resistance		Approx. 5.6 kΩ								
Response time	Off → On	1ms/3ms/5ms/10ms/20ms/7 Initial value:3ms		,	•		•			
responde une	$On \to Off$	1ms/3ms/5ms/10ms/20ms/7 Initial value:3ms			y CPU P	arameter	·)			
Insulation withsta	ind voltage	AC560V rms/3 Cycle (altitud	e 2000m)							
Insulation resista	nce	$10{\rm M}\!\!^{\rm Q}$ and higher by Insulation ohmmeter								
Common method	d	32points / COM								
Suitable cable siz	ze	0.3 mm²								
Current consump	otion( <sup>mA</sup> )	50mA								
Operation display	/	LED On with Input On								
External connect	ion method	40point connector								
Weight		0.1 kg								
	Circuit diag	ram	No	Contact	No	Contact				
			B20	0	A20	16			1	
0 1	Photoco	upler 🕈 🕈	B19	1	A19	17	B20	0 0	A20	
B20 1	R	¬┌┤	B18	2	A18	18	B19	0 0	A19	
	Ŕ ¦ <b>±</b>	. <b>★</b> ぱ	B17	3	A17	19	B18 B17	0 0	A18 A17	
31 A05	- <del>       </del>		B16	4	A16	20	B16	0 0	A16	
B02		' Internal	B15	5	A15	21	B15	0 0	A15	
Т сом		circuit	B14	6	A14	22	B14		A14	
DC24V /	Connector number		B13	7	A13	23	B13	0 0	A13	
100 🗆	<del></del>	B12	8	A12	24	B12 B11	0 0	A12 A11		
90	<del>                                     </del>	B11	9	A11	25	B10	0 0	A10		
		DC28.8V	B10	10	A10	26	B09	0 0	A09	
On rate(%) <sup>80</sup> 70		1 1 1 1 DO20.8V	B09	11	A09	27	B08	0 0	A08	
70		<del>                                     </del>	B08	12	A08	28	B07	0 0	A07	
60		<del>                                     </del>	B07	13	A07	29	B06 B05	0 0	A06 A05	
50		<del></del>	B06	14	A06	30	B04	0 0	A04	
40			B05 B04	15 NC	A05	31 NC	B03	0 0	A03	
0	10 20 30	40 50 55 °C	B04 B03	NC NC	A04 A03	NC NC	B02	0 0	A02	
Derating leve	Ambient :	temp.	B03	COM	A03 A02	COM	B01		A01	
Doraung leve	•		B01	COM	A01	COM				
			501		7.01					

### 9.2.5 32 point DC24V input module (source type)

Input point   32 points   32 points   15 points   1		Module type		DC I	nput mod	lule					
Photo coupler insulation   Photo coupler insulation   Rated input voltage   DC24V	Spec.										
Rated input voltage	Input point		32 points								
Rated input current	Insulation method	d	Photo coupler insulation								
Voltage range	Rated input volta	ge									
Production   Refer to the below derating level	Rated input curre	ent .	Approx. 4 mA								
On voltage / On current         DC19V and higher / 3 mA and higher           Off voltage / Off current         DC 11V and lower / 1.7mA and lower           Input resistance         Approx. 5.6 kΩ           Response time         Off → On Initial value 2.3ms         Imms/3ms/5ms/10ms/20ms/70ms/100ms (Set by CPU Parameter) Initial value.3ms           Insulation withstand voltage         AC560V rms/3 Cycle (allitude 2000m)           Insulation resistance         10 MS and higher by Insulation chmmeter           Common method         32 points / COM           Suitable cable size         0.3 mrl           Current consumption(m²)         50mA           Operation display         LED On with Input On           External connection method         40point connector           Weight         0.1 kg           Circuit diagram         No         Contact         No         Contact           B319         1 A19         17         B18         B2         A18         B8           B17         3 A17         19         B18         B19         1 A19         B19	Voltage range		DC20.4~28.8V (5% and low	er ripple r	ate)						
Off voltage / Off current	Input derating		Refer to the below derating I	evel							
Approx. 5.6 kΩ   1ms/3ms/5ms/10ms/20ms/70ms/100ms (Set by CPU Parameter)   1mital value:3ms   1mital	On voltage / On o	current	DC19V and higher / 3 mA and higher								
Response time	Off voltage / Off of	current	DC 11V and lower / 1.7mA a	and lower							
Initial value:3ms	Input resistance		1								
Initial value:3ms	Posnonso timo	$Off \rightarrow On$	Initial value:3ms		,		•				
Insulation resistance	Nesponse une	$On {\to} Off$		70ms/100	ms (Set by	y CPU P	arameter)				
Suitable cable size   0.3 mri	Insulation withsta	ind voltage	AC560V rms/3 Cycle (altitud	le 2000m)	)						
Suitable cable size	Insulation resista	nce	10 MΩ and higher by Insulation	on ohmm	eter						
Current consumption(mA)   S0mA	Common method	b	32 points / COM								
Derating level   LED On with Input On	Suitable cable siz	ze	0.3 m²								
No   Contact   No	Current consump	otion( <sup>mA</sup> )	50mA								
No   Contact   No   No   No   No   No   No   No   N	Operation display	/	LED On with Input On								
No   Contact   No	External connect	ion method	40point connector								
B20	Weight		0.1 kg								
B19		Circuit diag	ram	No	Contact	No	Contact				
B18   2   A18   18   B19   0   0   A19   A11   A15	_			B20	0	A20	16				
B18   2   A18   18   B19   A18   A17   A17   A17   A18   A18   B19   A18   B19   A18   A18   B19   A19   A	0 500	Photoco	upler 🕈 👇	B19	1	A19	17	B20	1	A20	
B17   3   A17   19   B16   A17   A17   A18   B17   B16   A18   A16   A17   A18   A		R	¬	B18			18		1	-	
Side   Aid   Connector number   Bide   Connector number   Connector number   Connector number   DC28.8V   DC24V   COM   Connector number   Connector number   DC28.8V   DC28.8	>	Ŕ	<b>★  </b>						1	_	
Connector number    Solution   Connector number   C	31 A05		internal						0 0		
Connector number  100 90 On rate(%) 70 60 50 40 Derating level    B14   6	B02								1		
Connector number    100	DC24V COM		Circuit					B14	1	A14	
On rate(%) 70 60 60 60 60 60 60 60 60 60 60 60 60 60		Compostor minel			_			B13	1	A13	
On rate(%) 70	400 -	Connector numb	ei						1 -	l	
On rate(%) 70 60 50 40 0 10 20 30 40 50 55 °C Derating level DC28.8V DC28.8V DC28.8V B09 11 A09 27 B06 B08 B07 B06 B07 B07 B06 B07 B07 B06 B07 B07 B06 B07 B06 B07 B07 B07 B06 B07									0 0	l	
On rate(%) 70 60 80 80 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 806 807 807 806 807 807 807 807 807 807 807 807 807 807	90		7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7	B10	10					l	
B07 13 A07 29 B06 B06 B05 B05 B06 B05	On rate (0/) 80	<del>                                     </del>	<u> </u>	B09	11	A09	27			l	
B07 13 A07 29 B06 B06 B05 B05 B06 B05	70 -	+++++	<del>-                                     </del>						1		
B06							29		1	l	
B05				B06	14	A06	30		1		
0 10 20 30 40 50 55 °C  Ambient temp.  Derating level    B04   NC   A04   NC   B02   B02   B01   B02   B03   B03   B03   B04   B04   B04   B05		<del>                                     </del>	<del>                                     </del>	B05	15		31				
Derating level    Box	40 🗀	10 20 20		B04					1		
Derating level B02 COM A02 COM			, 10 00 00	B03	NC		NC		100	1	
	Derating level	AHDIEHIL	CITID.	B02	COM		COM				
501   55   7.01   55				B01	СОМ	A01	COM				

### 9.2.6 64 point DC24V input module (source/sink type)

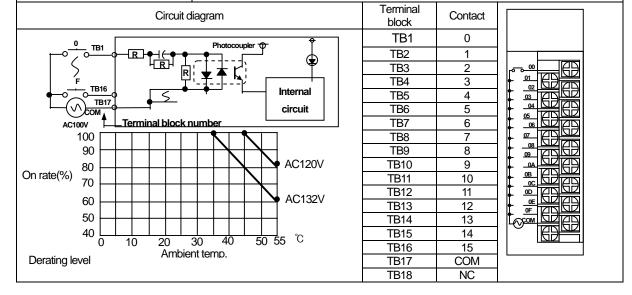
	lodule type					OC Input						
Spec.			-			XGI-E	)28A					
Input point		64 points										
Insulation method	Photo coupler insulation											
Rated input voltage		DC24	·V									
Rated input current		Appro	<b>x. 4</b> mA									
Voltage range		DC20	.4~28.8\	V (5% an	d lower ri	pple rate	)					
Input derating		Refer	to the be	elow dera	ting level							
On voltage / On current		DC 19	9V and h	nigher / 3r	nA and h	igher						
Off voltage / Off current		DC 11	1V and k	ower / 1.7	mA and	ower						
Input resistance		Appro	x. 5.6 k	2								
	Off → On			s/10ms/20	)ms/70m	s/100ms	(Set by 0	CPU Par	rameter)			
Response time			l value:3 3ms/5ms	ms s/10ms/20	)ms/70m	s/100ms	(Set by 0	CPU Par	rameter)			
$On \rightarrow Off$			l value:3				,,					
Insulation withstand volta	age	AC56	OV rms/3	3 Cycle (a	altitude 20	000m)						
Insulation resistance		10 MΩ	and hig	her by Ins	sulation o	hmmete	r					
Common method		32poii	nt / COM	1								
Suitable cable size	0.3 mm²											
Current consumption(mA)	60mA	<u> </u>										
Operation display	LED (	On with I	nput On	(32poin	t LED on	by switc	hing)					
External connection met	hod	40poii	nt conne	ctor × 2								
Weight		0.15 k	g									
Circuit di	iagram	No	Contact	No	Contact	No	Contact	No	Contact			
		1B20	0	1A20	16	2B20	32	2A20	48			
Photocou	.   1	1B19	1	1A19	17	2B19	33	2A19	49			
		1B18	2	1A18	18	2B18	34	2A18	50	B20	0 0	A
31 1A05	Internal	1B17 1B16	3	1A17 1A16	19 20	2B17 2B16	35 36	2A17 2A16	51 52	B19 B18	0 0	A
1B02	circuit	1B15	5	1A15	21	2B15	37	2A10	53	B17	0 0	A
DC24V		1B14	6	1A14	22	2B14	38	2A14	54	B16 B15	0 0	A
Connector	A Switching circuit	1B13	7	1A13	23	2B13	39	2A13	55	B14 B13	0 0	A
	в°	1B12	8	1A12	24	2B12	40	2A12	56	B12	0 0	A
A: displaying P00~P31		1B11	9	1A11	25	2B11	41	2A11	57	B11 B10	0 0	Α
90 90 90 90 90 90 90 90 90 90 90 90 90 9		1B10	10	1A10	26	2B10	42	2A10	58	B09 B08	0 0	A
On 70		1B09	11	1A09	27	2B09	43	2A09	59	B07	0 0	A
ate(%) 60 50		1B08	12 13	1A08	28	2B08	44	2A08	60	B06 B05	0 0	A
40 30	DC28.8V	1B07 1B06	14	1A07 1A06	29 30	2B07 2B06	45 46	2A07 2A06	61 62	B04 B03	0 0	A
20	1B05	15	1A05	31	2B05	47	2A05	63	B02	0 0	A	
0 10 20 30 <b>Ambient</b>	1B04	NC	1A04	NC	2B04	NC	2A04	NC	B01	الأنا	,	
temp.(°C)		1B03	NC	1A03	NC	2B03	NC	2A03	NC			
Derating level		1B02	COM	1A02	NC	2B02	COM	2A02	NC			
		1B01	СОМ	1A01	NC	2B01	COM	2A01	NC	ł		

### 9.2.7 64 point DC24V input module (source type)

	Module type	DC Input module											
Spec.						XGI-E	)28B						
Input point		64 poi	nts										
Insulation method		Photo coupler insulation											
Rated input voltage		DC24V											
Rated input current		Appro	<b>x. 4</b> mA										
Voltage range		DC20	.4~28.8\	/ (5% and	d lower ri	pple rate	)						
Input derating		Refer	to the be	elow dera	ting level								
On voltage / On current		DC 19	V and h	igher/3n	nA and h	igher							
Off voltage / Off current		DC 11	V and lo	wer / 1.7	mA and	lower							
Input resistance		Appro	x. 5.6 k	)									
Response time	$Off \rightarrow On$	Initial	value:3i										
response ume	$On \rightarrow Off$		ms/5ms value:3i	/10ms/20 ms	)ms/70m	s/100ms	(Set by 0	CPU Par	ameter)				
Insulation withstand volta	ige	AC56	OV rms/3	3 Cycle (a	ltitude 20	000m)							
Insulation resistance		10 MΩ	and hig	her by Ins	sulation o	hmmeter	-						
Common method		32 poi	nts / CO	М									
Suitable cable size	Suitable cable size			0.3 mm²									
Current consumption(mA)	60mA												
Operation display	Operation display			nput On	(32poin	t LED on	by switc	hing)					
External connection meth	nod	40point connector × 2											
Weight		0.15 k	g										
Circuit dia	gram	No	Contact	No	Contact	No	Contact	No	Contact				
Photos	<del></del>	1B20	0	1A20	16	2B20	32	2A20	48				
0 1B20 R	coupler	1B19	1	1A19	17	2B19	33	2A19	49				
	<b>↓</b>	1B18	2	1A18	18	2B18	34	2A18	50	B20	0 0	A20	
31_1405	<b>]</b> "	1B17	3	1A17	19	2B17	35	2A17	51	B19 B18	0 0	A19 A18	
1B02	Internal	1B16	4	1A16	20	2B16	36	2A16	52	B17	0 0	A18	
DC24V COM		1B15	5	1A15	21	2B15	37	2A15	53	B16	0 0	A16	
Connector	Switching	1B14	6	1A14	22	2B14	38	2A14	54	B15	0 0	A15	
number	A C circuit	1B13	7	1A13	23	2B13	39	2A13	55	B14 B13	0 0	A14 A13	
A: displaying P00	B °	1B12	8	1A12	24	2B12	40	2A12	56	B12	0 0	A12	
B: displaying P32		1B11	9	1A11	25	2B11	41	2A11	57	B11 B10	0 0	A11 A10	
100		1B10	10	1A10	26	2B10	42	2A10	58	B09	0 0	A09	
80		1B09	11	1A09	27	2B09	43	2A09	59	B08	0 0	A08	
On 70		1B08	12	1A08	28	2B08	44	2A08	60	B07 B06	0 0	A07 A06	
rate(%00		1B07	13	1A07	29	2B07	45	2A07	61	B05	0 0	A05	
40 30	DC28.8V	1B06	14	1A06	30	2B06	46	2A06	62	B04 B03	0 0	A04 A03	
20		1B05	15	1A05	31	2B05	47	2A05	63	B02	0 0	A02	
0 10 20 30 <b>Ambient</b>	40 50 55	1B04	NC	1A04	NC	2B04	NC	2A04	NC	B01	الشيا	A01	
		1B03	NC	1A03	NC	2B03	NC	2A03	NC				
Derating level temp.(℃)		1B02	COM	1A02	NC	2B02	COM	2A02	NC				
		1B01	COM	1A01	NC	2B01	СОМ	2A01	NC				

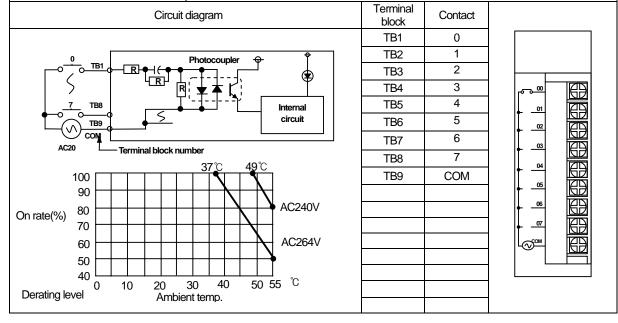
### 9.2.8 16 point AC110V input module

	Module type	AC Input module				
Spec.		XGI-A12A				
Input point		16 points				
Insulation metho	d	Photo coupler insulation				
Rated input volta	ge	AC100-120V(+10/-15%) 50/60 Hz(±3 Hz) (5% and lower distortion)				
Rated input curre	ent	Approx. 8 mA (AC100,60 Hz), approx. 7 mA (AC100,50 Hz)				
Inrush current		Max. 200 <sup>mA</sup> 1 <sup>ms</sup> and lower(AC132V)				
Input derating		Refer to the below derating level				
On voltage / On	current	AC80V and higher / 5 mA and higher (50 Hz,60 Hz)				
Off voltage / Off of	current	AC30V and higher / 1 mA and lower (50 Hz,60 Hz)				
Input resistance		Approx. 12 k $\Omega$ (60 Hz), approx. 15 k $\Omega$ (50 Hz)				
Response time	$Off \rightarrow On$	15 ms and lower(AC100V 50 Hz,60 Hz)				
Response une	$On \rightarrow Off$	25 ms and lower(AC100V 50 Hz,60 Hz)				
Insulation withsta	and voltage	AC1780V rms/3 Cycle (altitude 2000m)				
Insulation resista	nce	10 <sup>MΩ</sup> and higher by Insulation ohmmeter				
Common metho	d	16 point/ COM				
Suitable cable siz	ze	Stranded cable between 0.3~0.75 m² (2.8mm and smaller outer dia.)				
Suitable clamped	d terminal	R1.25-3 (Sleeve built-in clamped terminal is not available)				
Current consump	otion(mA)	30mA				
Operation display	y	LED On with Input On				
External connect	ion method	18point Terminal strip connector (M3 X 6 screws)				
Weight		0.13 kg				



### 9.2.9 8 point AC220V input module

	Module type	AC input module				
Spec.		XGI-A21A				
Input point		8 points				
Insulation metho	d	Photo coupler insulation				
Rated input volta	ge	AC100-240V(+10/-15%) 50/60 Hz(±3 Hz) (5% and lower distortion)				
Rated input curre	ent	Approx. 17 mA (AC200,60 Hz), approx. 14 mA (AC200,50 Hz)				
Inrush current		Max. 500 mA 1 ms and lower(AC264V)				
Input derating		Refer to the below derating level				
On voltage / On o	current	AC80V and higher / 5 mA and higher (50 Hz,60 Hz)				
Off voltage / Off current		AC30V and higher / 1 mA and lower (50 Hz,60 Hz)				
Input resistance		Approx. 12 kΩ(60 Hz), approx. 15 kΩ(50 Hz)				
Dooponoo timo	$Off \rightarrow On$	15 ms and lower(AC200V 50 Hz,60 Hz)				
Response time	$On \rightarrow Off$	25 ms and lower(AC200V 50 Hz,60 Hz)				
Insulation withsta	ınd voltage	AC2830V rms/3 Cycle (altitude 2000m)				
Insulation resista	nce	10 <sup>MQ</sup> and higher by Insulation ohmmeter				
Common method	d	8 points / COM				
Suitable cable siz	ze	Stranded cable between 0.3~0.75 mm² (2.8mm and smaller outer dia.)				
Suitable clamped	d terminal	R1.25-3 (Sleeve built-in clamped terminal is not available)				
Current consump	otion(mA)	20mA				
Operation display	/	LED On with Input On				
External connect	ion method	9point Terminal strip connector (M3 X 6 screws)				
Weight		0.13 kg				



# 9.3 Digital Output Module Spec.

# 9.3.1 8 point relay output module

	Module type		Relay o	output module				
Spec.			XC	GQ-RY1A				
Output point		8 points						
Insulation met	hod	Relay insulation						
Rated load vol	ltage/current	DC24V 2A(resistance load) / AC220V 2A(COSΨ = 1)						
Min. load volta	age / current	DC5V/1mA						
Max. load volta	age / current	AC250V, DC125V						
Leakage curre	ent at Off	0.1mA (AC220V, 60	OHz)					
Max. switching	g frequency	3,600 times/hr						
Surge killer		None						
	Mechanical	20 million and more	times					
		Rated load voltage/	current 100 thousand a	nd more times				
Life	Electrical	AC200V / 1.5A, AC	240V / 1A (COSΨ = 0.7	7) 100 thousand and more t	imes			
	Electrical	AC200V / 1A, AC24	40V / 0.5A (COSΨ = 0.3	35) 100 thousand and more	times			
		DC24V / 1A, DC100	0V/0.1A (L/R = 7ms)	100 thousand and more tim	nes			
Response	$Off \rightarrow On$	10 ms and lower						
time	ne On → Off 12 ms and lower							
Common met	hod	1 point/ 1COM (Inde	ependent contact)					
Current consu	ımption	260mA (when ever	y point is On)					
Operation disp	olay	LED On with output	:On					
External conne	ection method	18 point Terminal st	rip connector (M3 X 6 s	screws)				
Weight		0.13kg						
	C	Circuit diagram		Terminal block Contact				
				TB1 0				
				TB2 COM				
	<del>\</del>			TB3 1 TB4 COM				
	ightharpoons			TB5 2				
	₹	lπ	B1	TB6 COM				
	Internal	<u> </u>		TB7 3 TB8 COM				
	Internal	) <b>%</b>	no –	TB9 4				
	circuit		<u>B2</u>	TB10 COM				
	,		)	TB11 5				
				TB12 COM				
			À	TB13 6 TB14 COM				
				TB15 7				
			L—Terminal block	TB16 COM				
			number	TB17 NC				
				TB18 NC				

### 9.3.2 16 point relay output module

	Module type	Relay output module						
Spec.			XC	GQ-RY2A				
Output point		16 points						
Insulation meth	nod	Relay insulation						
Rated load volt	tage/current	DC24V 2A(resistance load) / AC220V 2A(COSΨ = 1)						
Min. load volta	ge / current	DC5V/1mA						
Max. load volta	age / current	AC250V, DC125	V					
Leakage curre	nt at Off	0.1mA (AC220V,	60Hz)					
Max. switching	frequency	3,600 times/hr						
Surge killer		None						
	Mechanical	20 million and mo	ore times					
		Rated load voltag	e/current 100 thousand a	nd more times				
Life	E	AC200V / 1.5A, A	C240V / 1A (COSΨ = 0.7	7) 100 thousand and me	ore times			
	Electrical	AC200V / 1A, A	C240V / 0.5A (COSY = 0	0.35) 100 thousand and	more times			
		DC24V / 1A, DC1	100V / 0.1A (L / R = 7ms)	100 thousand and more	e times			
Response	Off → On	10 ms and lower						
time On → Off 12 ms and lower								
Common meth	nod	16 point/ 1COM						
Current consur	mption	500mA (when ev	ery point is On)					
Operation disp	lay	LED On with output On						
External conne	ection method	18point Terminal	18point Terminal strip connector (M3 X 6 screws)					
Weight		0.17kg						
	C	Circuit diagram		Terminal Contact	t			
				block Contact	-			
			-	TB2 1	1			
	<del>Q-</del>			TB3 2				
100 6	_			TB4 3 TB5 4				
LED (2	<b>*</b>			TB6 5				
	<u></u>		TB1   L	TB7 6				
	nternal A RV	ا هٔ ا	<u> </u>	TB8 7				
	circuit	Ľ,		TB9 8				
			TB16	TB10 9 TB11 10				
				TB12 11				
			1B17 \\	TB13 12				
			J 🕴 🔾	TB14 13				
			Terminal	TB15 14				
			block number	TB16 15	]     <del>                                 </del>			
				TB17 COM	<del> </del>			

### 9.3.3 16 point relay output module(Surge Killer built-in type)

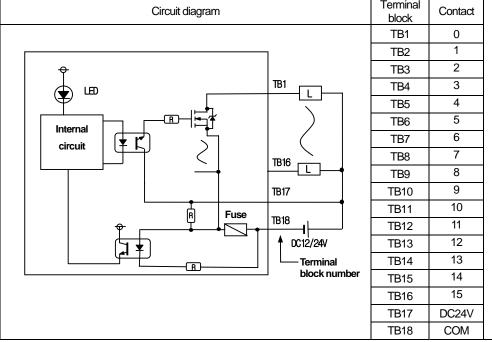
	Module type		Relay o	utput mod	ule				
Spec.				Q-RY2B					
Output point		16 points							
Insulation me	thod	Relay insulation							
Rated load vo	oltage/current	DC24V 2A(resistar	nce load) / AC220V 2A(C	OSΨ = 1)					
Min. load volta	age / current	DC5V / 1mA							
Max. load vol	tage / current	AC250V, DC125V							
Leakage curr	ent at Off	0.1mA (AC220V, 6	60Hz)						
Max. switchin	g frequency	3,600 times/hr							
Surge killer		Varistor (387 ~ 473	V), C.R absorber						
	Mechanical	20 million and more	e times						
		Rated load voltage	/current 100 thousand ar	nd more times	S				
Life	Floridad	AC200V / 1.5A, AC	C240V / 1A (COSΨ = 0.7	) 100 thousa	nd and mo	re times			
	Electrical	AC200V / 1A, AC2	40V / 0.5A (COSΨ = 0.3	5) 100 thous	and and m	ore times			
		DC24V / 1A, DC10	00V / 0.1A (L / R = 7ms) 1	100 thousand	and more	times			
Response	Off → On	10 ms and lower							
time	$On \rightarrow Off$	12 ms and lower	12 ms and lower						
Common me	thod	16 point/ 1COM							
Current consu	umption	500mA (when eve	ry point is On)						
Operation dis	play	LED On with output On							
External conn	nection method	18 point Terminal strip connector (M3 X 6 screws)							
Weight		0.19kg							
		Circuit diagram		Terminal block	Contact				
				TB1	0				
			1	TB2 TB3	1				
	<del>•</del>			TB4	3				
	lack			TB5	4				
	T		тв1	TB6	5				
	Internal	1 -		TB7	6				
		⇒ ╣ ⇄		TB8	7				
	circuit	<b>1</b> 🖳		TB9	8				
			TB16	TB10 TB11	9 10				
			TB17	TB12	11				
			<del> </del>	TB13	12				
			] 🕴 💛	TB14	13				
			Terminal block	TB15	14				
			number	TB16	15				
				TB17	COM				
				TB18	NC				

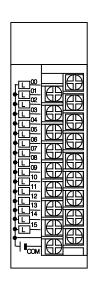
### 9.3.4 16 point Triac output module

	Module type	Triac	output module
Spec.		Х	(GQ-SS2A
Output point		16 points	
Insulation me	thod	Photo coupler insulation	
Rated load vo	oltage	AC 100-240V (50 / 60 Hz)	
Max. load vol	tage	AC 264V	
Max. load cu	rent	0.6A / 1 point, 4A / 1COM	
Min. load cur	rent	20 mA	
Leakage curr	ent at Off	2.5 mA (AC 220V 60 Hz)	
Max. inrush o	urrent	20A / Cycle and lower	
Max. voltage drop at On AC 1.5V and lower (2A)			
Surge killer		Varistor (387 ~ 473V), C.R absorber	
Response	$Off \rightarrow On$	1 ms and shorter	
time	$On \rightarrow Off$	0.5 Cycle + 1 ms and shorter	
Common me	thod	16 point/ 1 COM	
Current cons	umption	300 mA (when every point is On)	
Operation dis	play	LED On with output On	
External conr	nection method	18point Terminal strip connector (M3 X 6 s	screw)
Weight		0.2 kg	
	(	Circuit diagram	Terminal block Contact
LED	Internal circuit Tria	TB16 L Terminal block number	TB1 0 TB2 1 TB3 2 TB4 3 TB5 4 TB6 5 TB7 6 TB8 7 TB9 8 TB10 9 TB11 10 TB12 11 TB13 12 TB13 12 TB14 13 TB15 14 TB16 15
			TB17 COM TB18 NC

### 9.3.5 16 point transistor output module (sink type)

	Module type	Transistor output module						
Spec.		XGQ-TR2A						
Output point		16 points						
Insulation method	i	Photo coupler insulation						
Rated load voltag	e	DC 12/24V						
Operating load vo	oltage range	DC 10.2 ~ 26.4V						
Max. load current		0.5A / 1point, 4A / 1COM						
Leakage current	at Off	0.1mA and lower						
Max. inrush curre	nt	4A / 10 ms and lower						
Max. voltage drop	at On	DC 0.3V AND LOWER						
Surge killer		Zener diode						
Fuse		4Ax2(not replaceable)(Fuse cap.:50A)						
Fuse disconnection	on display	Yes(If a fuse is burnt out, it transfers a signal to CPU and LED is on) If external power supply is off, fuse status is not detected.						
Response time	$Off \rightarrow On$	1 ms and shorter						
Response une	$On \rightarrow Off$	1 ms and shorter (Rated load, resistance load)						
Common method	I	16 point/ 1COM						
Current consump	tion	70mA (when every point is On)						
External power	Voltage	DC12/24V ± 10% (4 Vp-p and lower ripple voltage)						
supply	Current	10mA and lower (if connected to DC24V)						
Operation display	,	LED On with output On						
External connecti	on method	18point Terminal strip connector						
Weight		0.11kg						
	0:	Terminal						





## 9.3.6 32 point transistor output module(sink type)

	Module type		Transi	stor outp	ut mod	lule					
Spec.		XGQ-TR4A									
Output point		32 point									
Insulation method		Photo coupler insulation									
Rated load voltage	)	DC 12/24V									
Operating load vol	tage range	DC 10.2 ~ 26.4V									
Max. load current		0.1A / 1point, 2A / 1COM									
Leakage current a	t Off	0.1mA and lower									
Max. inrush currer	nt	0.7A / 10 ms and lower	0.7A / 10 ms and lower								
Max. voltage drop	at On	DC 0.2V and lower									
Surge killer		Zener diode									
Danasa tima	Off → On	1 ms and shorter									
Response time	$On \rightarrow Off$	1 ms and shorter (Rated load,	resistan	ce load)							
Common method		32 points / 1COM									
Current consumpt	ion	130mA (when every point is O	n)								
External power	Voltage	DC12/24V $\pm$ 10% (4 Vp-p and lower ripple voltage)									
supply	Current	10mA and lower (if connected	to DC24	IV)							
Operation display		LED On with Input On									
External connection	n method	40 Pin Connector									
Suitable cable size	)	0.3 mm²									
Weight		0.1 kg									
	Circuit diag	gram	No	Contact	No	Contact					
			B20	0	A20	16		~			
			B19	1	A19	17		6.9	A20		
Φ.		<u> </u>	B18	2	A18	18	B20 B19	0 0	A20 A19		
		B20	B17	3	A17	19	B18	0 0	A18		
			B16	4	A16	20	B17	0 0	A17		
Ι Υ		<u> </u>	B15	5	A15	21	B16	0 0	A16		
	_ <del>_</del> ®⊢[ <u>*</u>	<u></u>	B14	6	A14	22	B15		A15		
Internal	<del>                                      </del>	<u></u>	B13	7	A13	23	B14	0 0	A14		
circuit	[ <b>‡</b> 戊]	)   (   [	B12	8	A12	24	B13	0 0	A13 A12		
		.   A05   [	B11	9	A11	25	B12 B11		A12 A11		
	-	<b>─</b> ┥ ├──── <u>└</u> └──┤┌	B10	10	A10	26	B10		A10		
			B09	11	A09	27	B09	0 0	A09		
		801,802	B08	12	A08	28	B08		A08		
		1 1 1	B07	13	A07	29	B07		A07		
		A01,A02	B06	14	A06	30	B06		A06		
		↑ DC12/24V	B05	15	A05	31	B05		A05		
			B03	NC	A03	NC	B04 B03	0 0	A04 A03		
		Connector					B02	0 0	A02		
		number	B03	NC DC42/	A03	NC	B01	10 9	A01		
		<u> </u>	B02	DC12/	A02	COM					
			B01	24V	A01	COM					

### 9.3.7 64 point transistor output module (sink type)

	Module type				Trans	sistor ou	tput mo	dule				
Spec.						XGQ-						
Output point		64 poin	its									
Insulation system		Photo	coupler i	nsulation								
Rated load voltage	)	DC 12	2/24V									
Operating load vol	tage range	DC 10	).2 ~ 26.4	·V								
Max. load current		0.1A/	1point, 2	A / 1COM								
Leakage current a	t Off	0.1m/	and low	er								
Max. inrush currer	nt	0.7A / 10 ms and lower										
Max. voltage drop	at On	DC 0.2	DC 0.2V and lower									
Surge killer		Zener	diode									
5	Off → On	1 ms a	1 ms and shorter									
Response time	$On \rightarrow Off$	1 ms a	and short	er (Rated	load, resi	stance lo	ad)					
Common method		16 poi	nt/ 1CON	1								
Current consumpti	ion	230m	A (when	every poin	t is On)							
Common method		32 poi	nts / CON	Л								
External power	Voltage	DC12	DC12/24V ± 10% (4 Vp-p and lower ripple voltage)									
supply	· •			er (if conne	ected to D	C24V)						
Operation display	Operation display			put On (	32point L	.ED on b	y switchi	ng)				
External connection	External connection method			tor×2								
Suitable cable size	)	0.3 mm										
Weight		0.15 k	g									
Circu	it diagram	No	Contact	No	Contact	No	Contact	No	Contact			
		1B20	0	1A20	16	2B20	32	2A20	48	•		
		1B19	1	1A19	17	2B19	33	2A19	49		^	
•		1B18	2	1A18	18	2B18	34	2A18	50	B20	00	١
	B20	1B17	3	1A17	19	2B17	35	2A17	51	B19	0 0	A20 A19
🕸		1B16	4	1A16	20	2B16	36	2A16	52	B18	0 0	A18
IJ <del>ੵ</del>	┧ <b>╬</b> ╸│	1B15	5	1A15	21	2B15	37	2A15	53	B17	0 0	A17
Internal		1B14	6	1A14	22	2B14	38	2A14	54	B16	0 0	A16
circuit	$\supset \bigcap \bigcup $	1B13	7 8	1A13	23 24	2B13	39	2A13	55	B15	0 0	A15
	(   A05 📐	1B12 1B11	9	1A12 1A11	25	2B12 2B11	40 41	2A12 2A11	56 57	B14 B13	0 0	A14 A13
		1B10	10	1A10	26	2B10	42	2A11	58	B12	0 0	A12
	B01,B02	1B09	11	1A09	27	2B09	43	2A10	59	B11	0 0	A11
	101,002	1B09	12	1A09	-	2B09 2B08	43	2A09 2A08	60	B10	0 0	A10
Switching	404 400		13		28 29	2B07	44	2A08 2A07	61	B09 B08	0 0	A09 A08
circuit	A01.A02	1B07 1B06	14	1A07 1A06	30	2B07 2B06	46	2A07 2A06	62	B08 B07	0 0	A08 A07
°0B	DC12/24V	1B05	15	1A05	31	2B05	46	2A06	63	B06	0 0	A06
		1B05	NC	1A05	NC	2B03	NC	2A05	NC	B05	0 0	A05
		1B04	NC	1A04	NC	2B04 2B03	NC	2A04 2A03	NC	B04	0 0	A04
	Connector	1B03		1A03	INC	2B02	140	2A02	IVC	B03 B02	0 0	A03 A02
A: displaying 0~31 B: displaying 32~63		1B01	12/24 VDC	1A01	COM1	2B01	12/24 VDC	2A01	COM2	B01	ستا	A01

## 9.3.8 16 point transistor output module (source type)

	Module type			stor output m	odule			
Spec.				XGQ-TR2B				
Output point		16 points						
nsulation method		Photo coupler	insulation					
Rated load voltag	е	DC 12/24V						
Operating load vo	ltage range	DC 10.2 ~ 26.4	1V					
Max. load current		0.5A / 1point, 4	A/1COM					
Leakage current a	at Off	0.1mA and low	er					
Max. inrush curre	nt	4A / 10 ms and lower						
Max. voltage drop	at On	DC 0.3V AND LOWER						
Surge killer		Zener diode						
Fuse		4A×2(not repla	ceable)(Fuse cap.:50A)					
Fuse disconnection	on display	Yes(If a fuse is	burnt out, it transfers a s	ignal to CPU a	and LED is o	n)		
Response time	$Off {\to} On$	1 ms and short	ter					
r coporise unie	$On {\to} Off$	1 ms and short	ter (Rated load, resistand	ce load)				
Common method		16 point/ 1CON	M					
Current consump	tion	70mA (when e	mA (when every point is On)					
External power	Voltage	DC12/24V ± 10% (4 Vp-p and lower ripple voltage)						
supply	Current	10mA and lower (if connected to DC24V)						
Operation display		LED On with o	utput On					
External connection	on method	18point Termir	nal strip connector					
Weight		0.12kg		T = · ·	Π			
	Circ	uit diagram		Terminal block	Contact			
				TB1	0			
				TB2	1			
🕈			TD1	TB3	2			
	LED			TB4	3			
				TB5	5			
Internal				TB6	6			
circuit	(* [5]	>		TB8	7			
	_}		TB16	TB9	8			
				TB10	9			
			<u>↑   TB17</u>	TB11	10			
		R Fuse	DC12/24V TB18	TB12	11			
		•		TB13	12			
	[A] <del>*</del> ]		Terminal	TB13	13			
		- R	block no.	TB15	14			
				TB16	15			
				.5.0	_			

TB17

TB18

COM

### 9.3.9 32 point transistor output module (source type)

	Module type	Т	ransisto	or output	module	)					
Spec.	· · · · · · · · · · · · · · · · · · ·			Q-TR4E							
Output point		32 points									
Insulation method		Photo coupler insulation									
Rated load voltage		DC 12/24V									
Operating load volt	age range	DC 10.2 ~ 26.4V									
Max. load current		0.1A / 1point, 2A / 1COM									
Leakage current at	Off	0.1mA and lower									
Max. inrush current	t	4A / 10 ms and lower									
Max. voltage drop a	at On	DC 0.3V AND LOWER									
Surge killer		Zener diode									
Response time	Off → On	1 ms and shorter									
Response time	$On \rightarrow Off$	1 ms and shorter (Rated load	resistan	ice load)							
Common method		32points / 1COM									
Current consumption	on	130mA (when every point is 0	On)								
External power	Voltage	DC12/24V $\pm$ 10% (4 Vp-p and lower ripple voltage)									
supply	Current	10mA and lower (if connected	to DC2	4V)							
Operation display		LED On with Input On									
External connection	n method	40 Pin Connector									
Suitable cable size		0.3 mm²									
Weight		0.1 kg									
	Circuit diagra	m	No	Contact	No	Contact					
			B20	0	A20	16					
			B19	1	A19	17	B20	0 0	A20		
			B18	2	A18	18	B19	0 0	A19		
			B17	3	A17	19	B18 B17	0 0	A18 A17		
		B02,B01	B16	4	A16	20	B16	0 0	A16		
		D010/04V	B15	5	A15	21	B15	0 0	A15		
	_	A02,A01 DC12/24V	B14	6	A14	22	B14	0 0	A14		
Internal			B13	7	A13	23	B13	0 0	A13		
circuit	<b>*</b> [	A05	B12	8	A12	24	B12	0 0	A12		
			B11	9	A11	25	B11 B10	0 0	A11 A10		
			B10	10	A10	26	B09	0 0	A09		
			B09	11	A09	27	B08	0 0	A08		
			B08	12	A08	28	B07	0 0	A07		
	_ '⊢	`   B20	B07	13	A07	29	B06 B05	0 0	A06 A05		
	L		B06	14	A06	30	B03	0 0	A04		
		†	B05	15	A05	31	B03	0 0	A03		
		Connector	B04	NC	A04	NC	B02	0 0	A02		
		number	B03	NC	A03	NC	B01	الركا	A01		
			B02	СОМ	A02	0V		-			
			B01		A01						

### 9.3.10 64 point transistor output module (source type)

	Module type				Trans	sistor ou	tput mo	dule				
Spec.						XGQ-	TR8B					
Output point		64 po	ints									
Insulation method		Photo	coupler	insulatio	1							
Rated load voltage		DC 12	2/24V									_
Operating load voltag	e range		DC 10.2 ~ 26.4V									
Max. load current	o rango		0.1A/1point, 2A/1COM									
Leakage current at O	f											
	<u> </u>	0.1mA and lower  4A / 10 ms and lower										
Max. inrush current	_	-										
Max. voltage drop at 0	On	DC 0.	3V and l	ower								
Surge killer		Zener	diode									
Response time	Off → On	1 ms	and shor	ter								
response ume	$On \rightarrow Off$	1 ms	and shor	ter (Rate	d load, re	sistance	load)					
Common method		32poi	nt / 1COI	M								
Current consumption		230m	A (when	every po	int is On)	)						_
Common method		+	nt / COM			<u> </u>						
Futornal names	+ -	DC12/24V ± 10% (4 Vp-p and lower ripple voltage)										
External power supply	+	10mA and lower (if connected to DC24V)										
							.1.1				_	
Operation display			LED On with Input On (32 point LED ON by switching)  40 Pin Connector × 2									
External connection n	nethod			ctor × 2								
Suitable cable size		0.3 mm										
Weight		0.15 kg										
Circuit	diagram	No	Contact	No	Contact	No	Contact	No	Contact			
		1B20	0	1A20	16	2B20	32	2A20	48			
		1B19	1	1A19	17	2B19	33	2A19	49		^	
		1B18	2	1A18	18	2B18	34	2A18	50	B20	0 0	1
<b>G</b> -	B02,B01,	1B17	3	1A17	19	2B17	35	2A17	51	B19	0 0	ı
	<del>                                     </del>	1B16	4	1A16	20	2B16	36	2A16	52	B18	0 0	- 1
❤	DC12/24V	1B15	5	1A15	21	2B15	37	2A15	53	B17	0 0	
		1B14	6	1A14	22	2B14	38	2A14	54	B16	0 0	- 1
Internal	A02,A01	1B13 1B12	7	1A13	23	2B13	39	2A13	55	B15	0 0	- 1
circuit	PUZ, PUT		8	1A12 1A11	24	2B12	40	2A12	56 57	B14 B13	0 0	- 1
	A05	1B11			25	2B11	41	2A11		B12	0 0	- 1
	\ <del>  \                                </del>	1B10	10	1A10	26	2B10	42	2A10	58	B11	0 0	
<u></u>		1B09	11	1A09	27	2B09	43	2A09	59	B10	0 0	- 1
		1B08	12	1A08	28	2B08	44	2A08	60	B09	0 0	- 1
		1B07	13	1A07	29	2B07	45	2A07	61	B08 B07	0 0	١
Switching	\\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\	1B06	14	1A06	30	2B06	46	2A06	62	B06	0 0	- 1
circuit A	B20	1B05	15	1A05	31	2B05	47 NO	2A05	63	B05	000	- 1
°°B	<b>↑</b>	1B04	NC	1A04	NC	2B04	NC	2A04	NC	B04	0 0	
		1B03	NC	1A03	NC	2B03	NC	2A03	NC	B03 B02	0 0	١
A: displaying ( B: displaying 3		1 <b>B02</b>	СОМ	1 <b>A02</b>	0V	<b>2B02</b> 2B01	сом	<b>2A02</b> 2A01	0V	B01	00	ا
D: OBOBVING S				1 7///17								

# 9.4 Digital I/O Combined Module Specifications

### 9.4.1 32 point (DC input - transistor output) I/O combined module

		XC	SH-DT4A				
		Input			0	utput	
Input point		16 points	Output point			16 points	
Insulation n	nethod	Photo coupler insulation	Insulation method			Photo coupler	insulation
Rated inpu	t voltage	DC 24V	Rated load v	roltage		DC 12 / 24V	
Rated inpu	t current	Approx. 4 mA	Operating load voltage range			DC 10.2 ~ 26.	4V
Operating v	voltage range	DC20.4~28.8V (5% and lower ripple rate)	Max. load cu	ırrent		0.1A / 1point, 1	1.6A / 1COM
Withstand	voltage	AC560Vrms/3Cycle(altitude2000m)	Leakage cur	rent at Off		0.1mA and lov	ver
On voltage	/On current	DC 19V and higher / 3mA and higher	Max. inrush	current		0.7A / 10 ms a	nd lower
Off voltage	/Off current	DC 11V and lower / 1.7mA and lower	Surge killer			Zener diode	
Input resist	ance	Approx. 5.6 kΩ	Max. voltage	drop at Or	n	DC 0.2V and I	ower
Response	Off→ On	1ms/3ms/5ms/10ms/20ms/70ms/ 100ms(set by CPU parameter) Initial value:3ms	Response	Off→ On	ı	1 ms and shor	ter
time	On → Off 1ms/3ms/5ms/10ms/20ms/70ms/ 100ms(set by CPU parameter) Initial value:3ms		time	On → Of	f	1 ms and shor (Rated load, re	ter esistance load)
Common method 16 point/ COM			Common me	ethod		16 point/ 1CO	M
Operation display LED On with input On			Operation dis	splay		LED On with o	output On
Current cons	sumption(mA)	110mA (when ever point is on)					
External method	connection	40 Pin Connector × 1					
Weight		0.1 kg					
		Circuit		E	xternal co	onnection	
Input 00	B20 R	Photocoupler +			No Con		
0F 0F 0F 0F 0F 0F 0F 0F	B05 302,B01	Internal circuit	B20 B19 B18 B17 B16 B15	1 A 2 A 3 A 4 A	A19 1 A18 1 A17 1 A16 2	6	O O A20 O O A19 O O A18 O O A17
	— Conne	ector number	B14			22 B16 B15	0 0 A15
Output  Intern circul	al 😾 🖍	A20 L A05 L A04,A03 A02,A01	B13 B12 B11 B10 B09 B08 B07 B06 B05 B04 B03 B02 B01	8 A 9 A 10 A 11 A 12 A 13 A 14 A 15 A NC A NC A	A12 2 A11 2 A10 2 A09 2 A08 2 A07 2 A06 3 A05 3 A04 D0	23 B14 24 B13 25 B12 26 B11 27 B09 28 B08 29 B07 B06 B1 B04 C12 B03 4V B02 B01	O O A14 O O A13 O O A12 O O A11 O O A10 O O A09 O O A08 O O A06 O O A05 O O A07

# 9.5 Applications of Smart Link

### 9.5.1 Modules accessible to Smart Link

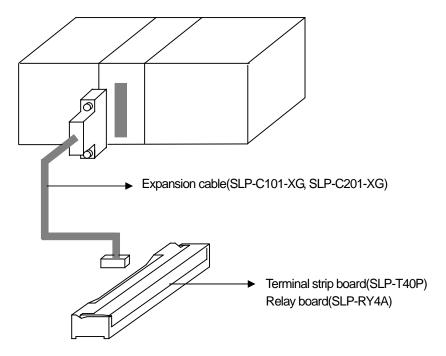
From digital I/O modules used for XGI series, the modules accessible to Smart Link are as follows.

Model	Specification	No. of Pins
XGI-D24A/B	DC input 32 point module	40 Pin Connector x 1
XGI-D28A/B	DC input 64 point module	40 Pin Connector x 2
XGQ-TR4A	TR output 32 point module(sink type)	40 Pin Connector x 1
XGQ-TR4B	TR output 32 point module(source type)	40 Pin Connector x 1
XGQ-TR8A	TR output 64 point module(sink type)	40 Pin Connector x 2
XGQ-TR8B	TR output 64 point module(source type)	40 Pin Connector x 2
XGH-DT4A	DC input 16 points/TR output 16 point mixed module	40 Pin Connector x 1

The company prepares smart link products for the convenience of using our products such as easy wiring of connector type I/O module. For further information, please refer to the data sheet contained in a smart link product.

Туре	Product	Specification
Terminal strip board	SLP-T40P	40 Pin Terminal strip
Relay board	SLP-RY4A	32 point relay built in
Cable	SLP-C101-XG	1m cable Ass'y
	SLP-C201-XG	2m cable Ass'y

### 9.5.2 Smart Link connection



# **Chapter 10. Base and Expansion Cable**

### 10.1 Specification

#### 10.1.1 Basic base

Power module, CPU module, Ethernet communication module can be inserted into basic base.

XGR-M06A uses 5.5A power module.

Table 1 Specification of basic base

Table 1 openioation of basic base				
Name Item	XGR-M06A			
The no. of IO module	6 modules			
Dimension (mm)	346 X 98 X 19			
Distance of hole for panel attachment	326 X 75			
Specification of hole for panel attachment	φ 4.5 (M4 screw used)			
Specification of screw for FG connection	(+)PHM 3 X 6 washer(\$\phi\$ 5)			
Weight (kg)	0.34			

### 10.1.2 Expansion Base

Power module, expansion driver module, IO module, special module, communication module can be inserted into expansion base.

Table 2 Specification of expansion base

Name Item	XGR-E12A
The no. of IO module	12 modules
Dimension (mm)	481 X 98 X 19
Distance of hole for panel attachment	461 X 75
Specification of hole for panel attachment	φ 4.5 (M4 screw used)
Specification of screw for FG connection	(+)PHM 3 X 6 washer (φ 5)
Weight (kg) (kg)	0.59

#### 10.1.3 Sync. Cable

This cable is used for the data synchronization between CPU modules.

Table 3 Specification of Sync. cable

Name Item	XGC-F201	XGC-F501
Length (m)	2.0	5.0
Weight (g)	21g	47g
The quality of the material	Multi Mode Fiber (max. 2 Km) – separate order for other specifications	

### 10.1.4 Expansion Cable

This is the cable for connecting the basic and expansion bases. These are Ethernet cables. Electrical and optical cables are provided for use in accordance with the network type.

Especially, since the electrical cables transmit control data by tens of micro, external noise may affect system performance and control seriously.

Therefore, when using electrical cables in the XGR system, the FTP cable is the standard. If the system is subject to serious noise environment, use shielded twisted pair cable, such as STP/FSTP.

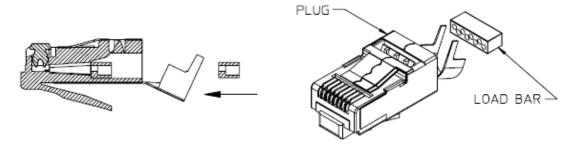


- 1) The length of the optical cables should not exceed 2Km.
- 2) The length of the electrical cables should not exceed 100m.

### 10.1.5 Connector for expansion cable (electrical)

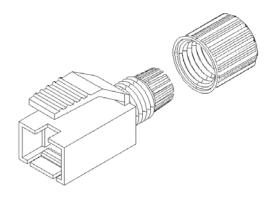
The electrical expansion cables should be shielded twisted pair cables, such as FTP, STP, and SFTP, in order to meet the EMC specification and reduce external noise. To use such shield cables, the plugs and fix housing should be as follows.

#### 1) Connector Plug



Type: RJ45 PLUG /INDUSTRIAL CAT6(44915-0021)

### 2) Plug Housing



Type (for FTP): RJ45 PLUG protection cover (WRJ45-0702) Type (for STP/SFTP): RJ45 PLUG protection cover (WRJ45-0701)

### 10.2 Parts and Names

### 10.2.1 Basic Base

Table 4. Identification and Function of the Basic Base No. Name **Function** 1 Guide hole for base mounting Hole for the installation of this base on the panel in the control cabinet 2 Power module connector The connector for mounting power module CPU module connector The connector for mounting CPU module 3 4 Module mounting connector The connector for mounting I/O module (5) FG terminal Functional ground terminal

### 10.2.2 Expansion Base

Table 5. Identification and Function of the Expansion Base No. Name **Function** 1 Guide hole for base mounting Hole for the installation of this base on the panel in the control cabinet 2 Power module connector The connector for mounting power module 3 Expansion module connector The connector for mounting expansion module 4 Module mounting connector The connector for mounting I/O module (5) FG terminal Functional ground terminal

# **Chapter 11. Installation and Wiring**

### 11.1 Installation

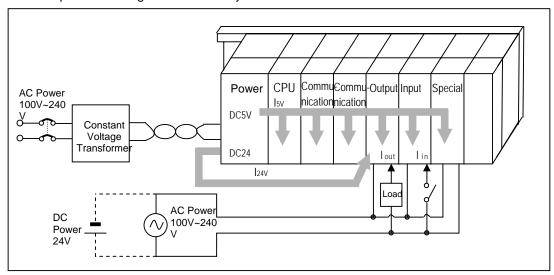
#### 11.1.1 Installation environment

The system keeps a high reliability, irrespective of the installation environment. However, to guarantee the reliability and stability, make sure to keep the following cautions.

- 1) Environmental conditions
  - (1) Install in a control panel resisting to moisture and vibration.
  - (2) Free of any continuous impact or vibration.
  - (3) Not exposed to direct sunrays.
  - (4) No condensation from sudden temperature fluctuation.
  - (5) Ambient temperature range between  $0 \sim 55^{\circ}$ C.
  - (6) Relative humidity between 5 ~ 95%.
  - (7) Free of any corrosive gas or flammable gas.
- 2) Installation construction
  - (1) When boring a screw hole or executing wiring construction, any wiring impurities should not be inserted to the PLC.
  - (2) The system should be installed in a place easily accessible.
  - (3) Do not install the system on a same panel of a high voltage device.
  - (4) It should be 50mm and more away from wiring duct or proximate modules.
  - (5) Grounding on a position where noise is lower than the specified level.
- 3) Heat protective design of control panel
  - (1) If installing the PLC in an air-tight control panel, it needs heat-protective(control) design considering the heat from the PLC as well as other devices. If ventilating by vent or fan, inflow of dust or gas may affect the performance of the PLC system.
  - (2) Install a filter or use a closed heat exchanger.

The following shows the calculation of PLC system's power consumption requiring heat protective design.

4) Power Consumption block diagram of the PLC system



- 5) Power consumption of each part
  - (1) Power consumption of power module

The power conversion efficiency of power module is about 70% and the other 30% is gone with heat; 3/7 of the output power is the pure power consumption. Therefore, the calculation is as follows.

• Wpw =  $3/7 \{(I_{5} \lor X_{5}) + (I_{24} \lor X_{24})\} (W)$ 

lsv: power consumption of each module DC5V circuit(internal current consumption)

l<sub>24</sub>v: the average current consumption of DC24V used for output module

(current consumption of simultaneous On point)

If DC24V is externally supplied or a power module without DC24V is used, it is not applicable.

(2) Sum of DC5V circuit current consumption

The DC5V output circuit power of the power module is the sum of power consumption used by each module.

- W5V = I5V X 5 (W)
- (3) DC24V average power consumption(power consumption of simultaneous On point)

The DC24V output circuit's average power of the power module is the sum of power consumption used by each module.

- W<sub>24</sub>V = I<sub>24</sub>V X 24 (W)
- (4) Average power consumption by output voltage drop of the output module(power consumption of simultaneous On point)
  - Wout = lout X Vdrop X output point X simultaneous On rate (W)

lout: output current(actually used current) (A)

Vdrop: voltage drop of each output module (V)

- (5) Input average power consumption of input module(power consumption of simultaneous On point)
  - Win = Iin X E X input point X simultaneous On rate (W)
  - lin: input current (root mean square value in case of AC) (A)
- E : input voltage (actually used voltage) (V)
- (6) Power consumption of special module power assembly
  - Ws = I<sub>5</sub>V X 5 + I<sub>2</sub>4V X 24 + I<sub>1</sub>00V X 100 (W)

The sum of power consumption calculated by each block is the power consumption of the entire PLC system.

### **Chapter 11. Installation and Wiring**

•  $W = W_{PW} + W_{5V} + W_{24V} + W_{out} + W_{in} + W_{s} (W)$ 

Calculate the heats according to the entire power consumption(W) and review the temperature increase within the control panel.

The calculation of temperature rise within the control panel is displayed as follows.

T = W / UA [°C]

W: power consumption of the entire PLC system (the above calculated value)

A: surface area of control panel [m<sup>2</sup>]

U: if equalizing the temperature of the control panel by using a fan and others - - - 6

If the air inside the panel is not ventilated - - - - - 4

#### Note

- 1) If the control cabinet is not well ventilated, temperature gradient in the cabinet may be large. Care must be taken that the parts right above heat generating devices may become very hot.
- 2) Coefficient U, which can be different according to quantity of material, is general example

Calculation example)

Redundant basic base: 4 communication modules equipped

Expansion base 1: optical expansion drive, 6 Input modules, 6 output modules

Expansion base 2:optical expansion drive, 6 analog input modules, 6 analog output modules.

Structure figure, calculation according to above steps

#### 11.1.2 Cautions for handling

It describes the cautions for handling from unpacking to installation.

- Please do not drop it or apply excessive force on it.
- Please do not separate PCB from the case. It may cause a trouble.
- During wiring, a special attention should be paid so that impurities such as wiring remainder should not be inserted into the top of a module. If impurities are found, immediately remove them.
- 1) Cautions for handling I/O module

It describes the cautions for installing or handling I/O module.

(1) Recheck the I/O module specifications.

The input module may be affected by input voltage while the output module may be subject to breakage, destruction or a fire if the voltage over the max. switching capacity is allowed.

(2) Available cable type

Cable should be selected in consideration of ambient temperature and allowable current; the min. size of cable should be AWG22(0.3mm²) and higher.

(3) Environment

If I/O module wiring is close to heating sources or materials or the wiring is directly contacted with oils for a long time during wiring, it may cause short-circuit, destruction or malfunction.

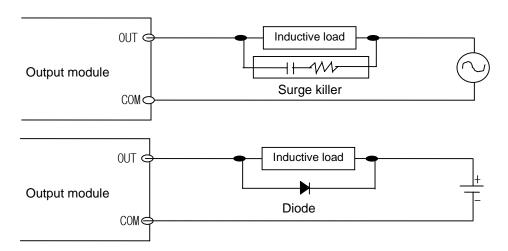
(4) Polarities

Please make sure to check the polarities of modules of which terminal block is polarized before allowing the power.

(5) Wiring

 When I/O wiring is executed with high voltage or power cable, it may cause inductive fault, probably leading to malfunction or trouble.

- No cable should not be arranged front of I/O operation display(LED)(I/O display may be hidden, hindering the interpretation)
- If an output module is connected to inductive load, please make sure to connect a surge killer or diode to load in parallel. Please connect the cathode side of a diode to (+) of the power.



#### (6) Terminal strip

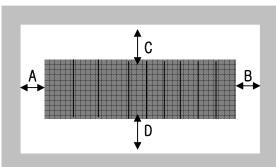
Please check the tightness of terminal strip and prevent any wiring impurities(remainder) from being inserted into the PLC when processing terminal strip wiring or screw hole making. It may cause malfunction or trouble.

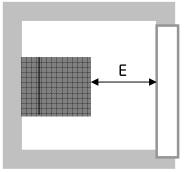
(7) Besides the above, it is prohibited to apply excessive impact on I/O module or separating PCB board from the case.

#### 2) Cautions for installing the base

It describes the cautions when installing the PLC on the control panel and others.

(1) A proper distance between the top of a module and structure/parts should be secured to facilitate ventilation and module replacement.





A, B: more than 5 cm

#### C, D: more than 5 cm for easy attachment/detachment

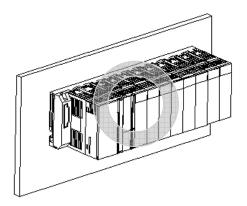
(more than 3cm with wiring duct. In case of duct height is more than 5cm, keep the distance more than 5cm.) In case using optical communication or maximum load of power module, keep the distance more than 15cm for ventilation.

#### E: more than 10 cm

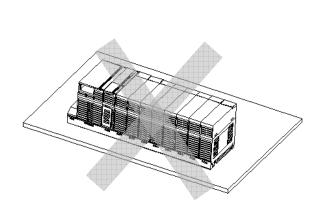
- In case of using optical cable, IO module of connector type, more than 8 cm distance necessary
- In case of Ethernet FTP cable, more than 10cm distance necessary
  - (2) Please do not install it vertically or horizontally for the ventilation purpose.

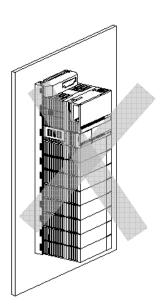
### **Chapter 11. Installation and Wiring**

- (3) Please use a different panel or secure a proper distance if there is vibration source from a large electronic contact or no-fuse breaker
- (4) If necessary, please install a wiring duct. However, please keep the following cautions.
- If installing on the top of PLC, maintain the height of a wiring duct 50mm more than for better ventilation. In addition, maintain the distance from the top of PLC so that the hook on the top of the base can be pressed.
- If installing on the bottom of it, let optical or coaxial cable be connected and consider the minimum radius of the cable.
- (5) Please install the PLC along the well-ventilated direction as presented below for the heat prevention purpose.

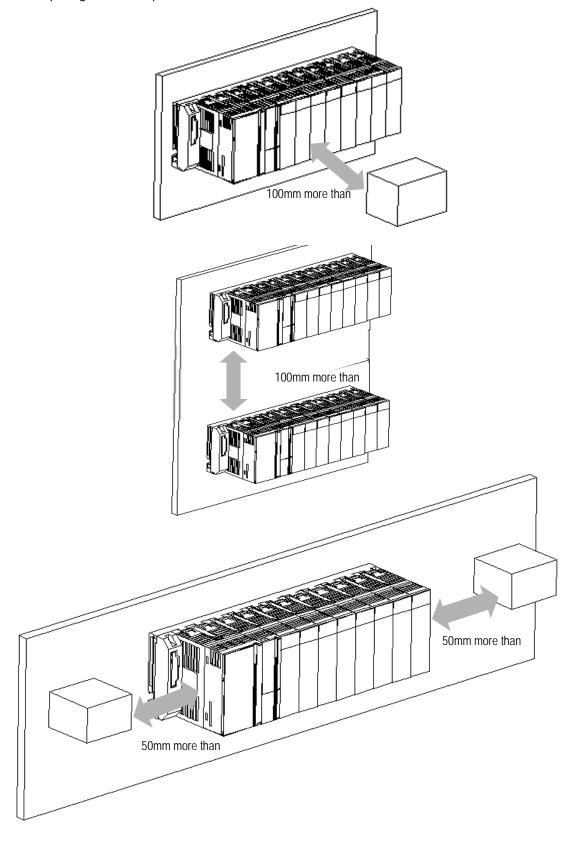


(6) Please do not install it to the direction as presented below.



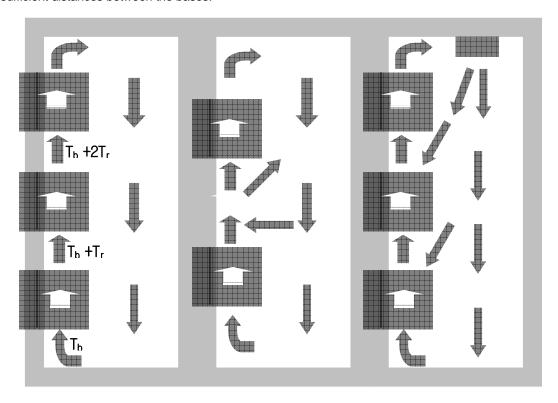


(7) To avoid any influence of radiating noise or heat, please install the PLC and other devices(relay, electronic contact) with a spacing secured as presented below.



### Chapter 11. Installation and Wiring

(8) In a layered-installation of PLCs, the temperature of the base at the top may become very high due to the heat transferred from the lower layers. If the temperature in the control cabinet is high, install a ventilating fan, or provide sufficient distances between the bases.



[Closed installation]

[Installation with distance]

[Ventilating fan]



# **Caution**

1) In case of closed installation, the temperature  $(T_b + T_r)$  around the modules right above the optical communication module and power module which generate large heat may be higher than that at other

(The temperature of the air near the modules should not exceed 55 °C.)

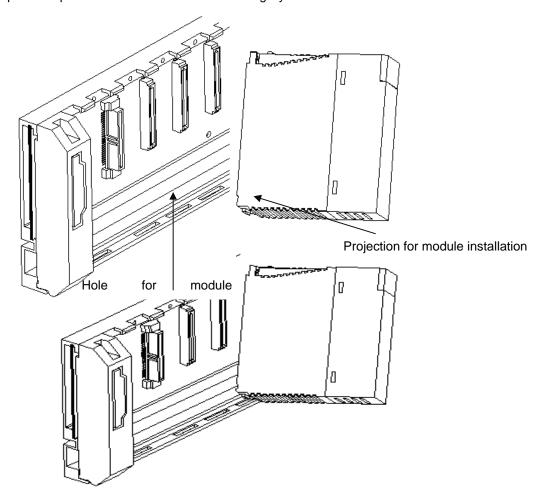
- Optical communication module: XGR-CPU(optical) module, expansion drive (optical) module, inter-PLC communication (optical) module
- 2) In order to dissipate the heat radiated from PLCs, heat conductivity between the enclosure wall and bases or base chassis should be considered in the design and installation.

#### 11.1.3 Attachment/Detachment of modules

It describes how to attach or detach a module on the base.

#### 1) Attachment

- Please insert the fixation projection on the bottom of a module to the hole of module installation of the base.
- Please fix it on the base by pushing the top of a module and tight it by using the module fixation screw.
- Please try to pull the top of a module to check whether it is tightly fixed on it.



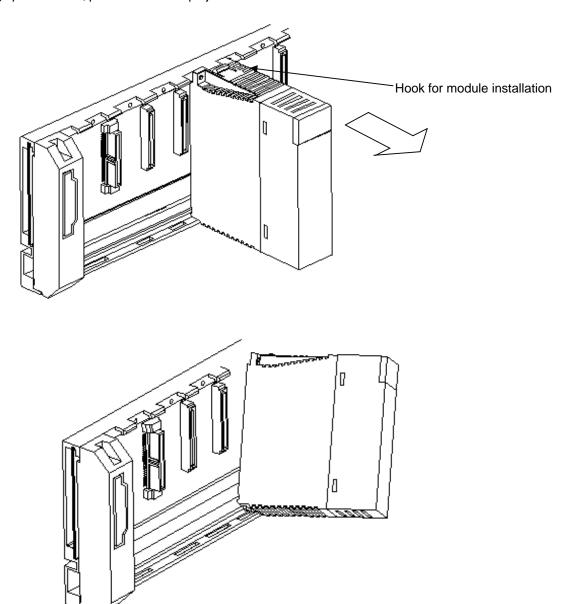


1) A module should be installed by inserting the projection for module installation to the hole for module installation. If applying an excessive force, a module may be broken.

#### **Chapter 11. Installation and Wiring**

#### 2) Detachment

- Please unscrew the fixation screw on the top of a module.
- Please press the hook for module installation with a module held by both hands.
- Please pull the bottom of a module toward the top while pressing the hook.
- Lifting up the module, please detach the projection for module installation from the hole for module installation.





# **Caution**

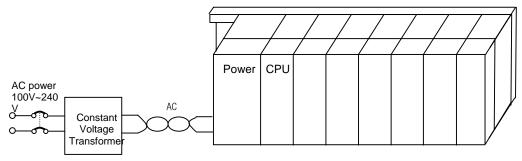
1) When detaching a module, please press the hook to detach it from the base and then, isolate the projection for module installation from the hole for module installation. At the moment, if trying to detach it forcibly, the hook or projection may be damaged.

## 11.2 Wiring

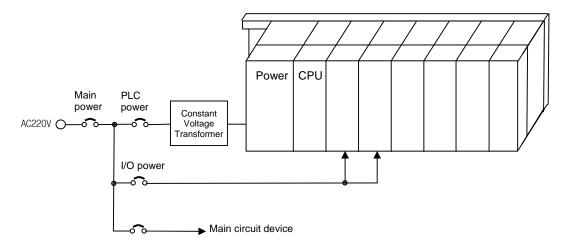
It describes the important information about wiring when using the system.

#### 11.2.1 Power wiring

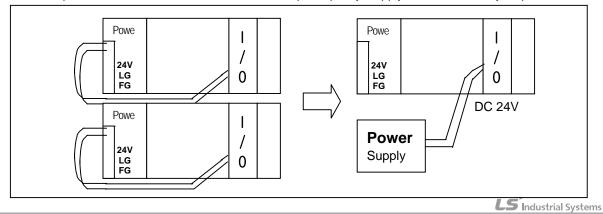
1) Connect a constant voltage transformer when the power variance is larger than the specified range.



- 2) Connect the power source of which inter-cable or cable-ground noise is small. (If a large one is connected, make sure to connect to an insulation transformer)
- 3) Isolate the PLC power, I/O devices and power devices as follows.



- 4) If using DC24V of the power module
  - Do not connect DC24V of several power modules in parallel. It may cause the destruction of a module.
  - If a power module can not meet the DC24V output capacity, supply DC24V externally as presented below.



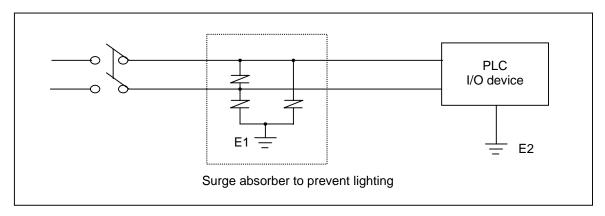
| 11-10

### **Chapter 11. Installation and Wiring**

- 5) AC110V/AC220V/DC24V cables should be compactly twisted and connected in the shortest distance.
- 6) AC110V/AC220V cable should be as thick as possible(2mm<sup>2</sup>) to reduce voltage drop.

AC110V/ DC24V cables should not be installed close to main circuit cable(high voltage/high current) and I/O signal cable. They should be 100mm away from such cables.

7) To prevent surge from lightning, use the lightning surge absorber as presented below.

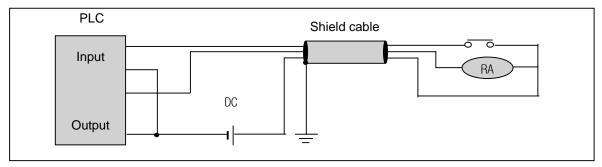




- 1) Isolate the grounding(E1) of lightning surge absorber from the grounding(E2) of the PLC.
- 2) Select a lightning surge absorber type so that the max. voltage may not the specified allowable voltage of the absorber.
- 8) When noise may be intruded inside it, use an insulated shielding transformer or noise filter.
- 9) Wiring of each input power should be twisted as short as possible and the wiring of shielding transformer or noise filter should not be arranged via a duct.

#### 11.2.2 I/O Device wiring

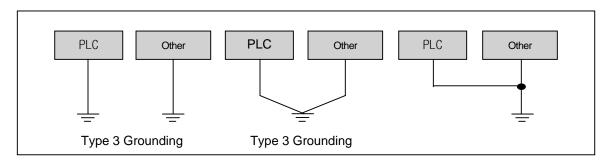
- 1) The size of I/O device cable is limited to 0.3~2 mm<sup>2</sup> but it is recommended to select a size(0.3 mm<sup>2</sup>) to use conveniently.
- 2) Please isolate input signal line from output signal line.
- 3) I/O signal lines should be wired 100mm and more away from high voltage/high current main circuit cable.
- 4) Batch shield cable should be used and the PLC side should be grounded unless the main circuit cable and power cable can not be isolated.



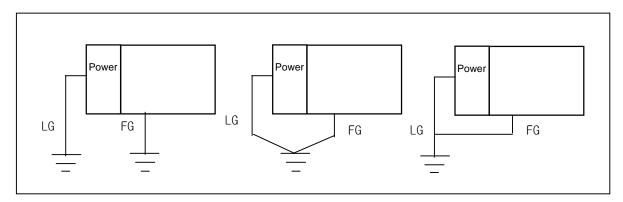
- 5) When applying pipe-wiring, make sure to firmly ground the piping.
- 6) The output line of DC24V should be isolated from AC110V cable or AC220V cable.
- 7) For a long distance wiring over 200m, please refer to 12.4 Cases in Chapter 12 because it is expected that accident may occur due to leakage current due to inter-cable capacity.

#### 11.2.3 Grounding wiring

- 1) The PLC contains a proper noise measure, so it can be used without any separate grounding if there is a large noise. However, if grounding is required, please refer to the followings.
- 2) For grounding, please make sure to use the exclusive grounding. For grounding construction, apply type 3 grounding (grounding resistance lower than 100  $\Omega$ )
- 3) If the exclusive grounding is not possible, use the common grounding as presented in B) of the figure below.



- A) Exclusive grounding: best
- B) common grounding: good
- C) common grounding: defective
- 4) Use the grounding cable more than 2 mm<sup>2</sup>. To shorten the length of the grounding cable, place the grounding point as close to the PLC as possible.
- 5) Separately ground the LG of the power module and the FG of the base board.



- A) Exclusive grounding: best
- B) common grounding: good
- C) common grounding: defective
- 6) If any malfunction from grounding is detected, separate the FG of the base from the grounding.

## **Chapter 11. Installation and Wiring**

## 11.2.4 Specifications of wiring cable

The specifications of cable used for wiring are as follows.

Types of external	Cable specification (mm²)		
connection	Lower limit	Upper limit	
Digital input	0.18 (AWG24)	1.5 (AWG16)	
Digital output	0.18 (AWG24)	2.0 (AWG14)	
Analogue I/O	0.18 (AWG24)	1.5 (AWG16)	
Communication	0.18 (AWG24)	1.5 (AWG16)	
Main power	1.5 (AWG16)	2.5 (AWG12)	
Protective grounding	1.5 (AWG16)	2.5 (AWG12)	

# Chapter 12. Maintenance

To maintain PLC in the best condition, please execute the following routine and periodic inspections.

## 12.1 Repairs and Maintenance

The I/O module mainly consists of semiconductor elements, so its life is almost semi permanent. However, such elements may be affected by the environment, so they should be periodically inspected and maintained. Please refer to the following checklist for the items to be checked once or twice every 6 months.

Che	cklist	Judgment basis	Actions
Power supply		Within the power variance range (less than –15% / +10%)	Adjust the power within the allowable voltage variance range.
I/O power		I/O specifications of each module	Adjust the power within the allowable voltage variance range.
	Temperature	0~+55℃	A direct the atomic countries and by weight a conditions properly
Environment	Humidity	5~95%RH	- Adjust the temperature and humidity conditions properly.
	Vibration	None	Use vibration-preventive rubber or other measures.
Shakes of module	es	Should not have shake	Every module should be protected from shaking.
Loose terminal so	rew	No looseness	Tighten any loose screw.
Spare parts		Check whether the amount and conditions of spare parts are proper	Replenish insufficient parts and improve the storage condition.

# 12.2 Routine Inspection

The following items should be routinely inspected.

Checklist Check point		Judgment basis	Actions	
Attachment o	f the base	Check any loose screw	Screws should be firmly tightened.	Tightening
Attachment o	f I/O module	Check the screws are firmly tightened     Check any separation of module cover	Should be firmly tightened.	Check screw
		Loosen screw	No looseness	Tightening
Attachment or expansion ca	f terminal strip and ble	Proximity with clamped terminal	Proper spacing	Calibration
o pariolo roadio		Connector of expansion cable	Connector should be tightened	Calibration
	PowerLED	Check whether it is LED ON	LED On (off is error)	
	RUNLED	Check whether it is LED ON in RUN state	LED On (off or blinking is error)	
Display	STOP LED	Check whether it is LED Off in RUN state	Blinking is error	Please refer to
LED In	Input LED	Check whether LED On or Off	LED On with input ON and LED Off with input off	chapter 14.2
Output LED Check whether LED C		Check whether LED On or Off	LED On with output ON and LED Off with output off	

## **Chapter 12. Maintenance**

# 12.3 Periodic Inspection

Please take a measure by checking the following items once or twice every 6 months.

Checklist		Check method	Judgment basis	Actions
	Temperature	Measure by	0~55°C	Adjusting according to the general spec.(the environment in panel)
Environment	Humidity	thermometer/hygrometer	5~95%RH	
	Contamination level	Measure corrosive gas	Free of corrosive gas	
PLC status	Looseness/shake	Try to move each module	Should be firmly attached	Tightening
1 LO Sidios	Built-in dust/impurities	Visual inspection	No built-in dust/impurities	-
	Looseness	Tightening with a screwdriver	No loosened screws	Tightening
Connection status	Proximate of clamped terminal	Visual inspection	Proper spacing	Calibration
	Loosened connector	Visual inspection	No looseness	Tightening connector screws
Check power voltage		Check the voltage of input terminal by using a tester	AC100~240V:AC85~ 264V DC24V:DC19.2 ~ 28.8V	Change the power supplied
Battery		Check the battery replacement timing and voltage drop	Check the total interruption time and warranty period     No battery voltage drop display	A battery should be replaced if it passes the warranty period despite of no display
Fuse		Visual inspection	• No fusing	Regularly replace it because element may be deteriorated by inrush current.

# **Chapter. 13 EMC Compliance**

## 13.1 Requirements Complying with EMC Specifications

EMC Directions describe "Do not emit strong electromagnetic wave to the outside: Emission" and "Do not have an influence of electromagnetic wave from the outside: Immunity", and the applicable products are requested to meet the directions. The chapter summarizes how to structure a system using XGT PLC to comply with the EMC directions. The description is the data summarized for the requirements and specifications of EMC regulation acquired by the company but it does not mean that every system manufactured according to the description meets the following specifications. The method and determination to comply with the EMC directions should be finally determined by the system manufacturer self.

#### 13.1.1 EMC specifications

The EMC specifications affecting the PLC are as follows.

**Table 13-1** 

Specification	Test items	Test details	Standard value
	EN55011 Radiated noise * 2	Measure the wave emitted from a product.	30~230 MHz QP: 50 dB \( \mu \rangle /m \) * 1 230~1000 MHz QP: 57 dB \( \mu \rangle /m \rangle \)
EN50081-2	EN55011 conducted noise	Measure the noise that a product emits to the power line.	150~500 kHz QP : 79 dB Mean : 66 dB 500~230 MHz QP : 73 dB Mean : 60 dB
	EN61000-4- Electrostatic immunity	Immunity test allowing static electricity to the case of a device.	15 kV Air discharge 8 kV Contact discharge
ENGLISH O	EN61000-4-4 Fast transient burst noise	Immunity test allowing a fast noise to power cable and signal cable.	Power line : 2 kV Digital I/O : 1 kV Analogue I/O, signal lines : 1 kV
EN61131-2	EN61000-4-3 Radiated field AM modulation	Immunity test injecting electric field to a product.	10Vm, 26~1000 MHz 80% AM modulation@ 1 kHz
	EN61000-4-12 Damped oscillatory wave immunity	Immunity test allowing attenuation vibration wave to power cable.	Power line : 1 kV Digital I/O(24V and higher) : 1 kV

<sup>\* 1 :</sup> QP: Quasi Peak, Mean : average value

<sup>\* 2 :</sup> PLC is a type of open device(installed on another device) and to be installed in a panel. For any applicable tests, the system is tested with the system installed in a panel.

#### 13.1.2 Panel

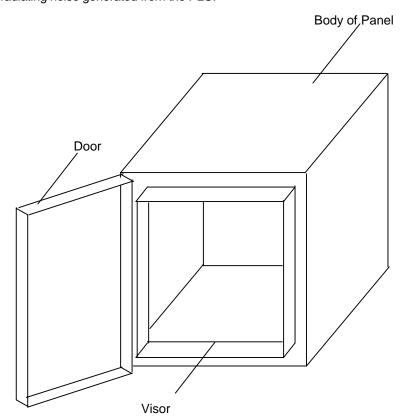
The PLC is a kind of open device(installed on another device) and it should be installed in a panel. It is because the installation may prevent a person from suffering from an accident due to electric shock as the person contacts with the product(XGT PLC) and the panel can attenuates the noise generating from the PLC.

In case of XGT PLC, to restrict EMI emitted from a product, it should be installed in a metallic panel. The specifications of the metallic panel are as follows.

#### 1) Panel

The panel for PLC should be installed and manufactured as follows.

- (1) The panel should be made of SPCC(Cold Rolled Mild Steel)
- (2) The plate should be 1.6mm and thicker
- (3) The power supplied to the panel should be protected against surge by using insulated transformer.
- (4) The panel should be structured so that electric wave is not leaked outside. For instance, make the door as a box as presented below. The main frame should be also designed to be covered the door in order to restrict any radiating noise generated from the PLC.



(5) The inside plate of panel should have proper conductivity with a wide surface as possible by eliminating the plating of the bolt used to be mounted on the main frame in order to secure the electric contact with the frame.

#### 2) Power cable and grounding cable

The grounding/power cable of PLC should be treated as follows.

- (1) The panel should be grounded with a thick wire() to secure a lower impedance even in high frequency.
- (2) LG(Line Ground) terminal and FG(Frame Ground) terminal functionally let the noise inside the PLC flow into the ground, so a wire of which impedance is low should be used.
- (3) Since the grounding cable itself may generate noise, thick and short wiring may prevent it serving as an antenna.

#### 13.1.3 Cable

- 1) Expansion cables can be classified into optical and electrical cables according to the connector type.
  - (1) For the optical cables, use MMF(Multi Mode Fiber) 50/65um LC Type Cable. Use indoor type, outdoor type, or conduit type according to the installation site.



Fig. MMF(LC Type) cable

(2) For the electrical cables, communication can be done with 100Mbit Twisted Pair cables, however, since the data transmission in expansion cables is in tens of micro unit, external noise may affect system performance and control seriously.

Therefore, electrical cables used in XGR systems should, basically, be shielded twisted pair cables such as FTP, STP, or FSTP.

#### FTP Cable



Fig. FTP Cable

#### STP Cable



Fig. STP Cable

2) Fixing a cable in the panel

If the expansion cable of XGT series is to be installed on the metallic panel, the cable should be 1cm and more away from the panel, preventing the direct contact.

The metallic plate of panel may shield noise from electromagnetic wave while it a cable as a noise source is close to the place, it can serve as an antenna. Every fast signal cable as well as the expansion cable needs proper spacing from the panel

## 13.2 Requirements Complying with Low Voltage Direction

The low voltage direction requires a device that operates with AC50~1000V, DC 75 ~ 1500V to have proper safety. The followings summarize the cautions for installing and wiring PLC of the XGT series to comply with the low voltage directions. The description is the data based on the applicable requirements and specifications as far as we know but it does not mean that every system manufactured according to the description meets the following specifications. The method and determination to comply with the EMC directions should be finally determined by the system manufacturer self.

#### 13.2.1 Specifications applicable to XGT series

XGT series follow the EN6100-1(safety of the device used in measurement/control lab).

XGT series is developed in accordance with the above specifications, even for a module operating at the rated voltage higher than AC50V/DC75V.

#### 13.2.2 Selection of XGT series PLC

(1) Power module

The power module of which rated input voltage is AC110/220V may have dangerous voltage(higher than 42.4V peak) inside it, so any CE mark compliance product is insulated between the primary and the secondary.

(2) I/O module

The I/O module of which rated voltage is AC110/220V may have dangerous voltage(higher than 42.4V peak) inside it, so any CE mark compliance product is insulated between the primary and the secondary. The I/O module lower than DC24V is not applicable to the low voltage directions.

(3) CPU Module, Base unit

The modules use DC5V, 3.3V circuits, so they are not applicable to the low voltage directions.

(4) Special module, Communication module

The modules use the rated voltage less than DC 24V, so they are not applicable to the low voltage directions.

## **Chapter 14 Troubleshooting**

The chapter describes types of potential errors that occur while operating the system, causes of errors, how to detect them and corrective measures.

## 14.1 Basic Troubleshooting Procedure

To improve the reliability of a system, it is important to take a corrective measure promptly if a trouble occurs as well as to use highly reliable devices. To operate a system immediately, it is the most important to quickly detect potential causes of a trouble and take corrective measures. To troubleshoot the system correctly, make sure to take the following cautions and procedures.

#### 1) Check by visual inspection

Please check the followings visually.

- Operation status(Stop, Run)
- Power On/Off status
- I/O device status
- Wiring status(I/O wiring, expansion and communication cable)
- Check the status of each display(POWER LED, RUN/STOP LED, I/O LED and etc), connect to peripherals and check the operation condition and program

#### 2) Check any abnormality

Please observe how a fault changes by executing the followings.

• Move the key switch to STOP and turn it On/Off

#### 3) Restricting Range

Estimate by which factor a fault occurs by the following methods.

- Is it from the PLC or external factor?
- I/O module or others?
- · PLC program?

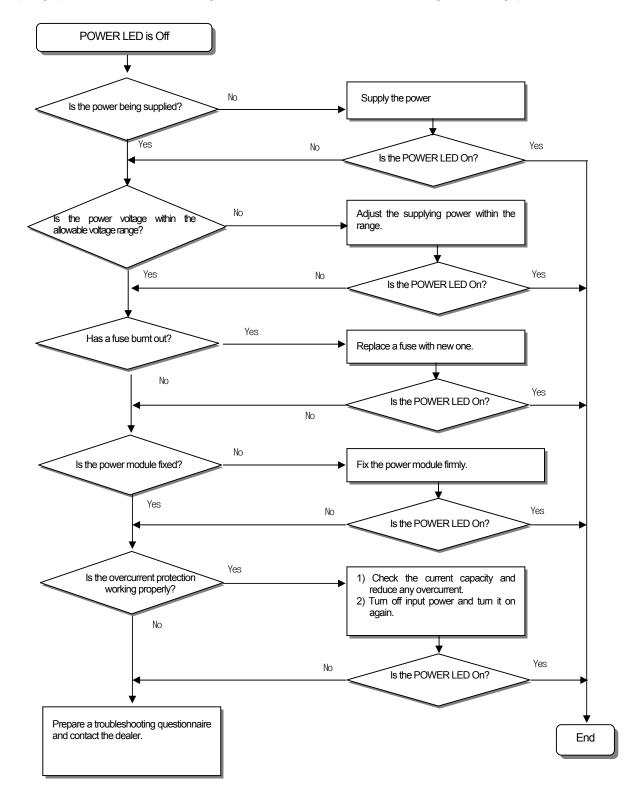
# 14.2 Troubleshooting

The above stated detection methods, description for error codes and measures are explained by phenomenon.

Trouble	
If Power LED is Off	Measures taken when Power LED is Off
If WAR. LED is On	Measures taken when WAR/ LED is On
If Err. LED is On	Measures taken when Error LED is On
If Run/Stop LED is Off	Measures taken when Run/Stop LED is Off
If I/O module does not work properly	Measures taken when I/O module does not work property
If writing a program is not possible	Measures taken when writing program is not possible
If Sync. cable is not properly installed	Measures taken when Sync. cable is not properly installed
If master switching occurs	Measures taken when master switching occurs
If redundant operation does not work when adding CPU	Measures taken when redundant operation does not work when adding CPU
If master switching fails	Measures taken when master switching fails

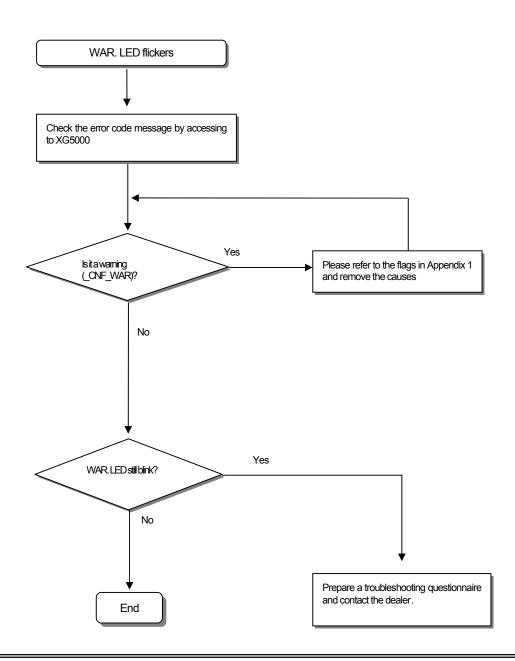
#### 14.2.1 Action when POWER LED is off

The paragraph describes the orders of taking a measure if POWER LED is Off when turning it on or during operation.



#### 14.2.2 Action when WAR. (Warning) LED is on.

The paragraph describes the orders of taking a measure if WAR.. LED is On when turning it on, starting operation or operating.



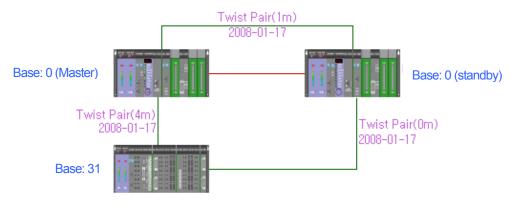
# /! Caution

If warning error occurs, the PLC system does not stop but it is necessary to check the error message and take a corrective measure. Or it may cause an error.

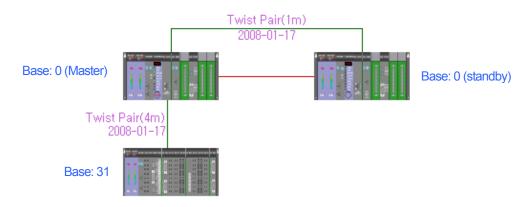
It describes measure when WAR LED is on because redundant system runs in single or configured b Line mode. Connecti XG5000 and execitue [Monitor]-[System Monitor] and select [PLC]-[System Configuration] to check.



[Figure 14.2.1] System configuration menu

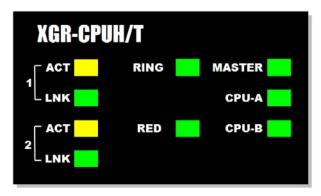


[Figure 14.2.2] system configuration (in case of Ring configuration)

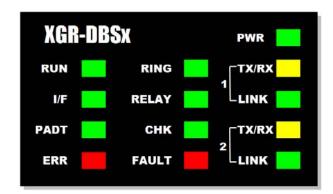


[Figure 14.2.3] System configuration (in case of line configuration)

In case system is configured as ring, basic base and expansion base is displayed by ring like [Figure 14.2.2]. In case system is configured as line, disconnection between bases is displayed like [Figure 14.2.3]. This can be checked by LED. In case system starts with line topology, RING LED turns off. In case it starts with ring topology and it changes the topology to line, RING LED flickers



[Figure 14.2.4] CPU module LED

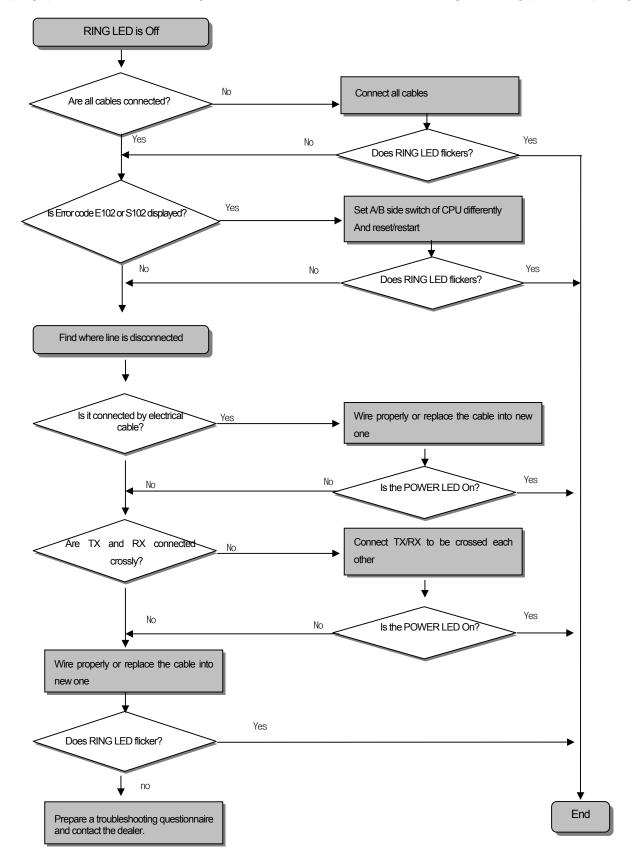


[Figure 14.2.5] Expansion drive LED



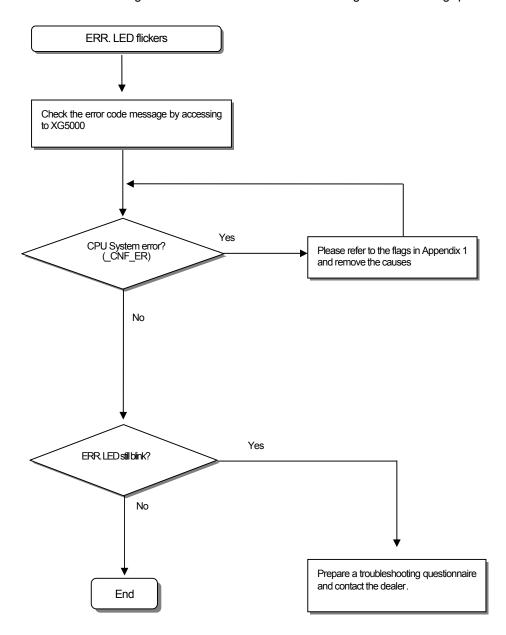
Since optical cable consists of two couples unlike electrical cable, TX and RX can be changed in case of installation. Make sure that direction of TX and RX does not change. (TX should be connected with RX, and RX with TX.)

The paragraph describes the orders of taking a measure if RING LED is off or flickers when turning it on, starting operation or operating.



#### 14.2.3 Action when ERR. LED is on

The paragraph describes the orders of taking a measure if ERR. LED flickers when turning PLC on or starting operation

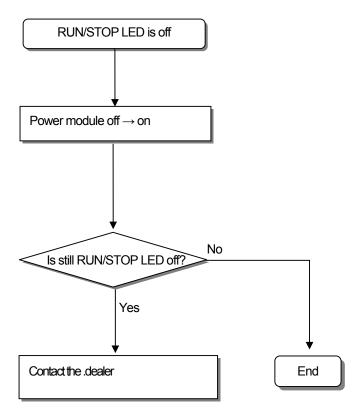


# /! Caution

If warning error occurs, the PLC system does not stop but it is necessary to check the error message and take a corrective measure. Or it may cause an error.

#### 14.2.4 Action when RUN/STOP LED is off

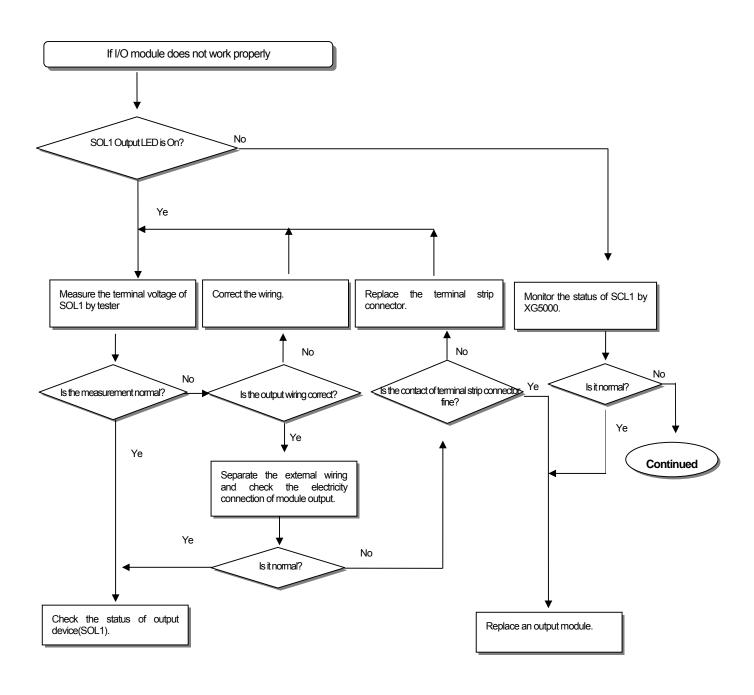
The paragraph describes the orders of taking a measure if RUN/STOP LED is Off when turning it on, starting operation or operating.

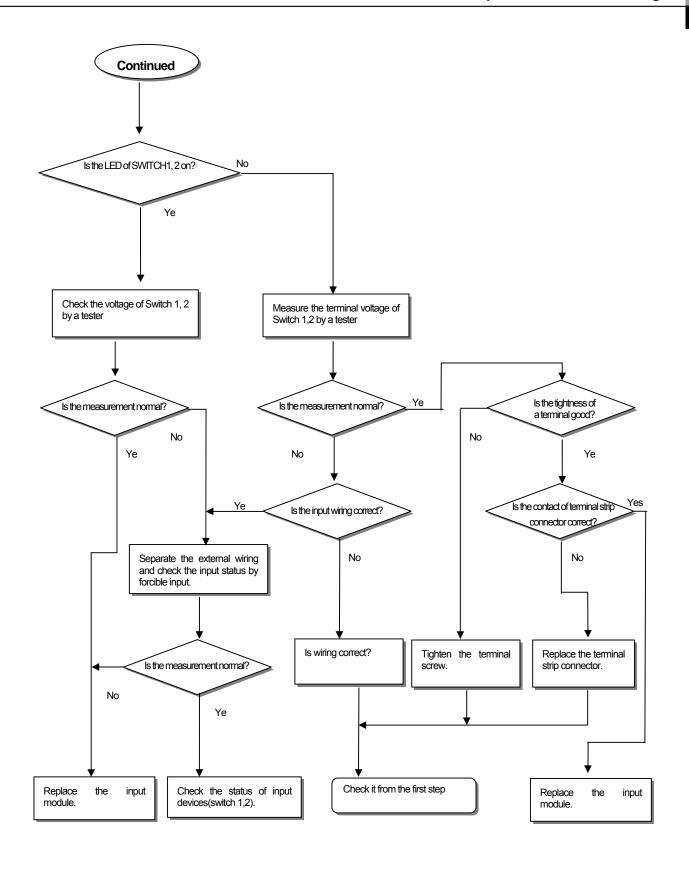


#### 14.2.5 Acton when I/O module does not work properly

For the orders of taking measures when I/O module does not properly work during operation, the paragraph explains it with the following illustration.

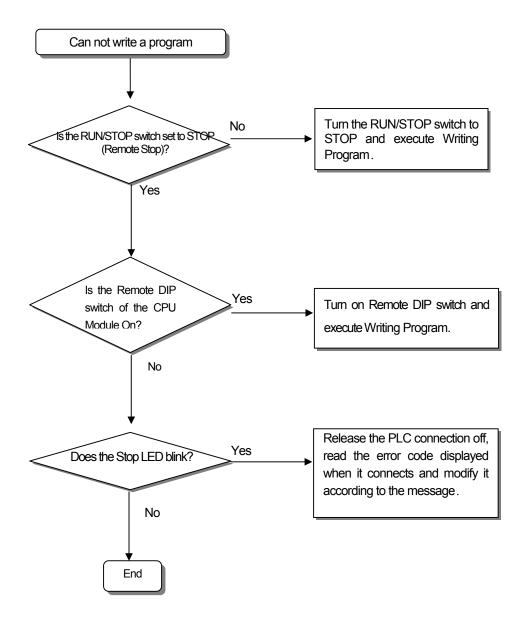






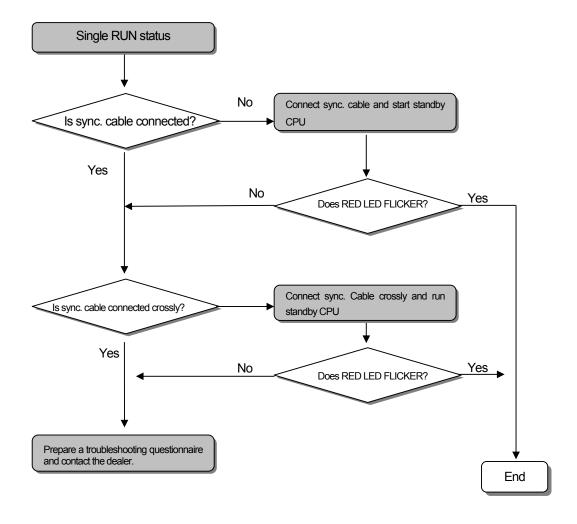
#### 14.2.6 Action when writing program is not possible

It describes the orders of taking a measure when writing a program into the CPU Module is not possible.



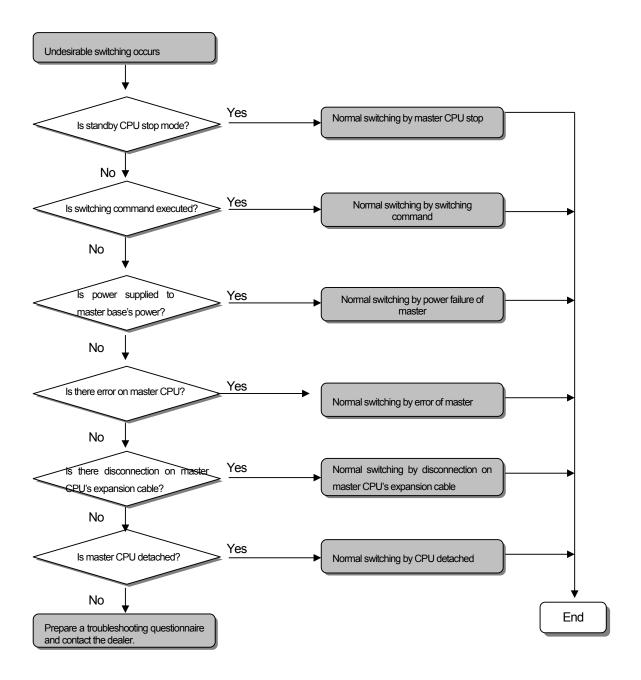
## 14.2.7 Action when Sync. cable is not installed properly

If there is a problem in Sync. Cable, redundant operation is not possible. It describes action when Sync. Cable is not installed properly.



#### 14.2.8 When undesirable master switching occurs

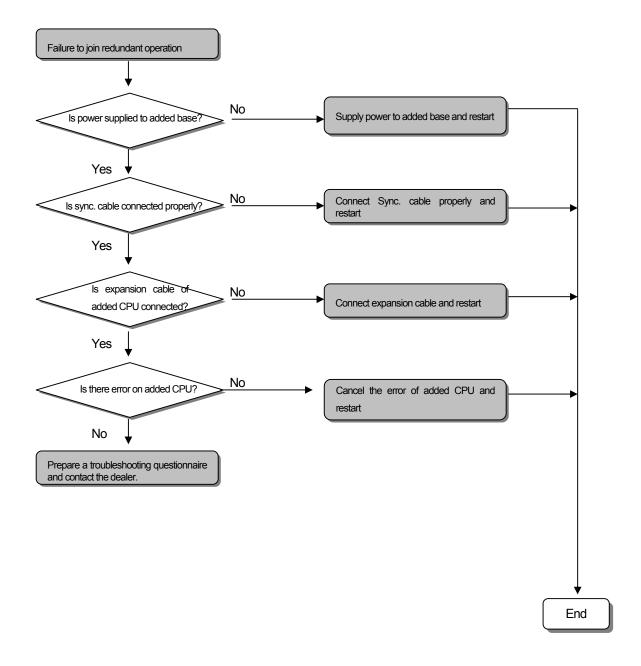
In case switching occurs, it is displayed by MASTER LED at front part. If the revelent is acting as master, MASTER LED is on and if it is acting as standby CPU, MASTER LED off. It switching the user does not want occurs, see the following steps.



#### 14.2.9 When newly added CPU does not join redundant operation

In case of adding new CPU to the previous system, it should act as standby CPU if normal. Before starting, check the Sync. Cable and expansion cable. To join reduntdunt operation, version of new CPU should be same with previous CPU. If not, error occurs because of version. Contact near dealer and get update of new OS.

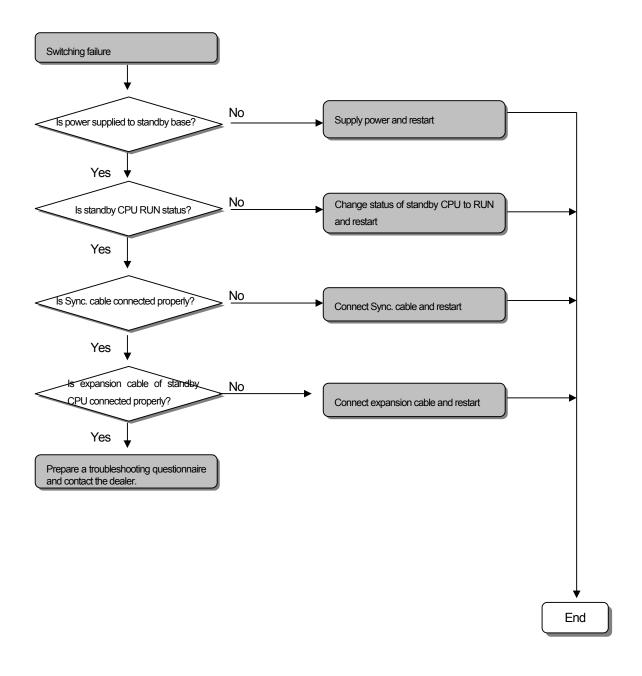
If you have a problem when adding new CPU, see the following steps.



#### 14.2.10 When failing to switch master

If system is not redunduncy status, switching may fail. Before switching, check the redundant ring configuration, RUN status of master/standby CPU, connection status of Sync. Cable.

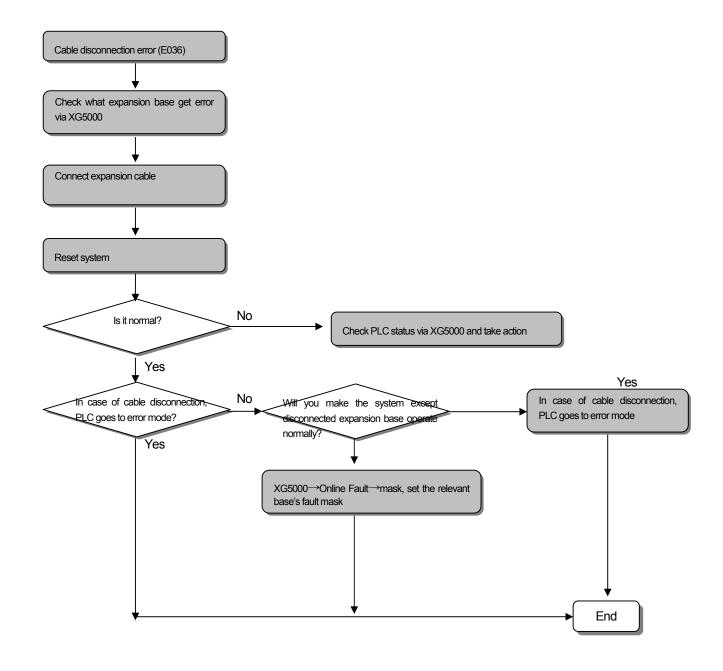
In case you try to switch but fail, see the following steps.



#### 14.2.11 When expansion cable is disconnected

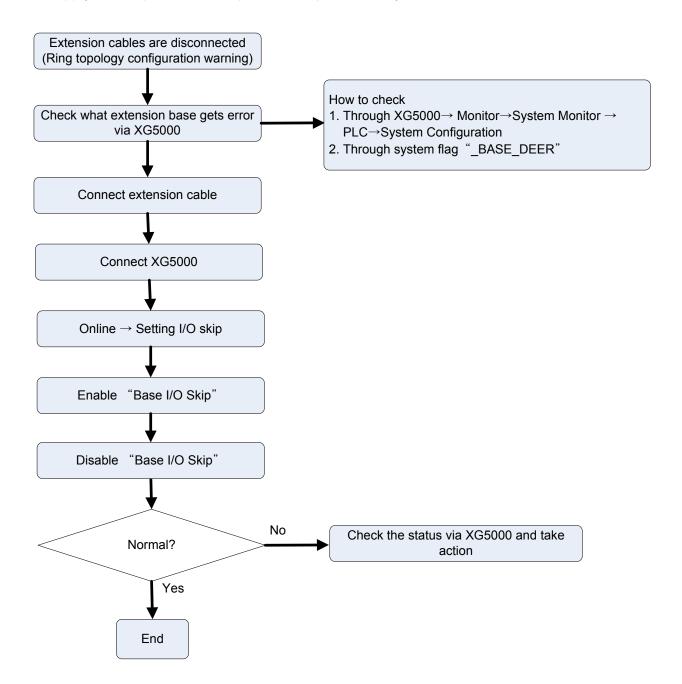
In case two expansion cables are disconnected, cable disconnection error occurs or system except disconnected expansion base operates normally.

(1) Cable disconnection error(E036) : In case fault mask is not set  $\rightarrow$ 



## **Chapter 14 Troubleshooting**

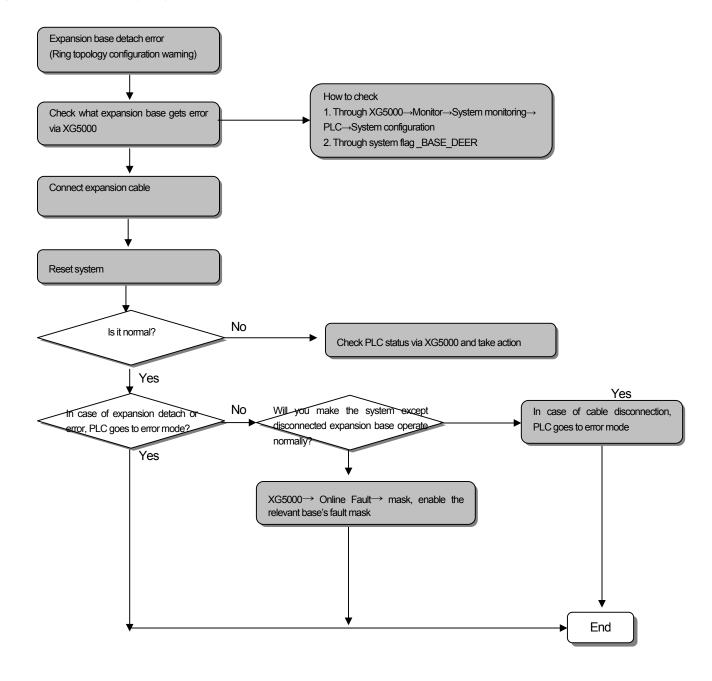
(2) system except disconnected expansion base operates normally: in case fault mask is set



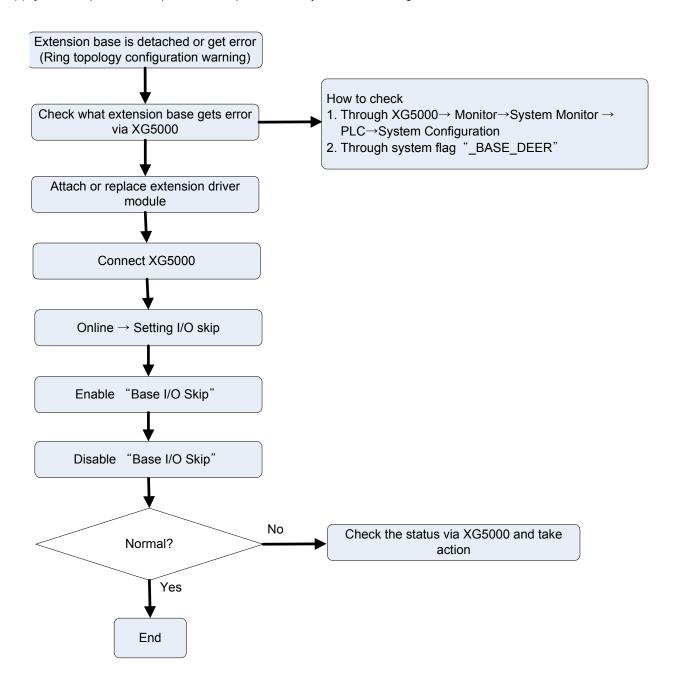
#### 14.2.12 When expansion driver gets error

In case expansion driver is detached (or get error), cable disconnection error occurs or system except disconnected expansion base operates normally.

(1) Expansion base detach error (E036): In case fault mask is not set



(2) system except detached expansion base operates normally: in case of enabling fault mask



# 14.3 Troubleshooting Questionnaires

If any trouble is found while using the XGI series, please fill out the form and call to fax it to us.

• For an error relating to special/communication modules, fill out the questionnaires attached in the user's manual of the product.

1. Customer's Contact Number:	TEL)	
	FAX)	
2. Model:	( )	
3. Details of the Product		
– Details of the CPU module :	- OS version ( ), - Product's serial number ( )	)
- XG5000 Version number used fo	or program compiling:( )	
4. Brief description of a device and syste	em:	
5. Modules using the CPU module:		
<ul><li>Operation by key switch (</li></ul>	), — Operation by XG5000 or Communication (	
<ul> <li>– Memory module operation (</li> </ul>	)	
6. STOP LED On of the CPU module?	Yes( ), No( )	
7. Error message generated from the X	G5000:	
8. Measures taken against the error cod	de in the above 7 :	
9. Other troubleshooting measures again	inst the error:	
10. Features of the error		
• Reiterative( ): Periodic(	), Relating to a specific sequence level( )	
Relating to the environment(	)	
• Intermittent( ): Approx. inter	val of the error occurrence:	
11. Detail description for the erroneous p	phenomena:	
12. Configuration of the applied system	:	

# 14.4 Cases

It describes trouble types and measures for circuits.

## 14.4.1 Trouble types and measures of input circuit

The followings describe the examples and measures of troubles.

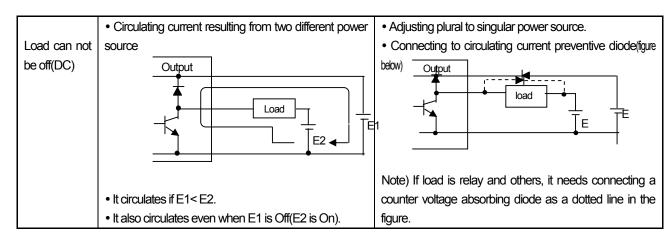
Phenomena	Causes	Measures
	Leakage current of an external device	Connect a proper resistance or capacitor so that
Input signal can	(if operating by proximate switch and others)	the voltage between terminals of input module is
not be off		below the return voltage.
	AC input	
	Leakage current	AC input
	Fytomal double	
	External device	
	Leakage current of an external device(operation by	
Input signal can	a limit switch with neon lamp)	CR value is determined by the value of leakage
not be off(neon lamp could be	AC input	current.
still on)	Leakage	- Recommended value C: 0.1 ~ 0.47uF
Suii Oi i)	R current	R:47~120Ω(1/2W)
	External devices	Or, separate a circuit completely and install another
	External device	display circuit.
	leakage current from the capacity between wires of	Install the power on an external device as
Input signal can	wiring cable	presented below.
not be off	AC input	AC Input
	Leakage	
	current	
	External device	External device
	Leakage current of an external device(operation by	Connect a proper resistance so that the voltage
Input signal can	a switch with LED mark)	between input module terminal and common
not be off	,	terminal is higher than off voltage as presented
	DC input	below.
	Leakage	DC Input
	R current	
	External device	E1
	0.1.	
Input piggal age	Circulating current by using plural different power	Change plural to singular power     Connecting to a circulating gurrent proventive.
Input signal can not be off	sources DC Input	Connecting to a circulating current preventive diode/figure below)
HOLDE OII		
		DC Input
	-   -   -   -   -   -   -   -   -   -	† †
	• If E1 > E2, it circulates.	

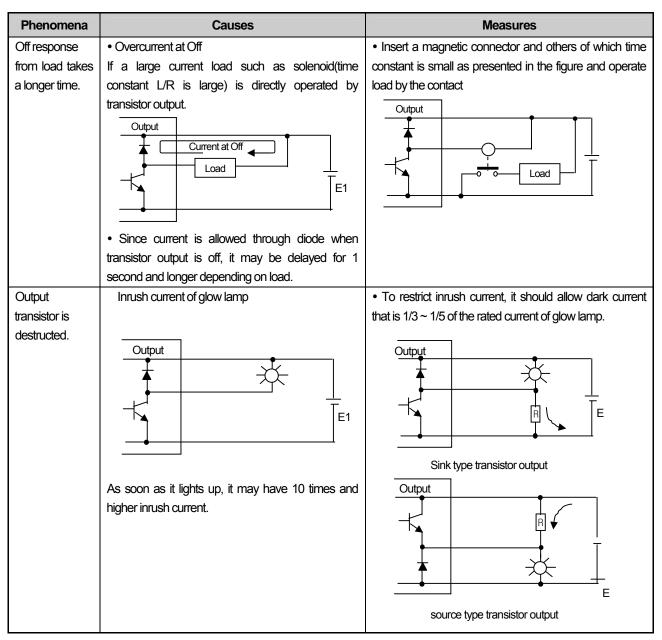
## 14.4.2 Trouble types and measures of output circuit

The followings describe the examples and measures of troubles.

Phenomena	Causes	Measures
	If load contains half-wave rectification(solenoid valve	• Connect a dozens ~ several hundreds $k\Omega$ resistor to a
Excessive	may have it)	load in parallel.
voltage is	• If the polarity is $\leftarrow$ , C is charged while the voltage +	
allowed to	power voltage charged to C is allowed to both ends of	
load when	diode(D). when the polarity is ↑. The max. voltage is	R
output	approx. 2√2 . —	
contact is off	C   D   C   C   C   C   C   C   C   C	Load
	Note) when using it as the above, the output element	
	does not have any problem but the performance of	
	diode(D) in load may be reduced, probably causing a	
	trouble.	
	Leakage current from surge absorbing circuit	• Connect a dozens of $k\Omega$ resistor or CR of which
Load can not	connected to an output element in parallel	impedance is equal to the resistance to load in parallel.
be off	Output	Note) If the length of wiring from output module to load is
	Load	long, it may have leakage current from capacity of
	Leakage current	cables.
	·	Load
	Leakage current from surge absorbing circuit	Operate the C-R type timer by mediating a relay.
Abnormal	connected to an output element in parallel.	Use other one but a C–R type timer.
time when	Output	Note) A timer's internal circuit may have half-wave
load is a C-R	Load	rectification
type timer	Ţ ţ į	
	Leakage current	Output

## **Chapter 14 Troubleshooting**





# 14.5 Error Codes List

## 14.5.1 Error codes during CPU operation

Code	Error causes	Measures	Operation status	LED status	Diagnostic timing			
13	Abnormal base information	Contact A/S service if it still exists after turning it on again	Turning it on Converting to RUN mode					
23	If a program to execute is not normal	Operate after program is reloaded (Cold) Replace a battery in case of abnormal battery (Cold) After a program is reloaded, check the storage condition and if any fault is found, replace the CPU module. (Cold)	leplace a battery in case of abnormal battery (Cold)  fiter a program is reloaded, check the storage condition  STOP  E023					
24	Abnormal I/O parameter	Check I/O parameter and the installed module Set I/O parameter to be same with installed module and download	heck I/O parameter and the installed module et I/O parameter to be same with installed module and STOP E024					
25	Abnormal basic parameter	Restart after basic parameter is reloaded Replace a battery in case of defective battery After basic parameter is reloaded, check the storage condition and if any fault is found, replace the CPU module.	Converting to RUN mode					
28	Abnormal Redundancy parameter	Start after loading redundancy parameter again (Doesn't check in case of downloading during Run)	E028	Turning it on, Loading program				
29	Abnormal special parameter	Start after loading special parameter again (Doesn't check in case of downloading during Run)	STOP	E029	Tuming it on, Loading program			
30	The module set in parameter and the actually installed module do not coincide	Check the wrong slot position by XG5000, modify a module or parameter and then, restart.  Reference flag: module type inconsistence error flag  (_IO_TYER, _IO_TYER_N, _IO_TYERR[n])	parameter and then, restart.  STOP, eference flag: module type inconsistence error flag  RUN					
31	Module detachment or module addition during operation	Check any detached/added slot position by XG5000, modify the installment and restart(according to parameter)  Reference flag: module detachment error flag  (_IO_DEER,_IO_DEER_N,_IO_DEERR[n])	scan ends					
32	Fuse of a module holding a fuse is burnt out during operation	Check the position of a slot of which fuse is burnt out by XG5000, replace a fuse and restart(according to parameter)  Reference flag: fuse disconnection error flag  (_FUSE_ER,_FUSE_ER_N,_FUSE_ERR[n])	STOP, RUN	E032	scan ends			

# **Chapter 14 Troubleshooting**

Code	Error causes	Measures(restart mode after the measure)	Operation status	LED status	Diagnostic timing	
36	Expansion base detach error	Check the detachment of expansion base	turning it on, Scan end, Executing program			
39	CPU abnormal end or trouble	Contact A/S service if it still exists after turning it on again	turning it on, Scan end, Executing program			
40	The scan time of a program exceeds the scan delay watchdog time designated by parameter during operation	Check the scan delay watchdog time designated by parameter, modify parameter or program and restart (cold)	I SIOP I			
41	Program execution code error	Download program again and restart	STOP	E041	tuming it on,	
43	Duplicated base number	Check the duplicated base number	E043	Executing program		
45	Base power error	Two power module are off Check attachment of power module	turning it on,			
48	Module position error	Module that can't be installed has bee installed For more detail, refer to error history	STOP RUN	E048	turning it on, Loading program Switching to RUN mode	
50	Error of external device is detected by a user program during operation	Repair a fault device by referring to error detection flag of external device and restart(according to parameter)  (_ANNUN_ER,_ANC_ERR[n])	STOP RUN	E050	When scan ends	
101	CPU position error	CPU is installed at wrong position Position CPU correctly	STOP	S101	turning it on,	
102	Duplicated CPU ID error	Set the A/B side switches of Master CPU and Standby CPU differently	STOP	S102	turning it on,	
103	Base abnormal error	Configure expansion cable as Ring Topology and position detached base correctly.  For information of detached base, refer to CPU error log	STOP, RUN	E103	Executing program	
300	Redundancy system synchronous operating error	During redundancy operating, synchronization error occurs	STOP	E300	Switching to redundancy operation, operating	

Code	Error causes	Measures(restart mode after the measure)	Operation status	LED status	Diagnostic timing
301	Standby CPU failed to operate as redundancy because of error of Master CPU	Restart as redundancy operation  • set operation mode of standby CPU as STOP  • Cancel the error of master CPU and restart  • Change standby CPU into RUN  Restart standby CPU as single operation  • Disable master CPU (STOP mode or power cut)  • restart standby CPU through reset switch or changing operation mode from STOP to RUN	STOP	E301	Starting standby operation
501	RTC data error	If there is no error in battery, reset RTC data via XG5000	RUN E501		turning it on, scan end
502	Low battery voltage	Replace battery while power in on RUN		E502	turning it on, scan end
bxx	Expansion base error	Check the power of expansion base  Check the expansion cable	RUN	Ebxx	Operating

## Note

- 1) Error No. 2 through 13 from "Error Codes during CPU Operation" can be checked in our A/S Service Center.
- 2) The other errors of which number is 22 and lower can be checked by using the error log of XG5000.

# Appendix 1 Flag list

# Appendix 1.1 User Flag

1. User flag

Address	Flag name	Туре	Writable	Contents	Description	
%FX6144	_T20MS	BOOL	-	20ms cycle clock	Clock signal used in user program reverses On/Off per a half cycle	
%FX6145	_T100MS	BOOL	-	100ms cycle clock	Please use more enough long clock signal than PLC scan time.	
%FX6146	_T200MS	BOOL	-	200ms cycle clock	Clock signal starts from Off condition when initialization program starts or scan program starts.	
%FX6147	_T1S	BOOL	-	1s cycle clock	_T100ms clock example	
%FX6148	_T2S	BOOL	-	2s cycle clock	50ms 50ms	
%FX6149	_T10S	BOOL	-	10s cycle clock		
%FX6150	_T20S	BOOL	-	20s cycle clock		
%FX6151	_T60S	BOOL	-	60s cycle clock		
%FX6153	_ON	BOOL	-	Ordinary time On	Always On state flag, used when writing user program.	
%FX6154	_OFF	BOOL	-	Ordinary time Off	Always Off state flag, used when writing user program.	
%FX6155	_1ON	BOOL	-	1'st scan On	Only 1'st scan On after operation start	
%FX6156	_10FF	BOOL	-	1'st scan Off	Only 1'st scan Off after operation start	
%FX6157	_STOG	BOOL	-	Reversal every scan (scan toggle)	On/Off reversed flag per every scan when user program is working. (On state for first scan)	
%FX6163	_ALL_OFF	BOOL	-	All output Off	On in case all outputs are off	
%FX30720	_RTC_WR	BOOL	Available	Writing data to RTC	Write data to RTC and Read	
%FX30721	_SCAN_WR	BOOL	Available	Initialize scan value	Initialize scan value	
%FX30722	_CHK_ANC_ERR	BOOL	Available	Request for detecting heavy fault of external device	Flag that requests detecting heavy fault of external	
%FX30723	_CHK_ANC_WAR	BOOL	Available	Request for detecting light fault of external device	Flag that requests detecting light fault (warning) of external	
%FX30724	_MASTER_CHG	BOOL	Available	Master/Standby switching	Flag used when switching master/standby	
%FW3860	_RTC_TIME_USER	ARRAY[07] OF BYTE	Available	Time to set	Flag for user to set time (year, month, hour, minute, second, day, century available)	

# **Appendix 1.2 System Error Representative Flag**

1. Master CPU system error representative flag

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Address	Flag name	Туре	Bit position	Contents	Description
%FD65	_CNF_ER	DWOR D	Represent ative flag	System error (heavy fault error)	Handles error flags about non-operation fault error as below.
%FX2081	_IO_TYER	BOOL	BIT 1	Error when Module type mismatched  Representative flag displayed when I/O configuration parameter for each slot is not ma practical module configuration or a specific module in the wrong location.  (Refer to "_IO_TYER_N, _IO_TYER[n]")	
%FX2082	_IO_DEER	BOOL	BIT 2	Module detachment error	Representative flag displayed when the module configuration for each slot is changed while running.  (Refer to "_IO_DEER_N, _IO_DEER[n]")
%FX2083	_FUSE_ER	BOOL	BIT 3	Fuse cutoff error	Representative flag displayed when the fuse of module is cut off.  (Refer to "_FUSE_ER_N, _FUSE_ER[n]")
%FX2086	_ANNUM_ER	BOOL	BIT 6	Heavy fault detection error in external device	Representative flag displayed when heavy fault error detected by user program is recorded in "_ANC_ERR[n]".
%FX2088	_BPRM_ER	BOOL	BIT 8	Basic parameter error	Basic parameter doesn't match CPU type.
%FX2089	_IOPRM_ER	BOOL	BIT 9	I/O parameter error	It is abnormal to the I/O configuration parameter.
%FX2090	_SPPRM_ER	BOOL	BIT 10	Special module parameter error	It is abnormal to the special module parameter.
%FX2091	_CPPRM_ER	BOOL	BIT 11	Communication module parameter error	It is abnormal to the communication module parameter.
%FX2092	_PGM_ER	BOOL	BIT 12	Program error	Indicates that there is problem with user-made program.
%FX2093	_CODE_ER	BOOL	BIT 13	Program code error	Indicates that while user program is running, the program code can't be interpreted.
%FX2094	_SWDT_ER	BOOL	BIT 14	CPU abnormal ends.	Displayed when the saved program gets damages by an abnormal end of CPU or program cannot work.
%FX2095	_BASE_POWE	BOOL	BIT 15	Abnormal base power	Base power off or power module error
%FX2096	_WDT_ER	BOOL	BIT 16	Scan watchdog error	Indicates that the program scan time exceeds the scan watchdog time specified by a parameter.
%FX2097	_BASE_INFO_E R	BOOL	BIT 17	Base information error	Base information is abnormal
%FX2102	_BASE_DEER	BOOL	BIT 22	Extension base detachment error	Extension base is detatched
%FX2103	_DUPL_PRM_E R	BOOL	BIT 23	Redundant parameter error	Abnormal Redundant parameter
%FX2104	_INSTALL_ER	BOOL	BIT 24	Module attachment position error	The module which can't be inserted into main base is inserted in to main base or The module which can't be inserted into extension base is inserted in to extension base

Address	Flag name	Туре	Bit position	Contents	Description	
%FX2105	_BASE_ID_ER	BOOL	BIT 25	Overlapped extension base number	extension base number is overlapped	
%FX2106	_DUPL_SYNC_ ER	BOOL	BIT 26	Redundant operation Sync. error	Synchronization between master and standby CPU in abnormal	
%FX2107	_AB_SIDEKEY_ ER	BOOL	BIT 27	A/B SIDE key overlap error	A,B side key of master, standby CPU are overlapped. They should be different.	
%FX2110	_BASE_AB_ER	BOOL	BIT 30	Base abnormal configuration	Configure extension cable as Ring Topology and position detached base correctly.  For information of detached base, refer to CPU error log	

2. Standby CPU System error representative flag

Address	Flag name	Туре	Bit position	Contents	Description
%FD129	_SB_CNF_ER	DWOR D	Represent ative flag	System error (heavy fault error)	Handles error flags about non-operation fault error as below.
%FX4129	_SB_IO_TYER	BOOL	BIT 1	Module type mismatch error	Attached module is different with I/O parameter or some module which can't be inserted into some slot is inserted some slot. Representative flag that detects them and displays (refer to _SB_IO_TYER_N, _SB_IO_TYERR)
%FX4130	_SB_IO_DEER	BOOL	BIT 2	Module detachment error	Representative flag displayed when the module configuration for each slot is changed while running.  (refer to _SB_IO_DEER_N,_SB_IO_DEERR]
%FX4131	_SB_FUSE_ER	BOOL	BIT 3	Fuse cutoff error	Representative flag displayed when the fuse of module is cut off.
%FX4134	_SB_ANNUM_ER	BOOL	BIT 6	Heavy fault detection error in external device	Representative flag displayed when heavy fault error detected by user program is recorded in "_ANC_ERR[n]".
%FX4136	_SB_BPRM_ER	BOOL	BIT 8	Basic parameter error	Basic parameter doesn't match CPU type.
%FX4137	_SB_IOPRM_ER	BOOL	BIT 9	I/O parameter error	It is abnormal to the I/O configuration parameter
%FX4138	_SB_SPPRM_ER	BOOL	BIT 10	Special module parameter error	It is abnormal to the special module parameter.
%FX4139	_SB_CPPRM_ER	BOOL	BIT 11	Communication module parameter error	It is abnormal to the communication module parameter.
%FX4141	_SB_CODE_ER	BOOL	BIT 13	Program code error	Indicates that while user program is running, the program code can't be interpreted.
%FX4142	_SB_SWDT_ER	BOOL	BIT 14	CPU abnormal ends.	Displayed when the saved program gets damages by an abnormal end of CPU or program cannot work.
%FX4143	_SB_BASE_POW ER_ER	BOOL	BIT 15	Abnormal base power	Base power off or power module error
%FX4144	_SB_WDT_ER	BOOL	BIT 16	Scan watchdog error	Indicates that the program scan time exceeds the scan watchdog time specified by a parameter.

## **Appendix 1 Flag List**

Address	Flag name	Туре	Bit position	Contents	Description
%FX4145	_SB_BASE_INFO _ER	BOOL	BIT 17	Base information error	Base information is abnormal
%FX4150	_SB_BASE_DEE	BOOL	BIT 22	Extension base detachment error	Extension base is detached.
%FX4151	_SB_DUPL_PRM _ER	BOOL	BIT 23	Abnormal redundant parameter	Redundant parameter is Abnormal
%FX4152	_SB_INSTALL_E R	BOOL	BIT 24	Module attachment position error	The module which can't be inserted into main base is inserted in to main base or The module which can't be inserted into extension base is inserted in to extension base
%FX4153	_SB_BASE_ID_E R	BOOL	BIT 25	Overlapped extension base number	extension base number is overlapped
%FX4154	_SB_DUPL_SYN C_ER	BOOL	BIT 26	Redundant operation Sync. error	Synchronization between master and standby CPU is abnormal
%FX4156	_SB_CPU_RUN_ ER	BOOL	BIT 28	Standby CPU run error	Standby CPU fails to join redundant operation when MASTER CPU is error
%FX4158	_SB_BASE_AB_E R	BOOL	BIT 30	Base abnormal configuration	Configure extension cable as Ring Topology and position detached base correctly.  For information of detached base, refer to CPU error log

# **Appendix 1.3 System Error Detail Flag**

1. Master CPU system error detail flag

Address	Flag name	Туре	Writable	Contents	Description
%FW424	_IO_TYERR	ARRAY[031] OF WORD	1	Module type mismatch error	Indicates slot and base where module mismatch error occurs
%FW456	_IO_DEERR	ARRAY[031] OF WORD	1	Module detachment error	Indicates slot and base where module detachment error occurs
%FW488	_FUSE_ERR	ARRAY[031] OF WORD	ı	Fuse cutoff error	Indicates slot and base where fuse cutoff error occurs
%FD83	_BASE_DEERR	DWORD	1	Extension base detachment error	Indicates base where extension base is detached
%FD574	_BASE_POWER	DWORD	-	Information of base where power module error occurs	Indicates base where power module error occurs
%FW416	_IO_TYER_N	WORD	-	Module type mismatch slot number	Indicates slot number where module type mismatch error occurs. When two or more occurs, first slot is indicated

# Appendix 1 Flag List

Address	Flag name	Туре	Writable	Contents	Description
%FW417	_IO_DEER_N	WORD	-	Module detachment slot number	Indicates slot number where module detachment error occurs. When two or more occurs, first slot is indicated
%FW418	_FUSE_ER_N	WORD	-	Fuse cutoff slot number	Indicates slot number Fuse cutoff error occurs. When two or more occurs, first slot is indicated
%FW1922	_ANC_ERR	WORD	Available	Heavy fault information of external device	Classifies the type of user defined error and writes value except 0. If detection of heavy fault is requested, it develops an external heavy fault detection error. By monitoring this flag, the user can know a reason of heavy fault.
%FX10849	_IO_ER_PMT	BOOL	-	Status of Ignoring IO module error	On when set to ignore IO module error
%FX10851	_CP_ER_PMT	BOOL	-	Status of Ignoring communication module error	On when set to ignore communication module error
%FX10850	_SP_ER_PMT	BOOL	-	Status of Ignoring special module error	On when set to ignore special module error
%FX10848	_FUSE_ER_PMT	BOOL	-	Status of Ignoring fuse error	On when set to ignore fuse module error

## 2. Standby CPU system error detail flag

Address	Flag name	Туре	Writable	Contents	Description
%FD147	_SB_BASE_DEERR	DWORD	-	Extension base detachment error	Indicates base where extension base is detached
%FW588	_SB_IO_TYERR	WORD	-	Module type mismatch error	Indicates slot and base where module mismatch error occurs
%FW589	_SB_IO_DEERR	WORD	-	Module detachment error	Indicates slot and base where module detachment error occurs

# **Appendix 1.4 System Warning Representative Flag**

1. MASTER CPU System warning representative flag

Address	Flag name	Туре	Bit position	Contents	Description
%FD66	_CNF_WAR	DWORD	Representative flag	System warning	Representative flag displayed the system warning state
%FX2112	_RTC_ER	BOOL	BIT 0	RTC error	Indicates that RTC data is abnormal
%FX2114	_BASE_EXIST_WAR	BOOL	BIT 2	Not joined base	Warns there is base which doesn't join operation
%FX2115	_AB_SD_ER	BOOL	BIT 3	Stop by operation error	Stopped by abnormal operation
%FX2116	_TASK_ER	BOOL	BIT 4	Task collision	It is collided to the task
%FX2117	_BAT_ER	BOOL	BIT 5	Battery error	It is to the error in the battery state
%FX2118	_ANNUM_WAR	BOOL	BIT 6	External device fault	Indicates that the light fault in the external device is detected.
%FX2120	_HS_WAR	BOOL	BIT 8	High speed link	Abnormal HS parameter
%FX2121	_REDUN_WAR	BOOL	BIT 9	Redundant configuration warning	It is not single CPU RUN mode and redundant configuration is not configured
%FX2122	_OS_VER_WAR	BOOL	BIT 10	O/S version mismatch	OS versions between CPUs, extension managers, extension drive modules are different
%FX2123	_RING_WAR	BOOL	BIT 11	Ring topology configuration warning	Configure an extension cable as the Ring topology
%FX2132	_P2P_WAR	BOOL	BIT 20	P2P parameter	Abnormal P2P parameter
%FX2140	_CONSTANT_ER	BOOL	BIT 28	Fixed cycle error	Fixed cycle error
%FX2141	_BASE_POWER_WAR	BOOL	BIT 29	Power module error warning	One or two power module is error
%FX2142	_BASE_SKIP_WAR	BOOL	BIT 30	Base skip cancelation warning	In case of canceling the base skip, base is different with IO parameter
%FX2143	_BASE_NUM_OVER_WAR	BOOL	BIT 31	Base number setting error	Base number of extension drive module is not 1~31

2. Standby CPU System warning representative flag

Address	Flag name	Туре	Bit position	Contents	Description
%FD130	_SB_CNF_WAR	DWORD	Represent ative flag	System warning	Representative flag displayed the system warning state
%FX4160	_SB_RTC_ER	BOOL	BIT 0	RTC error	Indicates that RTC data is abnormal
%FX4162	_SB_BASE_EXIST_ WAR	BOOL	BIT 2	Not joined base	Warns there is base which doesn't join operation
%FX4163	_SB_AB_SD_ER	BOOL	BIT 3	Stop by operation error	Stopped by abnormal operation
%FX4164	_SB_TASK_ER	BOOL	BIT 4	Task collision	It is collided to the task
%FX4165	_SB_BAT_ER	BOOL	BIT 5	Battery error	It is to the error in the battery state
%FX4166	_SB_ANNUM_WAR	BOOL	BIT 6	External device fault	Indicates that the light fault in the external device is detected.
%FX4168	_SB_HS_WAR	BOOL	BIT 8	High speed link	Abnormal HS parameter
%FX4170	_SB_OS_VER_WAR	BOOL	BIT 10	O/S version mismatch	OS versions between CPUs, extension managers, extension drive modules are different
%FX4171	_SB_RING_WAR	BOOL	BIT 11	Ring topology configuration warning	Configure an extension cable as the Ring topology
%FX4180	_SB_P2P_WAR	BOOL	BIT 20	P2P parameter	Abnormal P2P parameter
%FX4188	_SB_CONSTANT_E	BOOL	BIT 28	Fixed cycle error	Fixed cycle error
%FX4189	_SB_BASE_POWER _WAR	BOOL	BIT 29	Power module error warning	One or two power module is error
%FX4190	_SB_BASE_SKIP_W AR	BOOL	BIT 30	Base skip cancelation warning	In case of canceling the base skip, base is different with IO parameter
%FX4191	_SB_BASE_NUM_O VER_WAR	BOOL	BIT 31	Base number setting error	Base number of extension drive module is not 1~31

# **Appendix 1.5 System Warning Detail Flag**

1. Master CPU system warning detail flag

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Address	Flag name	name Type		Contents	Description		
%FX2624	_HS_WARN	ARRAY[011] OF BOOL	1	Abnormal HS parameter	Relevant flag is on in case Hs parameter is abnormal		
%FX2640	_P2P_WARN	ARRAY[07] OF BOOL	-	Abnormal P2P parameter	Relevant flag is on in case P2P parameter is abnormal P2P		
%FD587	_BASE_ACPF _WAR	DWORD	1	Instantaneous power cutoff occurrence warning information	Indicates base where Instantaneous power cutoff occurs		
%FW164	_HS_WAR_W	WORD	-	Abnormal HS parameter	Indicates abnormal HS link number by bit		
%FW165	_P2P_WAR_W	WORD		Abnormal P2P parameter	Indicates abnormal P2P link number by bit		
%FW1923	_ANC_WAR	WORD		Light fault information external device	Classifies the type of user defined error and writes value except 0. If detection of heavy fault is requested, it develops an external light fault detection error. By monitoring this flag, the user can know a reason of light fault.		

2. Standby CPU system warning detail flag

Address	Flag name	Туре	Writable	Contents	Description
%FX4672	_SB_HS_WA	ARRAY[011] OF	-	Abnormal HS parameter	Relevant flag is on in case Hs parameter is abnormal
%FX4688	_SB_P2P_WA	ARRAY[07] OF BOOL	-	Abnormal P2P parameter	Relevant flag is on in case P2P parameter is abnormal P2P
%FW292	_SB_HS_WA R_W	WORD	-	Abnormal HS parameter	Indicates abnormal HS link number by bit
%FW293	_SB_P2P_WA	WORD	-	Abnormal P2P parameter	Indicates abnormal P2P link number by bit

# **Appendix 1.6 System Operation Status Information Flag**

1. Master CPU system operation status information flag

Address	Flag name	Туре	Bit position		Description
%FD64	_SYS_STATE	DWORD	Representat ive flag		Indicates PLC mode and operation state of system.
%FX2048	RUN	BOOL	BIT 0	RUN	
%FX2049	_STOP	BOOL	BIT 1	STOP	
%FX2050	ERROR	BOOL	BIT 2	ERROR	Indicates CPU's operation status
%FX2051	DEBUG	BOOL	BIT 3	DEBUG	
%FX2052	_LOCAL_CON	BOOL	BIT 4	Local control	Indicates operation mode changeable state only by the Mode key and XG5000.
%FX2054	_REMOTE_CON	BOOL	BIT 6	Remote Mode On	It is Remote control mode
%FX2058	_RUN_EDIT_DON	BOOL	BIT 10	Editing during Run completed	Indicates completion of editing during Run
%FX2059	_RUN_EDIT_NG	BOOL	BIT 11	Editing during Run abnormally completed	Edit is ended abnormally during Run
%FX2060	_CMOD_KEY	BOOL	BIT 12	Operation mode change by key	Indicates Operation mode change by key
%FX2061	_CMOD_LPADT	BOOL	BIT 13	Operation mode change by local PADT	Indicates operation mode change by local PADT
%FX2062	_CMOD_RPADT	BOOL	BIT 14	Operation mode change by remote PADT	Indicates operation mode change by remote PADT
%FX2063	_CMOD_RLINK	BOOL	BIT 15	Operation mode change by remote communication module	Indicates operation mode change by remote communication module
%FX2064	_FORCE_IN	BOOL	BIT 16	Forced Input	Forced On/Off state about input contact
%FX2065	_FORCE_OUT	BOOL	BIT 17	Forced Output	Forced On/Off state about output contact
%FX2066	_SKIP_ON	BOOL	BIT 18	Input/Output Skip	I/O Skip on execution
%FX2067	_EMASK_ON	BOOL	BIT 19	Fault mask	Fault mask on execution
%FX2069	_USTOP_ON	BOOL	BIT 21	Stopped by STOP function	Stopped after scan completion by 'STOP' function while RUN mode operation.
%FX2070	_ESTOP_ON	BOOL	BIT 22	Stopped by ESTOP function	Instantly stopped by 'ESTOP' function while RUN mode operation.
%FW192	_SL_OS_VER	ARRAY[031] OF WORD	-	O/S version of extension drive module	Indicates O/S version of extension drive module
%FW600	_BASE_INFO	ARRAY[031] OF WORD	-	Base information	Indicates how many base is installed
%FB12	_RTC_TIME	ARRAY[07] OF BYTE	-	Current clock	Indicates current clock
%FX2072	_INIT_RUN	BOOL		Initialization task on execution	User defined Initialization program on execution.
%FX2074	_AB_SIDE	BOOL	-	CPU position	CPU position (A-SIDE: ON, B-SIDE: OFF)

## Appendix 1 Flag List

Address	Flag name	Туре	Bit position	Contents	Description
%FX2076	_PB1	BOOL	-	Program Code 1	Program code 1 is selected
%FX2077	_PB2	BOOL	-	Program Code 2	Program code 1 is selected
%FX30736	_INIT_DONE	BOOL	writable	Initialization task execution completion	If this flag is set by user's initial program, it is started to execution of scan program after initial program completion.
%FW584	_RTC_DATE	DATE	-	RTC's current date	Indicates RTC's current date
%FD67	_OS_VER	DWORD	-	O/S version	Indicates CPU O/S version
%FD68	_OS_DATE	DWORD	-	O/S data	Indicates CPU O/S data
%FD69	_CP_OS_VER	DWORD	-	Extension manager O/S version	Indicates extension manager O/S version
%FD573	_OS_TYPE	DWORD	-	For PLC classification	Whether it is provided to other division
%FW1081	_FALS_NUM	INT	-	FALS number	Indicates FALS number
%FD293	_RTC_TOD	TIME_OF_DA Y	-	RTC's current clock	Indicates RTC's current clock RTC. (ms unit)
%FD582	_RUN_EDIT_CNT	UDINT	-	The no. of editing during Run	Indicates the no. of editing during Run
%FW140	_AC_F_CNT	UINT	-	The no. of instantaneous power cutoff	Indicates the no. of instantaneous power cutoff
%FW158	_POWER_OFF_C	UINT	-	The no. of power cutoff	Indicates the no. of power cutoff
%FW386	_SCAN_MAX	UINT	writable	Max. scan time	Indicates max. scan time after(unit: 0.1ms)
%FW387	_SCAN_MIN	UINT	writable	Min. scan time	Indicates min. scan time after Run
%FW388	_SCAN_CUR	UINT	writable	Current scan time	Indicates current scan time (unit 0.1ms)
%FW585	_RTC_WEEK	UINT	-	RTC's current day	Indicates RTC's current day
%FW141	_CPU_TYPE	WORD	-	CPU ID (XGR - 0xA801)	Indicates CPU type
%FW633	_RBANK_NUM	WORD	-	Currently used block no.	Indicates currently used block no.
%FD125	_BASE_SKIP_INF	DWORD	-	Base skip information	Indicates base skip information
%FD124	_BASE_EMASK_I NFO	DWORD	-	Base fault mask information	Indicates base fault mask information
%FW1372	_SLOT_EMASK_I NFO	ARRAY[031] OF WORD	-	Slot fault mask information	Indicates slot fault mask information
%FW1404	_SLOT_SKIP_INF	ARRAY[031] OF WORD	-	Slot skip information	Indicates slot skip information

2. Standby CPU system operation status information flag

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Address	Flag name	Туре	Bit position	Contents	Description
%FD128	_SB_SYS_STATE	DWOR D	Represent ative flag	System information	Handles system information
%FX4096	_SB_RUN	BOOL	BIT 0	RUN	
%FX4097	_SB_STOP	BOOL	BIT 1	STOP	Indicates CPU's operation status
%FX4098	_SB_ERROR	BOOL	BIT 2	ERROR	
%FX4100	_SB_LOCAL_CON	BOOL	BIT 4	Local control	Local control mode
%FX4102	_SB_REMOTE_CO	BOOL	BIT 6	Remote mode On	Remote control mode
%FX4106	_SB_RUN_EDIT_D ONE	BOOL	BIT 10	Editing during Run completed	Indicates completion of editing during Run
%FX4107	_SB_RUN_EDIT_N G	BOOL	BIT 11	Editing during Run abnormally completed	Edit is ended abnormally during Run
%FX4108	_SB_CMOD_KEY	BOOL	BIT 12	Operation mode change by key	Indicates Operation mode change by key
%FX4109	_SB_CMOD_LPAD	BOOL	BIT 13	Operation mode change by local PADT	Indicates operation mode change by local PADT
%FX4110	_SB_CMOD_RPAD T	BOOL	BIT 14	Operation mode change by remote PADT	Indicates operation mode change by remote PADT
%FX4111	_SB_CMOD_RLINK	BOOL	BIT 15	Operation mode change by remote communication module	Indicates operation mode change by remote communication module
%FX4112	_SB_FORCE_IN	BOOL	BIT 16	Forced Input	Forced On/Off state about input contact
%FX4113	_SB_FORCE_OUT	BOOL	BIT 17	Forced Output	Forced On/Off state about output contact
%FX4114	_SB_SKIP_ON	BOOL	BIT 18	Input/Output Skip	I/O Skip on execution
%FX4115	_SB_EMASK_ON	BOOL	BIT 19	Fault mask	Fault mask on execution
%FX4117	_SB_USTOP_ON	BOOL	-	Stopped by STOP function	Stopped after scan completion by 'STOP' function while RUN mode operation.
%FX4118	_SB_ESTOP_ON	BOOL	-	Stopped by ESTOP function	Instantly stopped by 'ESTOP' function while RUN mode operation.
%FD131	_SB_OS_VER	DWOR D	-	O/S version	Indicates CPU O/S version
%FD132	_SB_OS_DATE	DWOR D	-	O/S data	Indicates CPU O/S data
%FD133	_SB_CP_OS_VER	DWOR D	-	O/S version of extension drive module	Indicates O/S version of extension drive module
%FW286	_SB_POWER_OFF	UINT	-	The no. of power cutoff	Indicates the no. of power cutoff

## Appendix 1 Flag List

Address	Flag name	Туре	Bit position	Contents	Description
	_CNT				
%FW269	_SB_CPU_TYPE	WORD	-	CPU ID (XGR - 0xA801)	Indicates CPU type
%FW632	_SB_BASE_INFO	WORD	-	Base information	Indicates how many base is installed.

# **Appendix 1.7 Redundant Operation Mode Information Flag**

## 1. Redundant operation mode information

Address	Flag name	Туре	Bit position	Contents	Description
%FD0	_REDUN_STATE	DWOR D	Represent ative flag	Redundant operation information	Representative flag that indicates Redundant operation information
%FX0	_DUAL_RUN	BOOL	BIT 0	Redundant operation	Now Redundant operation CPU A, CPU B are normal
%FX1	_RING_TOPOLO	BOOL	BIT 1	Ring topology status	Extension base is configure as ring
%FX2	_LINE_TOPOLO	BOOL	BIT 2	Line topology status	Extension base is configure as line
%FX4	_SINGLE_RUN_ A	BOOL	BIT 4	A-SIDE single Run mode	Indicates A-SIDE single Run mode
%FX5	_SINGLE_RUN_ B	BOOL	BIT 5	B-SIDE single Run mode	Indicates B-SIDE single Run mode
%FX6	_MASTER_RUN_ A	BOOL	BIT 6	A-SIDE is master Run mode (Incase standby CPU exists)	Indicates A-SIDE is master Run mode
%FX7	_MASTER_RUN_ B	BOOL	BIT 7	B-SIDE is master Run mode (Incase standby CPU exists)	Indicates B-SIDE is master Run mode

## **Appendix1.8 Operation Result Information Flag**

## 1. Operation Result Information Flag

Address	Flag name	Туре	Writable	Contents	Description
%FX672	_ARY_IDX_ERR	BOOL	Writable	Index range excess error in case of using array	In case of using array, index is out of setting value's range
%FX704	_ARY_IDX_LER	BOOL	Writable	Index range excess error latch in case of using array	Error occurred when index is out of setting value's range, in case of using array, is kept and the user erases this by program
%FX6160	_ERR	BOOL	Writable	Operation error flag	As an operation error flag by unit of operation function (FN) or function block (FB), it is renewed every operation
%FX6165	_LER	BOOL	Writable	Operation error latch flag	Operation error latch flag by program block (PB) unit. Error is kept until relevant program ends and the user erases this by program

# Appendix 1.9 Operation mode Key Status Flag

## 1. Operation mode key status flag

Address	Flag name	Туре	Writable	Contents	Description
				Remote key status	CPU key position status information- (remote: off, not
%FX291	_REMOTE_KEY	BOOL	-	information	remote: On)
%FX294	_STOP_KEY	BOOL	-	Stop key status information	CPU key position status information- (Stop: off, not stop: On)
%FX295	_RUN_KEY	BOOL	-	Run key status information	CPU key position status information- (Run: off, not Run: On)

# Appendix 1.10 Link Flag (L) List

It describes data link (L) flag

[Table 1.10.1] Communication Flag List according to High speed link no. (High speed link no. 1  $\sim$  12)

Item	Keyword	Туре	Content	Description
				Indicates normal operation of all station according to parameter set in High
			High speed link	speed link, and On under the condition as below.
	_HSn_RLINK	Bit	parameter "n" normal operation	1. In case that all station set in parameter is RUN mode and no error,
			of all station	2. All data block set in parameter is communicated normally, and
				3. The parameter set in each station itself is communicated normally.
				Once RUN_LINK is On, it keeps On unless stopped by LINK_DISABLE.
				In the state of _HSmRLINK flag On, if communication state of the station
				set in the parameter and data block is as follows, this flag shall be On.
			Abnormal state	In case that the station set in the parameter is not RUN mode, or
	_HSn_LTRBL	Bit	after_HSn_RLINK	2. There is an error in the station set in the parameter, or
			ON	3. The communication state of data block set in the parameter is not good.
				LINK TROUBLE shall be On if the above 1, 2 & 3 conditions occur, and if the condition return to the normal state, it shall be Off again.
		Bit Array		Indicates the general state of communication information for each data
	_HSn_STATE[k] (k=000~127)		High speed link parameter "n", k block general state	block of setting parameter.
HS link				HS1STATEk=HS1MODk&_HS1TR X k&(~_HSnERRk)
	_HSn_MOD[k] (k=000~127)	Bit Array	High speed link parameter "n", k block station RUN operation mode	Indicates operation mode of station set in k data block of parameter.
	_HSn_TRX[k]	Bit	Normal communication with High speed	Indicates if communication state of k data of parameter is communicated smoothly according to the setting.
	(k=000~127)	Array	link parameter "n", k block station	
			High speed link parameter "n", k	Indicates if the error occurs in the communication state of k data block of
	_HSn_ERR[k]	Bit	block station	parameter.
	(k=000~127)	Array	operation error mode	
	_HSn_SETBLOCK[k	bit Array	High speed link parameter "n", k block setting	Indicates whether or not to set k data block of parameter.

Notes		
High Speed Link no.	L area address	Remarks
1	L000000~L00049F	Comparing with High speed link 1 from [Table 1], the flag address of different high speed link station no. is as follows by a simple calculation formula.
2	L000500~L00099F	Thight speed link station no. is as follows by a simple calculation formula.
3	L001000~L00149F	* Calculation formula : L area address =
4	L001500~L00199F	L000000 + 500 x (High speed link no. – 1)
5	L002000~L00249F	In case of using high speed line flag for Program and monitoring, you can use
6	L002500~L00299F	the flag map registered in XG5000 conveniently.
7	L003000~L00349F	
8	L003500~L00399F	
9	L004000~L00449F	
10	L004500~L00499F	
11	L005000~L00549F	

k means block no. and appears 8 words by 16 per 1 word for 128 blocks from  $000\sim127$ . For example, mode information (\_HS1MOD) appears from block 0 to block 15 for L00010, and block  $16\sim31$ ,  $32\sim47$ ,  $48\sim63$ ,  $64\sim79$ ,  $80\sim95$ ,  $96\sim111$ ,  $112\sim127$  information for L00011, L00012, L00013, L00014, L00015, L00016, L00017. Thus, mode information of block no. 55 appears in L000137.

## [Table 2] Communication Flag List according to P2P Service Setting

P2P parameter no.(n): 1~8, P2P block(xx): 0~63

No.	Keyword	Туре	Contents	Description
P2P	_P2Pn_NDRxx	Bit	P2P parameter n, xx	Indicates P2P parameter n, xx Block service normal end
			Block service normal	
			end	
	_P2Pn_ERRxx	Bit	P2P parameter n, xx	Indicates P2P parameter n, xx Block service abnormal end
			Block service abnormal	
			end	
	_P2Pn_STATUSxx	Word	P2P parameter n, xx	Indicates error code in case of P2P parameter n, xx Block service abnormal end
			Block service abnormal	
			end error Code	
	_P2Pn_SVCCNTxx	Double word	P2P parameter n, xx	
			Block service normal	Indicates P2P parameter n, xx Block service normal count
			count	
	_P2Pn_ERRCNTxx	Double word	P2P parameter n, xx	
			Block service abnormal	Indicates P2P parameter n, xx Block service abnormal count
			count	

## Appendix 1.11 Communication Flag (P2P) List

Link Register List according to P2P No.

P2P Parameter No. (n): 1~8, P2P Block(xx): 0~63

Lirik Registe	r List according	IO PZP IN	J.	P2P Parameter No. (n): 1~8, P2P Block(xx): 0~63
No.	Flags	Туре	Contents	Description
N00000	_PnBxxSN	Word	P2P parameter n, xx block another station no	Saves another station no. of P2P parameter 1, 00 block. In case of using another station no. at XG-PD, it is possible to edit during RUN by using P2PSN command.
N00001 ~ N00004	_PnBxxRD1	Device structure	Area device 1 to read P2P parameter n, xx block	Saves area device 1 to read P2P parameter n, xx block.
N00005	_PnBxxRS1	Word	Area size 1 to read P2P parameter n, xx block	Saves area size 1 to read P2P parameter n, xx block.
N00006 ~ N00009	_PnBxxRD2	Device structure	Area device 2 to read P2P parameter n, xx block	Saves area device 2 to read P2P parameter n, xx block.
N00010	_PnBxxRS2	Word	Area size 2 to read P2P parameter n, xx block	Saves area size 2 to read P2P parameter n, xx block.
N00011 ~ N00014	_PnBxxRD3	Device structure	Area device 3 to read P2P parameter n, xx block	Saves area device 3 to read P2P parameter n, xx block.
N00015	_PnBxxRS3	Word	Area size 3 to read P2P parameter n, xx block	Saves area size 3 to read P2P parameter n, xx block.
N00016 ~ N00019	_PnBxxRD4	Device structure	Area device 4 to read P2P parameter n, xx block	Saves area device 4 to read P2P parameter n, xx block.
N00020	_PnBxxRS4	Word	Area size 4 to read P2P parameter n, xx block	Saves area size 4 to read P2P parameter n, xx block.
N00021 ~ N00024	_PnBxxWD1	Device structure	Area device 1 to save P2P parameter n, xx block	Saves area device 1 to save P2P parameter n, xx block.
N00025	_PnBxxWS1	Word	Area size 1 to save P2P parameter n, xx block	Saves area size 1 to save P2P parameter n, xx block.
N00026 ~ N00029	_PnBxxWD2	Device structure	Area device 2 to save P2P parameter n, xx block	Saves area device 2 to save P2P parameter n, xx block.
N00030	_PnBxxWS2	Word	Area size 2 to save P2P parameter n, xx block	Saves area size 2 to save P2P parameter n, xx block.
N00031 ~ N00034	_PnBxxWD3	Device structure	Area device 3 to save P2P parameter n, xx block	Saves area device 3 to save P2P parameter n, xx block.
N00035	_PnBxxWS3	Word	Area size 3 to save P2P parameter n, xx block	Saves area size 3 to save P2P parameter n, xx block.
N00036 ~ N00039	_PnBxxWD4	Device structure	Area device 4 to save P2P parameter n, xx block	Saves area device 4 to save P2P parameter n, xx block.
N00040	_PnBxxWS4	WORD	Area size 4 to save P2P parameter n, xx block	Saves area size 4 to save P2P parameter n, xx block.

## Notes

N area shall be set automatically when setting P2P parameter by using XG-PD and available to modify during RUN by using P2P dedicated command.

N area has a different address classified according to P2P parameter setting no., block index. The area not used by P2P service as address is divided, can be used by internal device.

# **Appendix 1.12 Reserved Word**

The reserved words are predefined words to use in the system. Therefore, it is impossible to use them as the identifier.

Reserved Words
ACTION END_ACTION
ARRAY OF
AT
CASE OF ELSE END_CASE CONFIGURATION END_CONFIGURATION
Name of Data Type
DATE#, D# DATE_AND_TIME#, DT#
EXIT
FOR TO BY DO END_FOR
FUNCTION END_FUNCTION
FUNCTION_BLOCK END_FUNCTION_BLOCK
Names of Function Block
IF THEN ELSIF ELSE END_IF
OK
Operator (IL Language) Operator (ST Language)
PROGRAM
PROGRAM END_PROGRAM
REPEAT UNTIL END_REPEAT
RESOURCE END_RESOURCE
RETAIN
RETURN
STEP END_STEP
STRUCTURE END_STRUCTURE
T#
TASK WITH
TIME_OF_DAY#, TOD#
TRANSITION FROM TO END_TRANSITION
TYPE END_TYPE
VAR END_VAR
VAR_INPUT END_VAR
VAR_OUTPUT END_VAR
VAR_IN_OUT END_VAR VAR_EXTERNAL END_VAR
VAR_ACCESS END_VAR
VAR GLOBAL END VAR
WHILE DO END WHILE
WITH

## Warranty

#### 1. Warranty Period

The product you purchased will be guaranteed for 18 months from the date of manufacturing.

#### 2. Scope of Warranty

Any trouble or defect occurring for the above-mentioned period will be partially replaced or repaired. However, please note the following cases will be excluded from the scope of warranty.

- (1) Any trouble attributable to unreasonable condition, environment or handling otherwise specified in the manual,
- (2) Any trouble attributable to others' products,
- (3) If the product is modified or repaired in any other place not designated by the company,
- (4) Due to unintended purposes
- (5) Owing to the reasons unexpected at the level of the contemporary science and technology when delivered.
- (6) Not attributable to the company; for instance, natural disasters or fire
- 3. Since the above warranty is limited to PLC unit only, make sure to use the product considering the safety for system configuration or applications.

## **Environmental Policy**

LS Industrial Systems Co., Ltd supports and observes the environmental policy as below.

# Environmental Management LS Industrial Systems considers the environmental preservation as the preferential management subject and every staff of LS Industrial Systems use the reasonable endeavors for the pleasurably environmental preservation of the earth. About Disposal LS Industrial Systems' PLC unit is designed to protect the environment. For the disposal, separate aluminum, iron and synthetic resin (cover) from the product as they are reusable.



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